

SM_BUS_ADDRESS :	
PDI Address :	
SIM Bus Service	SM Bus Address
SD-SDRAM A(0)	Addr
SD-SDRAM B(0)	Addr
SD-SDRAM C(0-1)	Addr
SD-SDRAM D(1)	Addr
TC Master (DMS1) :	
SM Bus Service :	SM Bus Address
DSP Data Transfer Station	MDN MDN
TCA Thermal Sensor	MDN
TL TAGE/TGPM+2	MDN, GAN
ADDA/DAG	MDN
GPR (Thermistor array)	MDN
FUSE(Thermistor array)	7C5, 7C6, 7A6, 7B6, 7B8

Device Identification

GPU Thermal Sensor

1st

000000000000

00000000

2nd

GPU Temperature

1st

000000000000

APL00000000

2nd

USB2.0/PCIE/SATA Setting			USB2.0 Setting		
1	00000001		1	00000001	
2	00000002		2	00000002	
3	00000003	USB Port1	3	00000003	USB Port1
4	00000004		4	00000004	
5	00000005	USB Port3	5	00000005	USB Port3
6	00000006	USB Port4	6	00000006	USB Port4
7	00000007	Cable Header	7	00000007	Cable Header
8	00000008		8	00000008	SATA M040
9	00000009		9	00000009	Camera
10	0000000A		10	0000000A	X-Ray
11	0000000B		11	0000000B	
12	0000000C	Thunderbolt 4	12	0000000C	Tablet E04
13	0000000D		13	0000000D	TV
14	0000000E		14	0000000E	RF
15	0000000F				
16	00000010				
17	00000011	PCIE3.0 x 4 SSD			
18	00000012				
19	00000013				
20	00000014	SDRAM 8GB			
21	00000015				
22	00000016	RAM			
23	00000017	RAM_150C			
24	00000018				
25	00000019	PCIE3.0 x 4 SSD			
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27	0000001B				
28	0000001C				
29	0000001D	PCIE3.0 x 4 SSD			
30	0000001E				
31	0000001F				

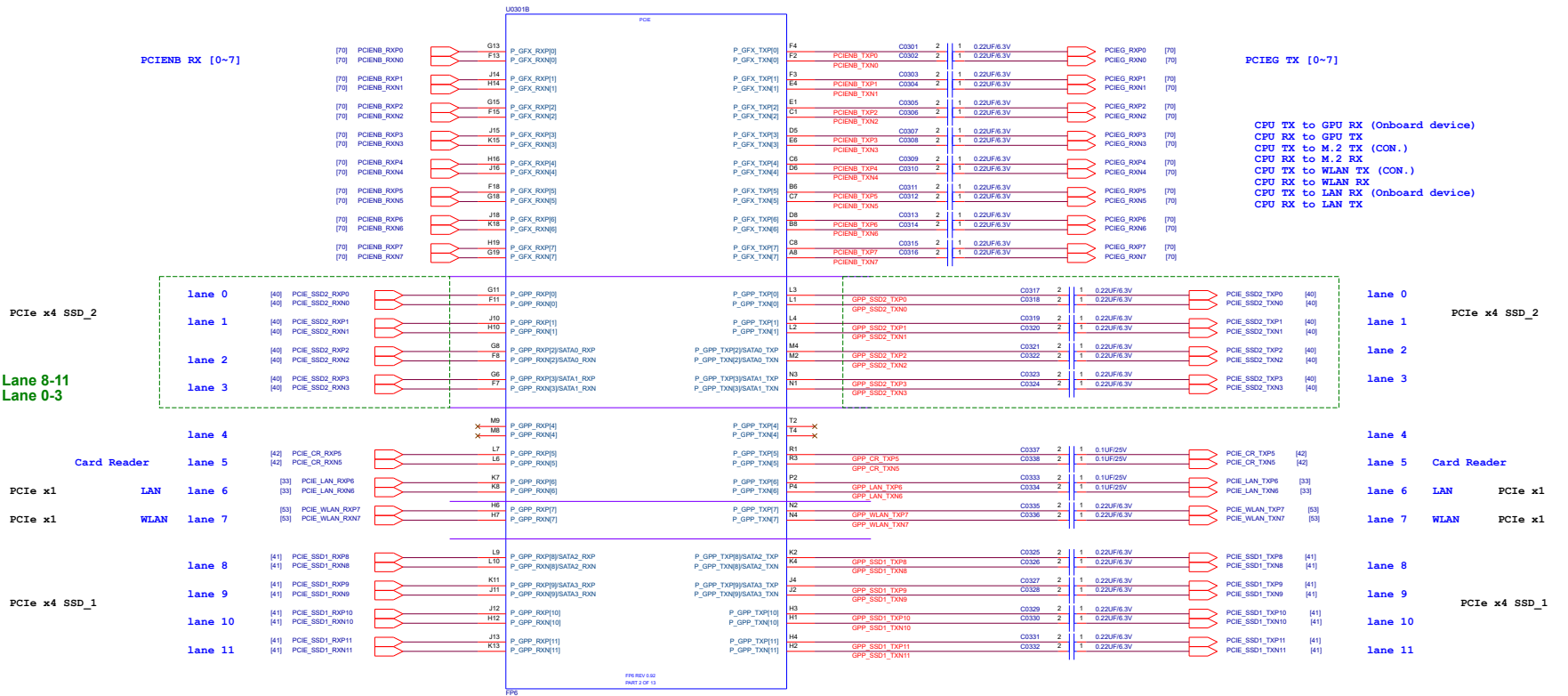
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1	ISSUE 1: Overload on the system	CAUSE 1: High traffic volume	SOLUTION 1: Increase server capacity	Completed	Ref: [1]
2	ISSUE 2: Data corruption	CAUSE 2: Software bug	SOLUTION 2: Patch the software	In Progress	Ref: [2]
3	ISSUE 3: Slow load times	CAUSE 3: Inefficient database queries	SOLUTION 3: Optimize database queries	Planned	Ref: [3]
4	ISSUE 4: Security vulnerability	CAUSE 4: Outdated security patches	SOLUTION 4: Update security patches	Completed	Ref: [4]
5	ISSUE 5: User interface issues	CAUSE 5: Poor user experience	SOLUTION 5: Redesign the UI	In Progress	Ref: [5]
6	ISSUE 6: System downtime	CAUSE 6: Hardware failure	SOLUTION 6: Replace faulty hardware	Completed	Ref: [6]
7	ISSUE 7: Data loss	CAUSE 7: Lack of backup	SOLUTION 7: Implement backup system	Planned	Ref: [7]
8	ISSUE 8: Performance degradation	CAUSE 8: Memory leak	SOLUTION 8: Fix memory leak	In Progress	Ref: [8]
9	ISSUE 9: Network connectivity issues	CAUSE 9: Network congestion	SOLUTION 9: Upgrade network infrastructure	Planned	Ref: [9]
10	ISSUE 10: Compliance issues	CAUSE 10: Non-compliance with regulations	SOLUTION 10: Review and update policies	Completed	Ref: [10]
11	ISSUE 11: Integration problems	CAUSE 11: Incompatible systems	SOLUTION 11: Develop custom integration	In Progress	Ref: [11]
12	ISSUE 12: Scalability issues	CAUSE 12: Limited resources	SOLUTION 12: Scale resources	Planned	Ref: [12]
13	ISSUE 13: User privacy concerns	CAUSE 13: Data handling practices	SOLUTION 13: Implement privacy controls	Completed	Ref: [13]
14	ISSUE 14: System reliability	CAUSE 14: Redundancy issues	SOLUTION 14: Implement redundancy	In Progress	Ref: [14]
15	ISSUE 15: Data integrity	CAUSE 15: Data validation errors	SOLUTION 15: Implement data validation	Planned	Ref: [15]
16	ISSUE 16: System security	CAUSE 16: Weak passwords	SOLUTION 16: Enforce strong passwords	Completed	Ref: [16]
17	ISSUE 17: System performance	CAUSE 17: Slow response times	SOLUTION 17: Optimize system performance	In Progress	Ref: [17]
18	ISSUE 18: System availability	CAUSE 18: Single point of failure	SOLUTION 18: Eliminate single point of failure	Planned	Ref: [18]
19	ISSUE 19: System maintainability	CAUSE 19: Complex code	SOLUTION 19: Simplify code	Completed	Ref: [19]
20	ISSUE 20: System flexibility	CAUSE 20: Rigid architecture	SOLUTION 20: Design flexible architecture	In Progress	Ref: [20]
21	ISSUE 21: System interoperability	CAUSE 21: Incompatible protocols	SOLUTION 21: Standardize protocols	Planned	Ref: [21]
22	ISSUE 22: System extensibility	CAUSE 22: Limited functionality	SOLUTION 22: Add new features	Completed	Ref: [22]
23	ISSUE 23: System scalability	CAUSE 23: Limited capacity	SOLUTION 23: Increase capacity	In Progress	Ref: [23]
24	ISSUE 24: System reliability	CAUSE 24: High failure rate	SOLUTION 24: Improve reliability	Planned	Ref: [24]
25	ISSUE 25: System security	CAUSE 25: Vulnerable components	SOLUTION 25: Secure components	Completed	Ref: [25]
26	ISSUE 26: System performance	CAUSE 26: Slow processing	SOLUTION 26: Optimize processing	In Progress	Ref: [26]
27	ISSUE 27: System availability	CAUSE 27: Downtime	SOLUTION 27: Minimize downtime	Planned	Ref: [27]
28	ISSUE 28: System maintainability	CAUSE 28: Complex configuration	SOLUTION 28: Simplify configuration	Completed	Ref: [28]
29	ISSUE 29: System flexibility	CAUSE 29: Rigid design	SOLUTION 29: Design flexible system	In Progress	Ref: [29]
30	ISSUE 30: System interoperability	CAUSE 30: Incompatible standards	SOLUTION 30: Adopt standards	Planned	Ref: [30]
31	ISSUE 31: System extensibility	CAUSE 31: Limited growth	SOLUTION 31: Plan for growth	Completed	Ref: [31]
32	ISSUE 32: System scalability	CAUSE 32: Limited resources	SOLUTION 32: Scale resources	In Progress	Ref: [32]
33	ISSUE 33: System reliability	CAUSE 33: High failure rate	SOLUTION 33: Improve reliability	Planned	Ref: [33]
34	ISSUE 34: System security	CAUSE 34: Vulnerable components	SOLUTION 34: Secure components	Completed	Ref: [34]
35	ISSUE 35: System performance	CAUSE 35: Slow processing	SOLUTION 35: Optimize processing	In Progress	Ref: [35]
36	ISSUE 36: System availability	CAUSE 36: Downtime	SOLUTION 36: Minimize downtime	Planned	Ref: [36]
37	ISSUE 37: System maintainability	CAUSE 37: Complex configuration	SOLUTION 37: Simplify configuration	Completed	Ref: [37]
38	ISSUE 38: System flexibility	CAUSE 38: Rigid design	SOLUTION 38: Design flexible system	In Progress	Ref: [38]
39	ISSUE 39: System interoperability	CAUSE 39: Incompatible standards	SOLUTION 39: Adopt standards	Planned	Ref: [39]
40	ISSUE 40: System extensibility	CAUSE 40: Limited growth	SOLUTION 40: Plan for growth	Completed	Ref: [40]
41	ISSUE 41: System scalability	CAUSE 41: Limited resources	SOLUTION 41: Scale resources	In Progress	Ref: [41]
42	ISSUE 42: System reliability	CAUSE 42: High failure rate	SOLUTION 42: Improve reliability	Planned	Ref: [42]
43	ISSUE 43: System security	CAUSE 43: Vulnerable components	SOLUTION 43: Secure components	Completed	Ref: [43]
44	ISSUE 44: System performance	CAUSE 44: Slow processing	SOLUTION 44: Optimize processing	In Progress	Ref: [44]
45	ISSUE 45: System availability	CAUSE 45: Downtime	SOLUTION 45: Minimize downtime	Planned	Ref: [45]
46	ISSUE 46: System maintainability	CAUSE 46: Complex configuration	SOLUTION 46: Simplify configuration	Completed	Ref: [46]
47	ISSUE 47: System flexibility	CAUSE 47: Rigid design	SOLUTION 47: Design flexible system	In Progress	Ref: [47]
48	ISSUE 48: System interoperability	CAUSE 48: Incompatible standards	SOLUTION 48: Adopt standards	Planned	Ref: [48]
49	ISSUE 49: System extensibility	CAUSE 49: Limited growth	SOLUTION 49: Plan for growth	Completed	Ref: [49]
50	ISSUE 50: System scalability	CAUSE 50: Limited resources	SOLUTION 50: Scale resources	In Progress	Ref: [50]

Pin I/O Name	SW0	SW1	CS0/MS
0	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0
1	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0
2	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0
3	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0
4	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0
5	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0
6	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0
7	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0
8	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0
9	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0
10	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0
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27	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0
28	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0
29	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0
30	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0
31	SW0/1/CS0/MS0	SW0/1/CS0/MS0	SW0/1/CS0/MS0

PCIe/WLAN/LAN/SSD

RX Side

TX Side





Project Name

Type-C_ALT_USB3-10G + DP + PD + Slave_Charger_TI

Rev

R1.0

Title : ww **USB3.1 TYPE-C+TI 1046A**

Size

D

Dept.: **ASUSTeK COMPUTER INC. NB1** **Engineer:** **Design IP**

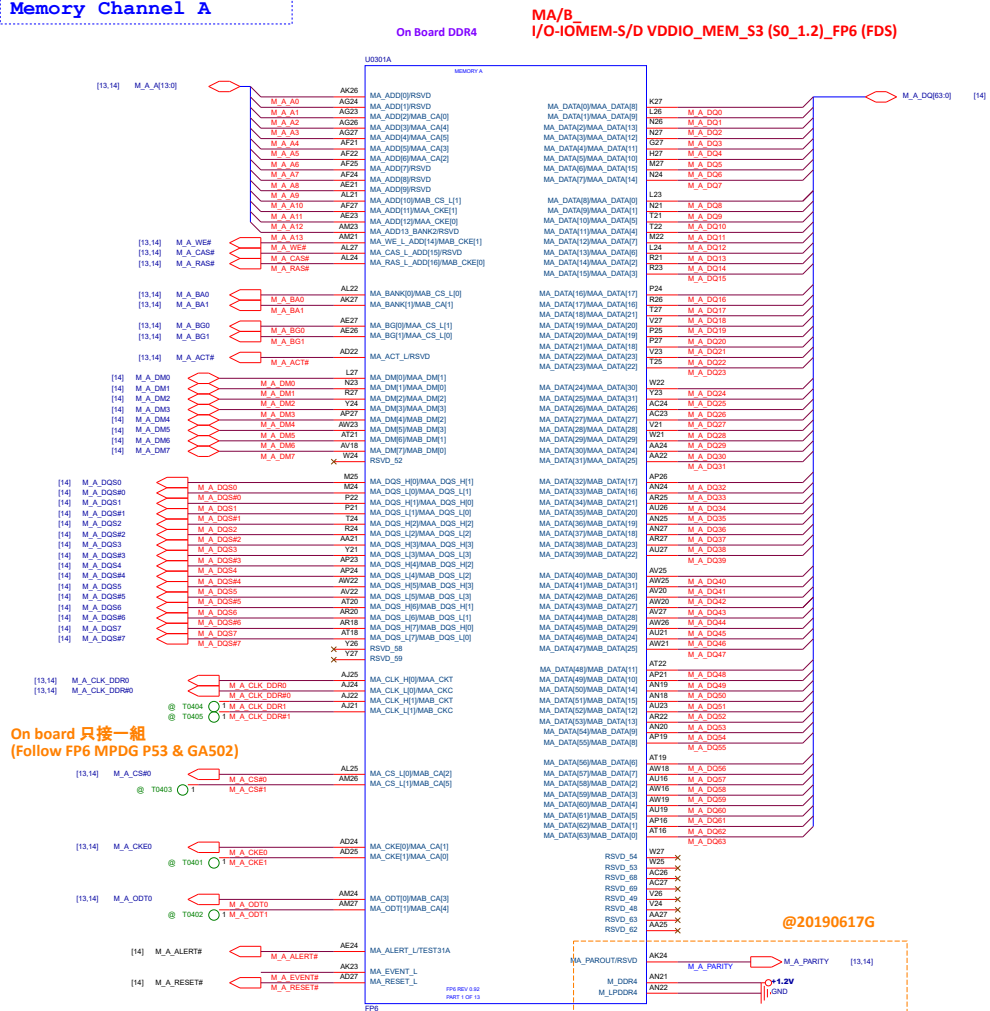
Date: **Friday, November 06, 2020**

Sheet

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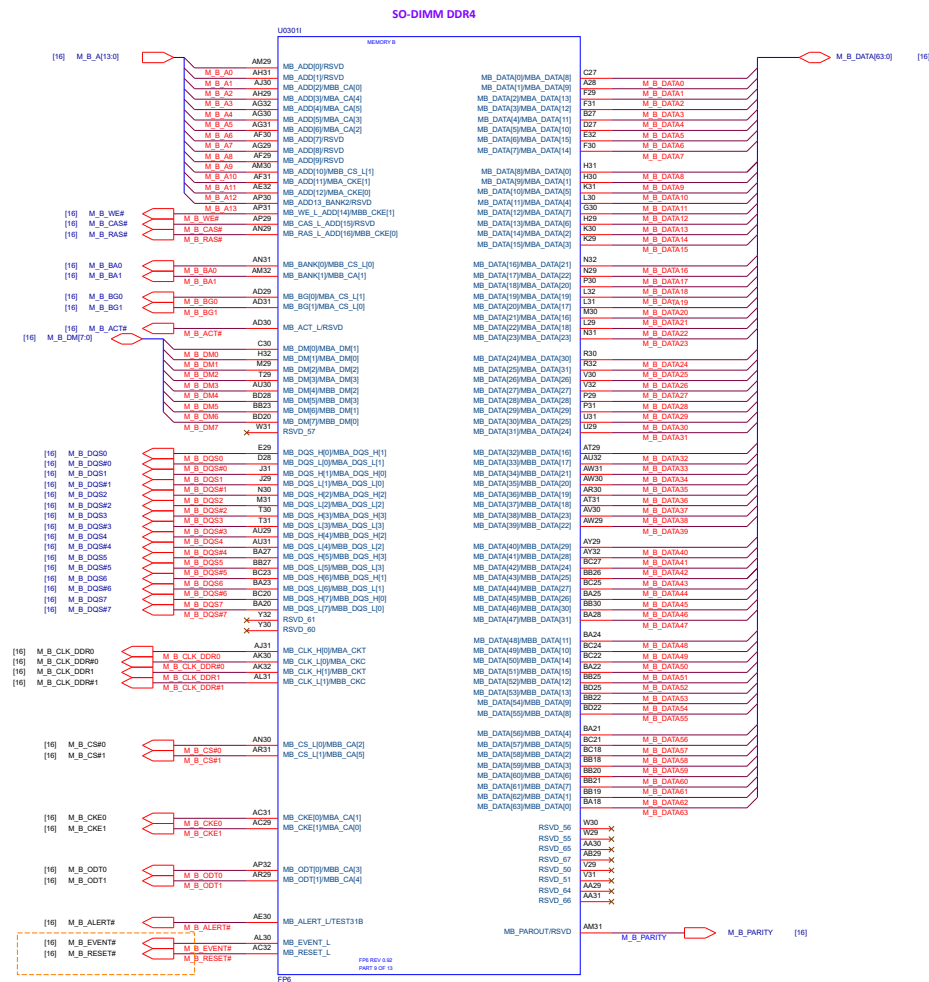
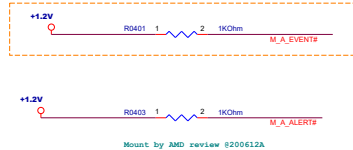
of

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On board 只接一組
(Follow FP6 MPDG P53 & GA502)

Follow FP6 CRB no connect and pull-H@20181005B



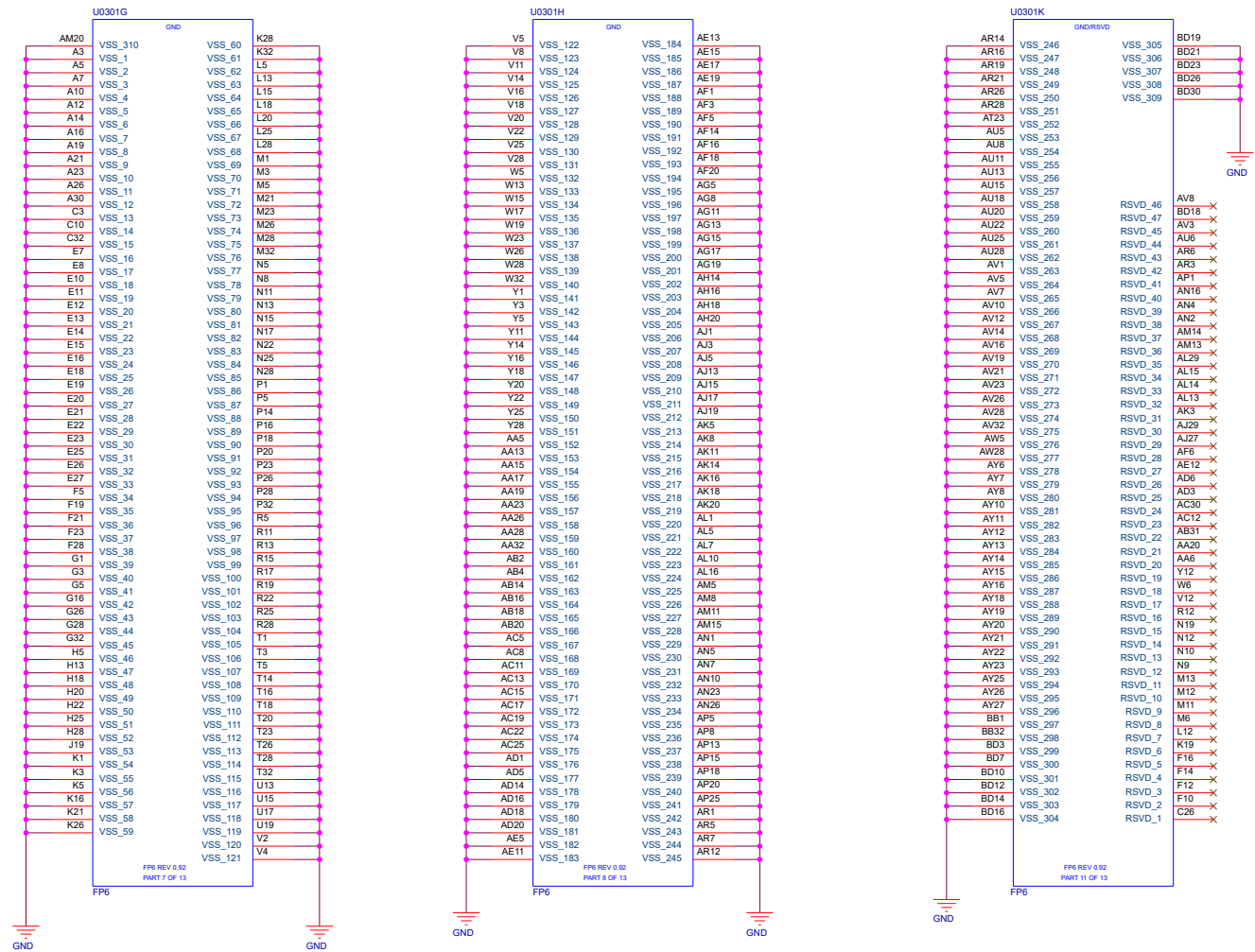
EVENT# 對接pull-H +1.2V (FP6 CRB)

RESET# only 對接 (FP6 CRB)

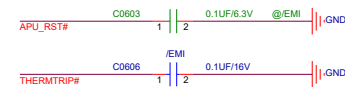


FP6 CRB預留不上

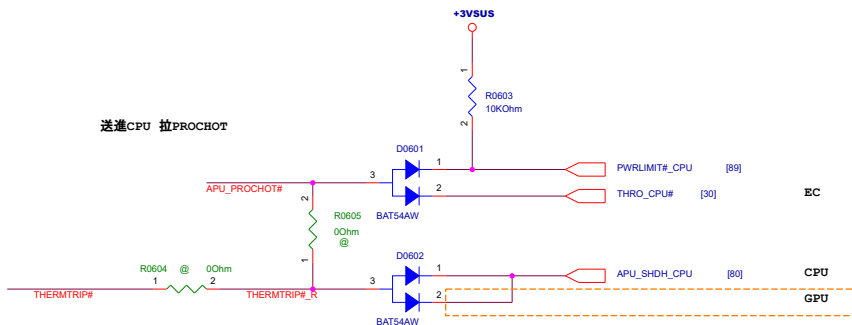
CPU_GND



Display Port TX/RX
O-IOVP-D_VDDP (S0_0.75)_FP6 (FDS)

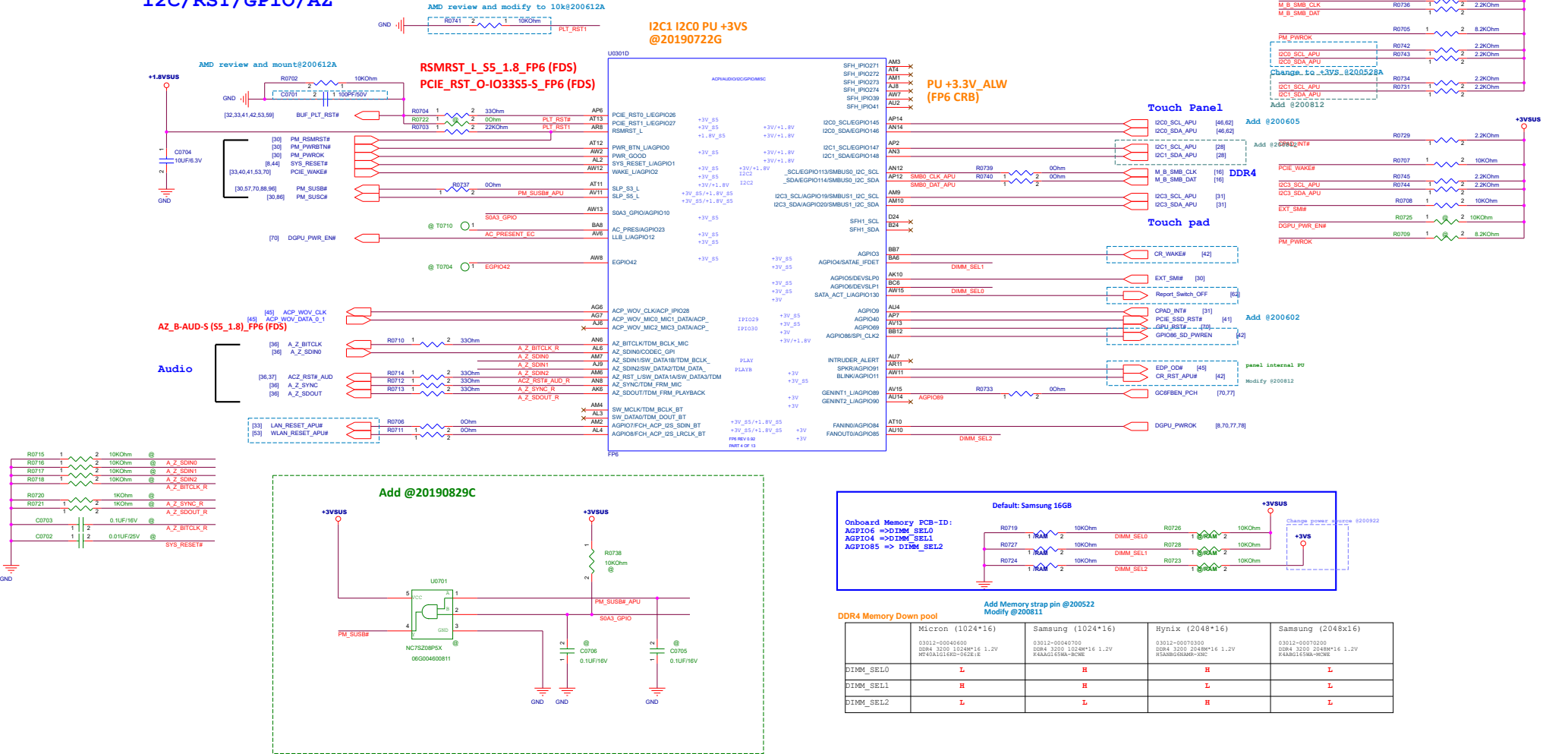


Test pin follow AMD BP Probing header



<Variant Name>

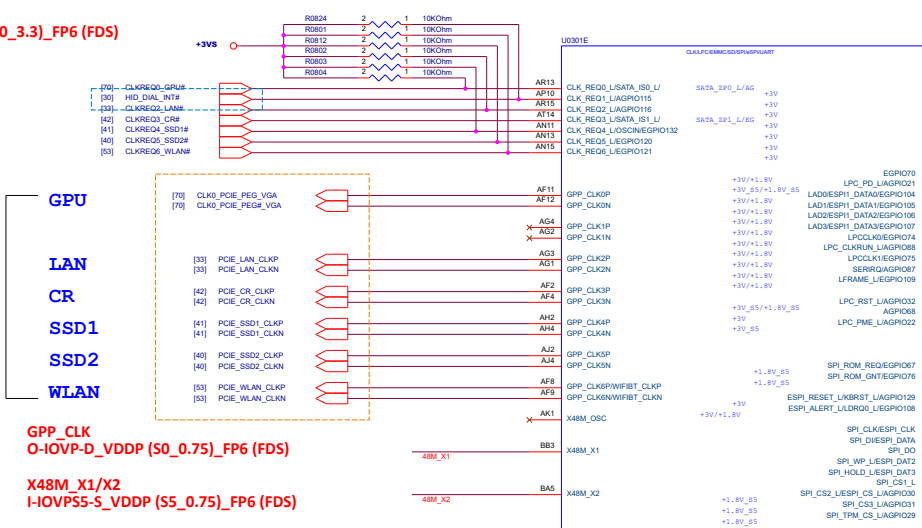
I2C/RST/GPIO/AZ



<Variant Name>



CLK_REQ
B-IO33-S (S0_3.3)_FP6 (FDS)

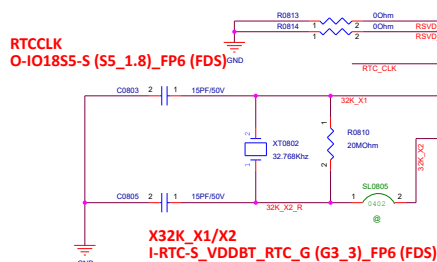


PCIE CLK P/N
後端記得預留0 ohm

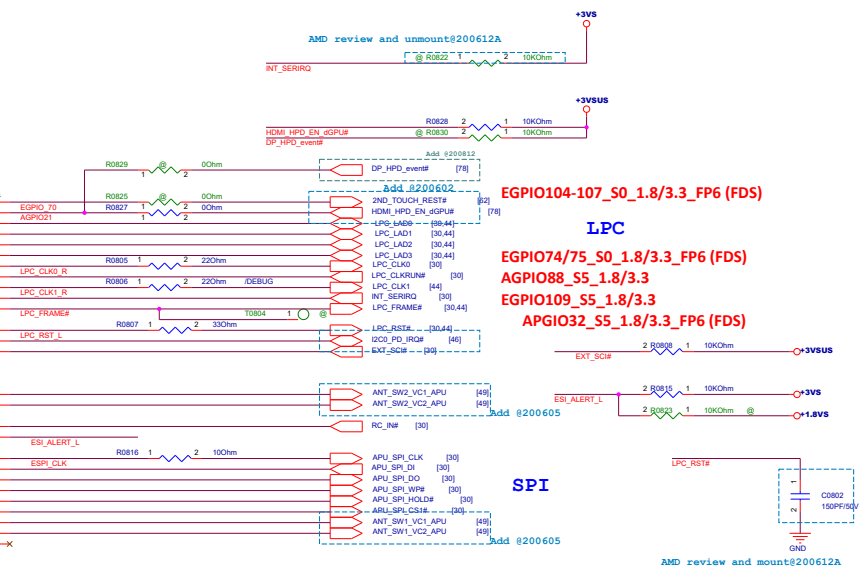
GPU
LAN
CR
SSD1
SSD2
WLAN

GPP_CLK
O-IOVP-D_VDDP (S0_0.75)_FP6 (FDS)

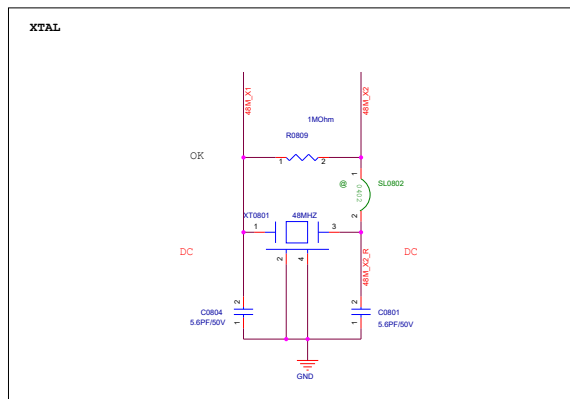
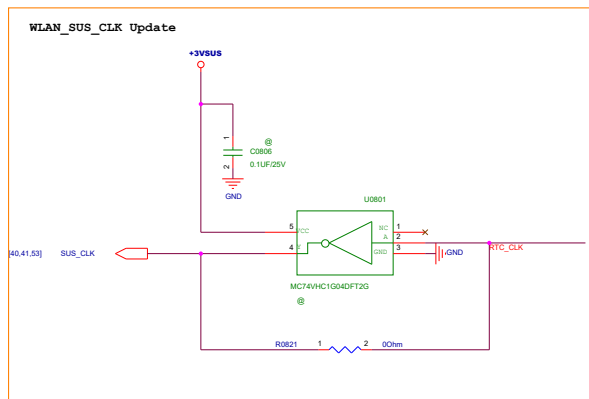
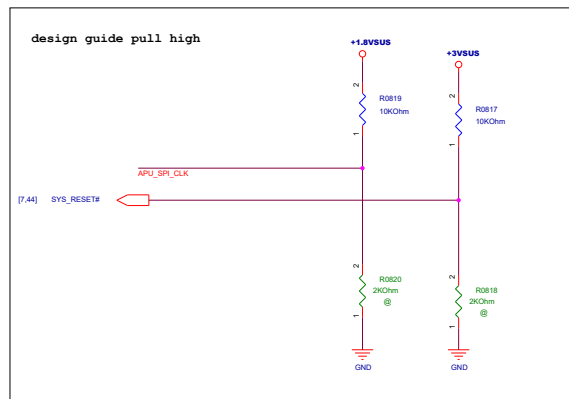
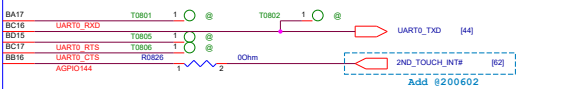
X48M_X1/X2
I-IOVPS5-S_VDDP (S5_0.75)_FP6 (FDS)



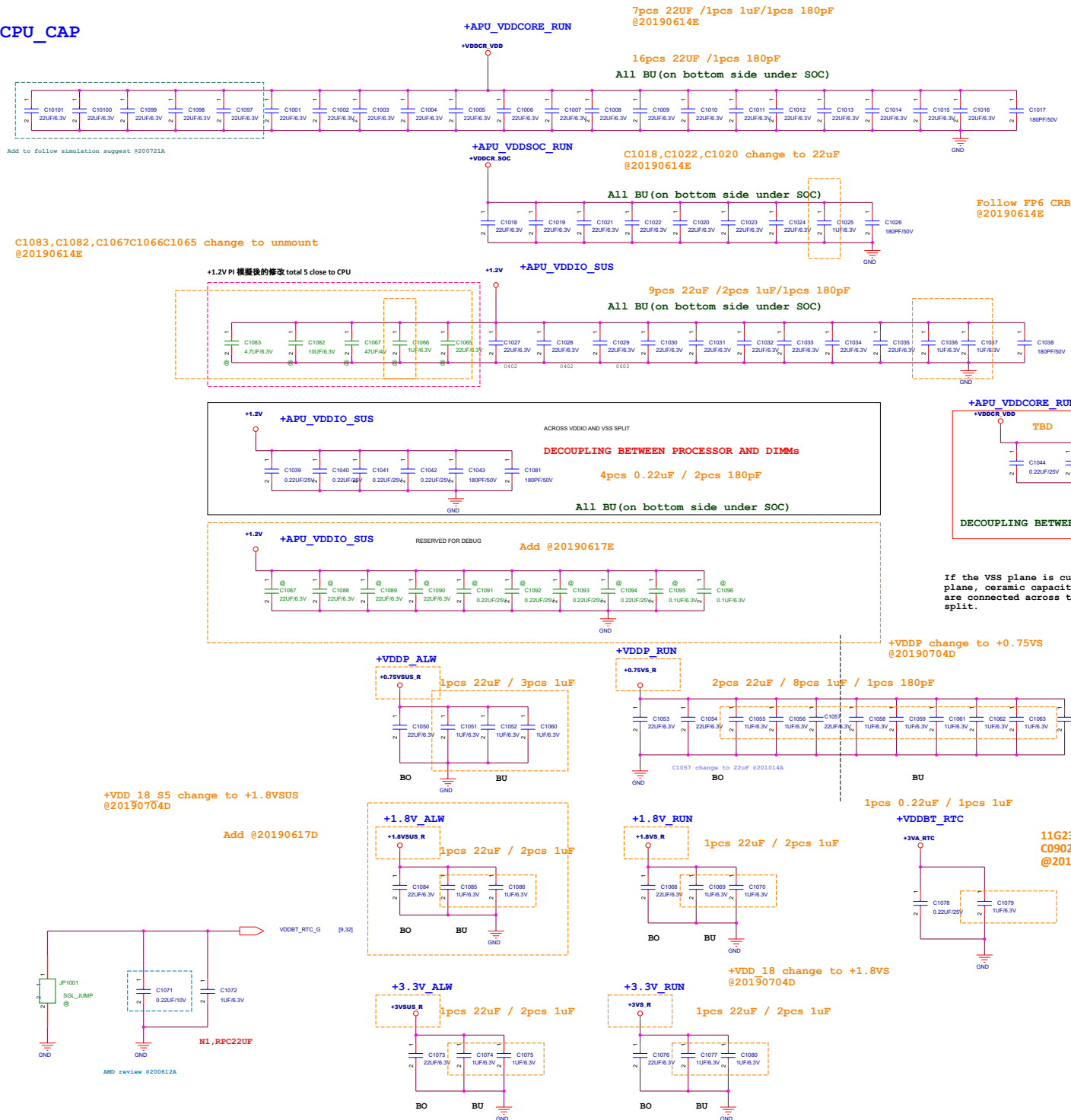
X32K_X1/X2
I-RTC-S_VDDBT_RTC_G (G3_3)_FP6 (FDS)



UART0/1_S0_3.3_FP6 (FDS)



CPU_CAP





Project Name

Type-C_ALT_USB3-10G + DP + PD + Slave_Charger_TI

Rev

R1.0

Title : PD_TPS65993AC

Size

C

Dept.: ASUSTeK COMPUTER INC.

Engineer: Design IP

Date: Friday, November 06, 2020

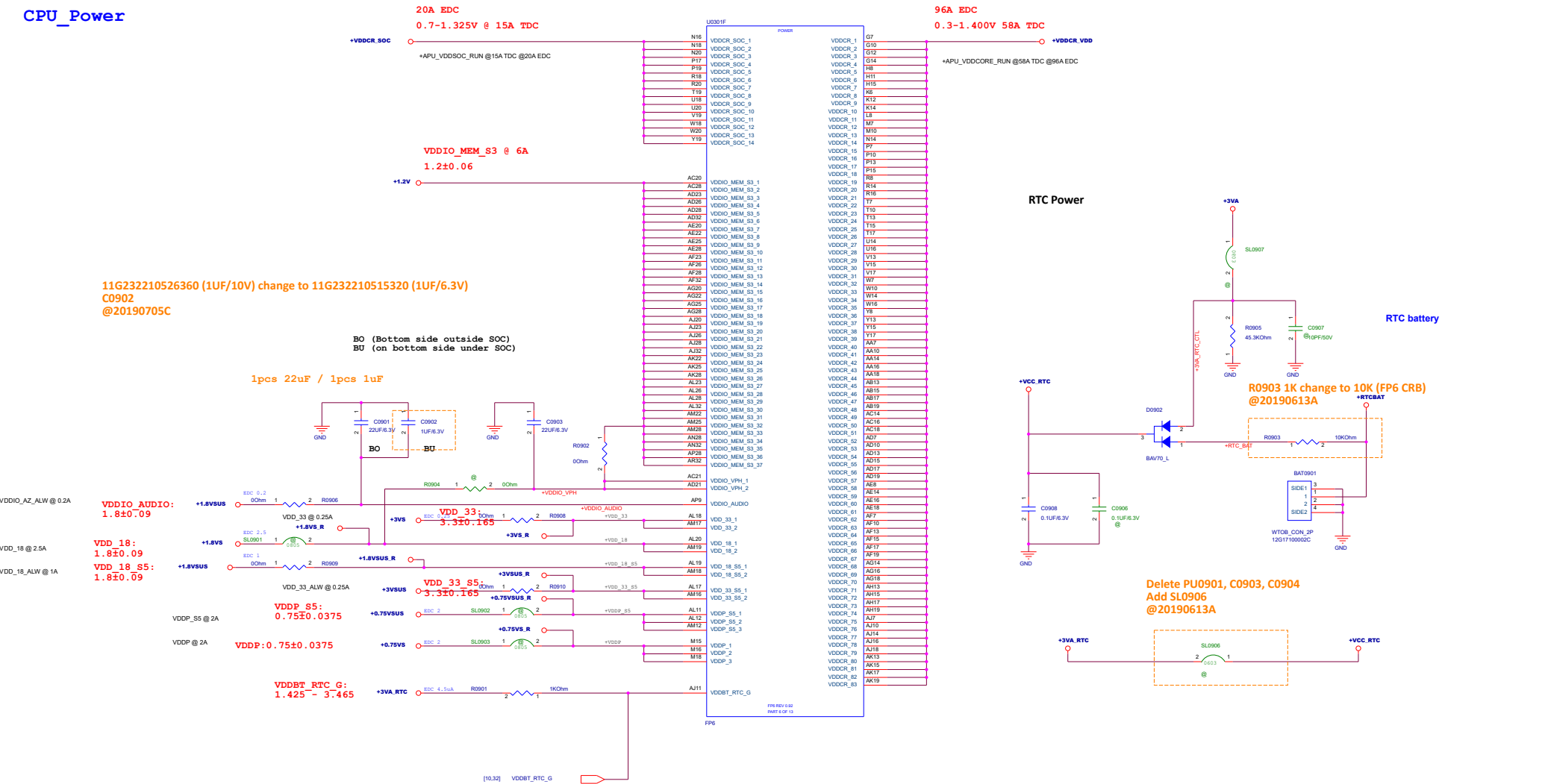
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CPU_Power



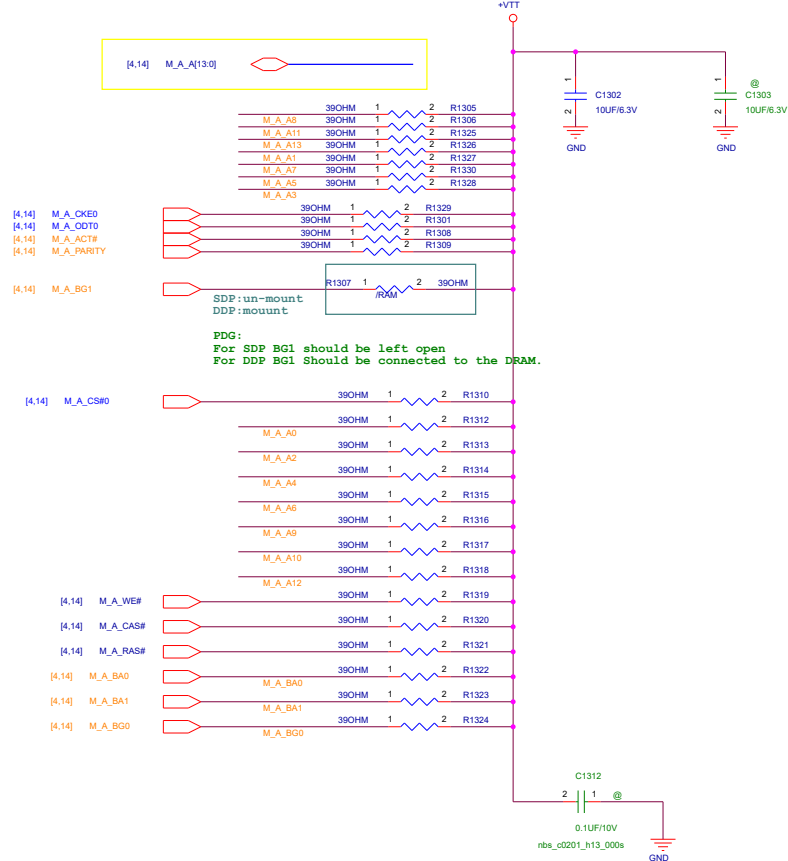
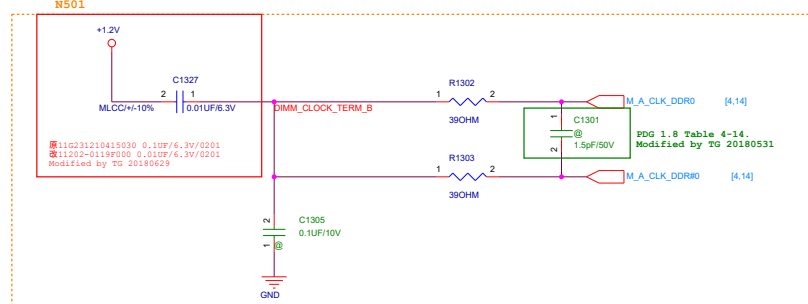


Figure 57. CLK Routing Model (DDR4 x16 DRAM Down)

The termination component values for MA_CLK are listed in Table 40.

Table 40. Component Table—DDR4 x16 CLK Termination

Ref	Value	Tolerance	Package	Comments
R _{TT}	39Ω	5%	0402	CLK termination
C _{TT}	0.1 μF	5%	0402	CLK termination to VSS or VDDIO_MEM_S3. CLK termination must match the CLK reference plane.



Clock Pull up power change from +0.6V to +1.2V (CFL PDG) 20820601

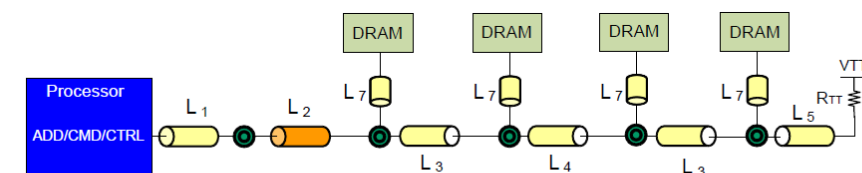


Figure 58. ADD/CMD/CTL Routing Model (DDR4 x16 DRAM Down)

The termination component values for ADD/CMD/CTL are listed in Table 42.

Table 42. Component Table—DDR4 x16 ADD/CMD/CTL Termination

Ref	Value	Tolerance	Package	Comments
R _{TT}	39Ω	5%	0402	ADD/CMD/CTL termination to VTT

<Core Design>

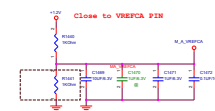
[illegible]

The figure shows two cross-sectional schematic diagrams of power MOSFETs. The top diagram is for a 1000V/100A device, and the bottom diagram is for a 1000V/200A device. Both devices have a 1000V gate oxide, a 100A drain current, and a 100A drain voltage. The 1000V/200A device has a 200A drain current and a 200A drain voltage. The diagrams show the internal structure of the MOSFETs, including the gate, drain, and source regions, and the various layers and contacts. The 1000V/100A device has a 100A drain current and a 100A drain voltage, while the 1000V/200A device has a 200A drain current and a 200A drain voltage. The diagrams are labeled with '1000V' and '100A' or '200A' to indicate the device parameters.

[illegible][illegible]

Note: 1. Double the capacitor quantity for DRx16 configuration.

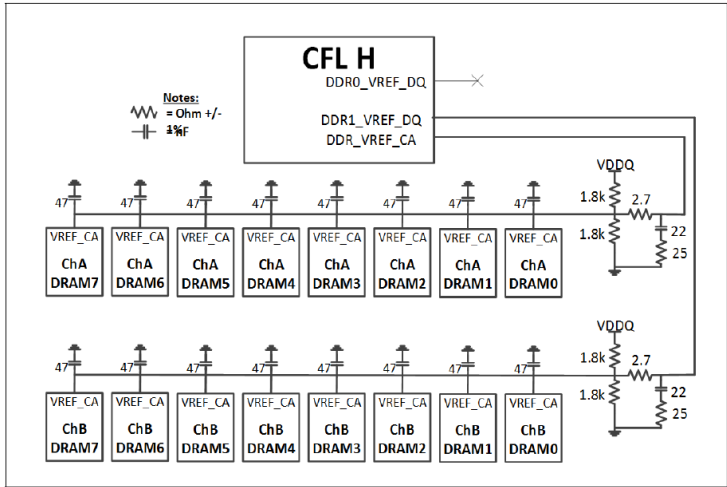
7	8	9
UDQS_c	VSSQ	VDDQ
UDQS_t	UDQ1	VDD
UDQ3	UDQ5	VSSQ
UDQ7	VSSQ	VDDQ
LDM_n/LDBI_n	VSSQ	UZQ
LDQ1	VDDQ	LZQ
VDD	VSS	VDDQ
LDQ3	LDQ5	VSSQ
LDQ7	VDDQ	VDD
CK_t	CK_c	VSS
CS_n	RAS_n/A16	VDD
A12/BC_n	CAS_n/A15	BG1
A3	BA1	TEN
A1	A5	ALERT_n
A9	A7	VPP
VSS	A13	VDD



R1418 1.5K --> 1K (FP6 PR sample)
@20191119E

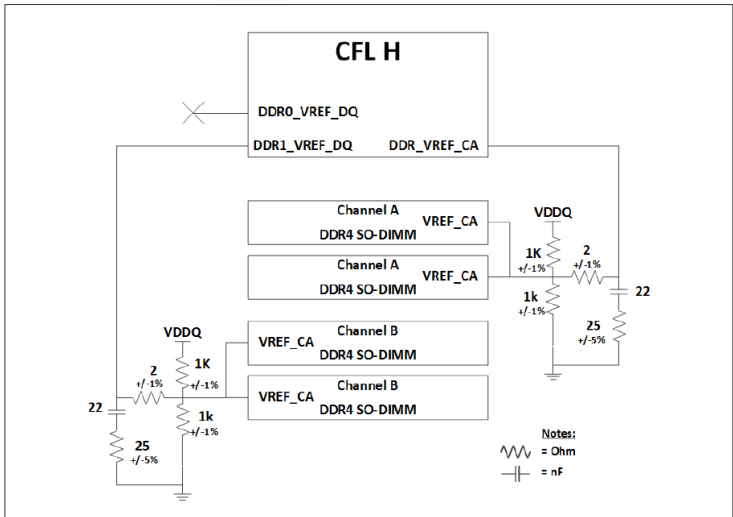
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Size	Document Number		Rev
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Date:	Friday, November 06, 2020	Sheet	17 of 104

Figure 4-24. CFL-H DDR4 x8 Memory Down V_{REF-CA} Overview



Memory Down Vref

Figure 4-22. CFL-H DDR4 SO-DIMM V_{REF-CA} Overview



SO-DIMM1 Vref

SODIMM CHB-DIMM TOP H4.0mm STD (J1601)

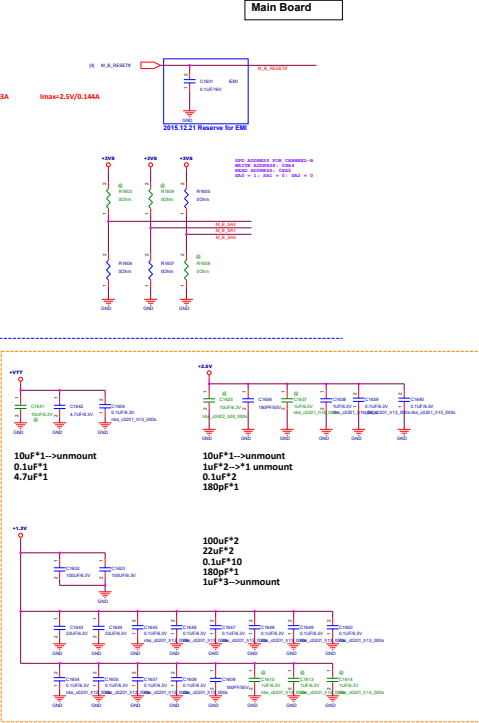
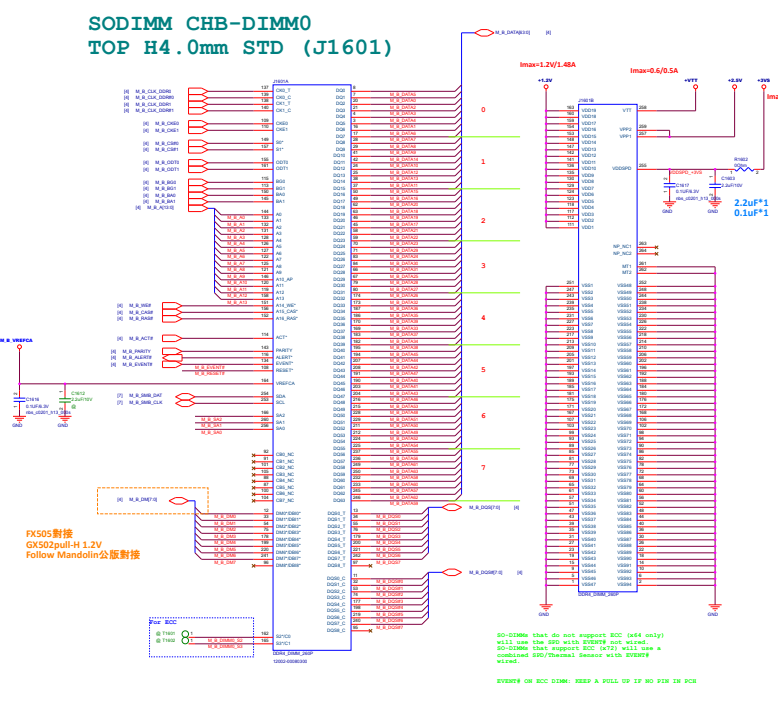



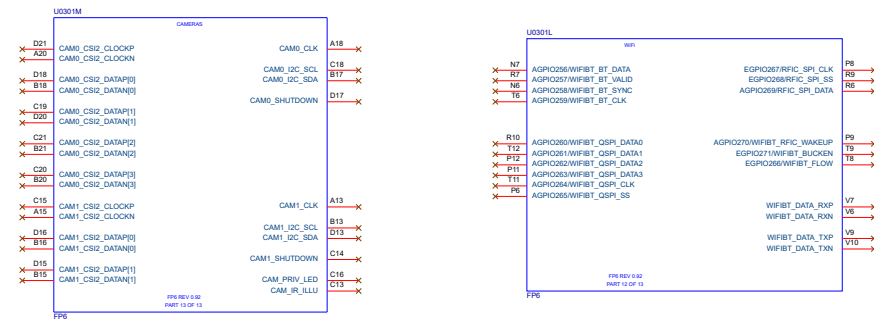
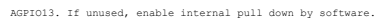
Table 4-24. DDR4 SODIMM Power Plane Decoupling

Memory Configuration	Power Domain	Decoupling Location	Qty x μ F (size)	Note
DDR4 2 Channels SODIMM 1DPC	VDDQ	4 near each side of the DIMM connector close to VDD pins	16x 10 μ F (0603)	
		4 near each side of the DIMM connector close to VDD pins	16x 1 μ F (0402)	
		1 placeholder	1x 330 μ F (7343)	
	VTT	Placed on VTT plane close to DIMM, 1 cap stuffed, 1 placeholder	2x 10 μ F (0603)	
		Placed on VTT plane close to DIMM	4x 1 μ F (0402)	
	VPP	DIMM Pin side, 1 per DIMM	2x 10 μ F (0603)	
		DIMM Pin side, 1 per DIMM	2x 1 μ F (0402)	
	VDDSPD	Place close to DIMM	2x 0.1 μ F (0402)	
		Place close to DIMM	2x 2.2 μ F (0402)	

DDR4 - 2666MHz (8G)
1st : Hynix - 03A08-00051400
2nd : Samsung - 03A08-00051300
DDR4 - 2666MHz (16G)
1st : Hynix - 03A08-00061400
2nd : Samsung - 03A08-00061500

		Project Name	Rev
		GA503QS	1.0
Title : DIM_CA/DQ Voltage			
Size B	Dept.: ASUSTeK COMPUTER	Engineer:	EE
Date: Friday, November 06, 2020	Sheet	19	of 104

Title			
<Title>			
Size	Document Number		Rev
A	<Doc>		R1.0
Date:	Friday, November 06, 2020	Sheet	20 of 104



Title			
<Title>			
Size	Document Number		Rev
A	<Doc>		R1.0
Date:	Friday, November 06, 2020	Sheet	22 of 104

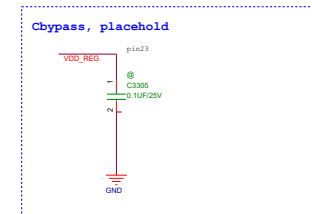
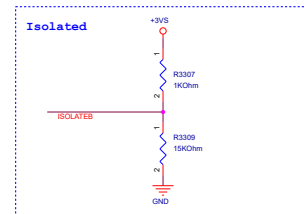
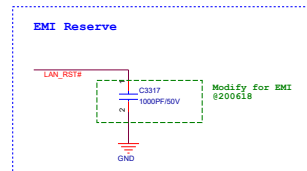
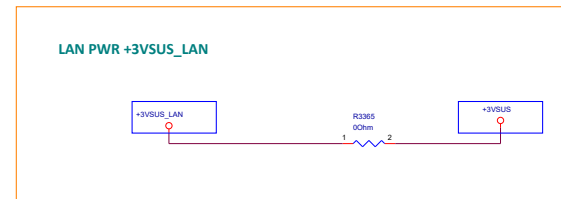
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Size	Document Number		Rev
A	<Doc>		R1.0
Date:	Friday, November 06, 2020	Sheet	15 of 104

Title			
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Size	Document Number		Rev
A	<Doc>		R1.0
Date:	Friday, November 06, 2020	Sheet	23 of 104

Title			
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Size	Document Number		Rev
A	<Doc>		R1.0
Date:	Friday, November 06, 2020	Sheet	24 of 104

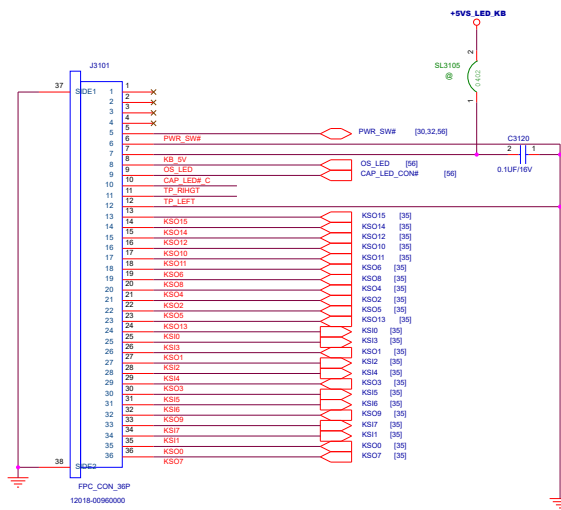
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Size	Document Number		Rev
A	<Doc>		R1.0
Date:	Friday, November 06, 2020	Sheet	25 of 104

Title			
<Title>			
Size	Document Number		Rev
A	<Doc>		R1.0
Date:	Friday, November 06, 2020	Sheet	26 of 104

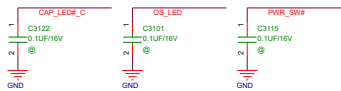


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<Title>			
Size	Document Number		Rev
A	<Doc>		R1.0
Date:	Friday, November 06, 2020	Sheet	29 of 104

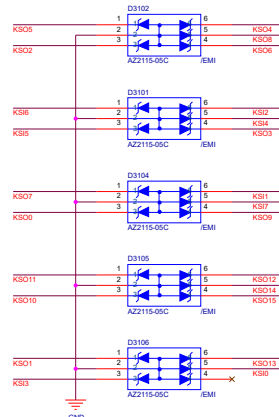
Keyboard Connector



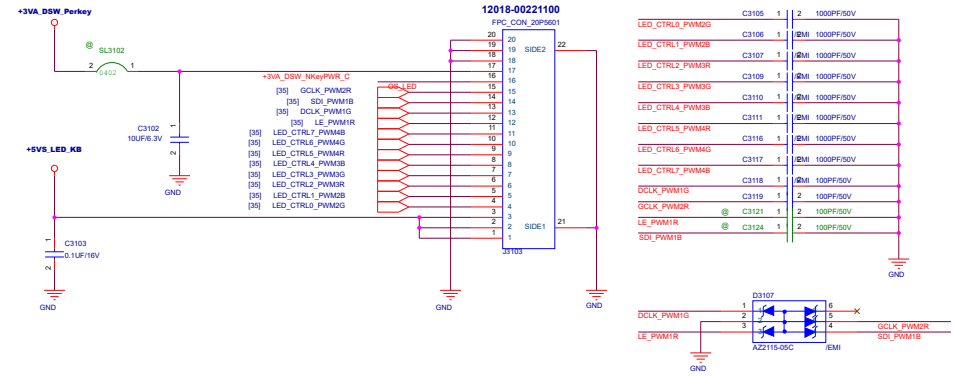
Reserved for EMI



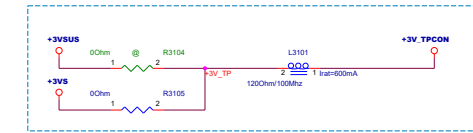
For EMI



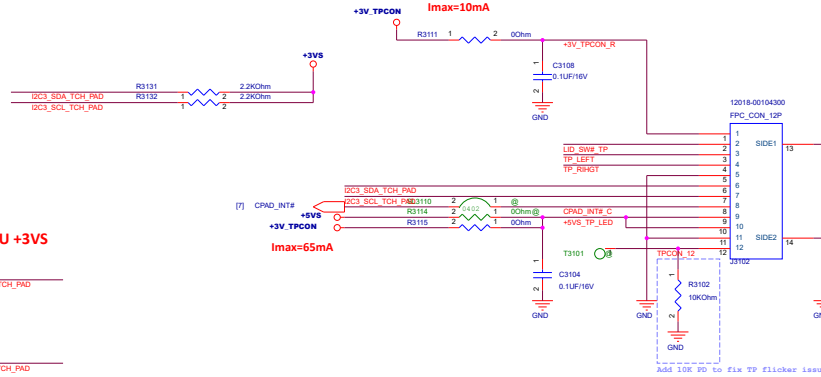
Keyboard LED



Touch Pad / Ten Keys Connector



Add +3V_TPCON option @200521A



1st: 12018-00104300

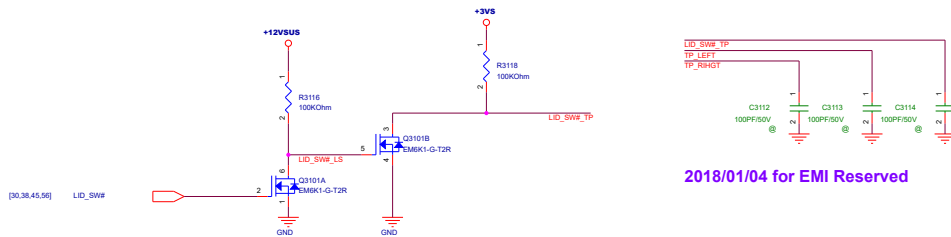
Touch Pad Pin Define

Connector type: 12 pins FFC connector, pitch is 0.5 mm.

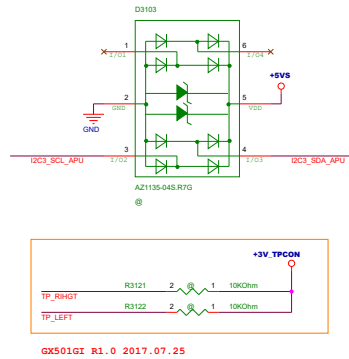
Pin#	Signal	I/O	Description
1	VDD_3.3V	Power	3.3V +/-5% Power ripple: 100 mVpp max. Power sequence: See section 4.6.
2	LID_CLOSE	I	Lid close/open pin. Indicates that the lid is closed or opened. Low when lid is closed. High when lid is opened.
3	SWL	I	Low active, left button signal.
4	SWR	I	Low active, right button signal.
5	GND	GND	Ground
6	SDA	I/O	I2C data. I/O max: 8 mA max.
7	SCL	I/O	I2C clock. I/O max: 8 mA max.
8	INT	O	Active low, indicates that the touchpad plans to send data to host
9	LED_VDD	Power	Power for LED circuit. 3.3V, driver current: TBD
10	LED_VDD	Power	Power for LED circuit. 3.3V, driver current: TBD
11	GND	GND	Ground
12	LED_CONTROL	I	To lighten the LED when high. High active

2nd: 12018-00103800

Reserved for EMI



2018/01/04 for EMI Reserved



GX501GI R1.0 2017.07.25

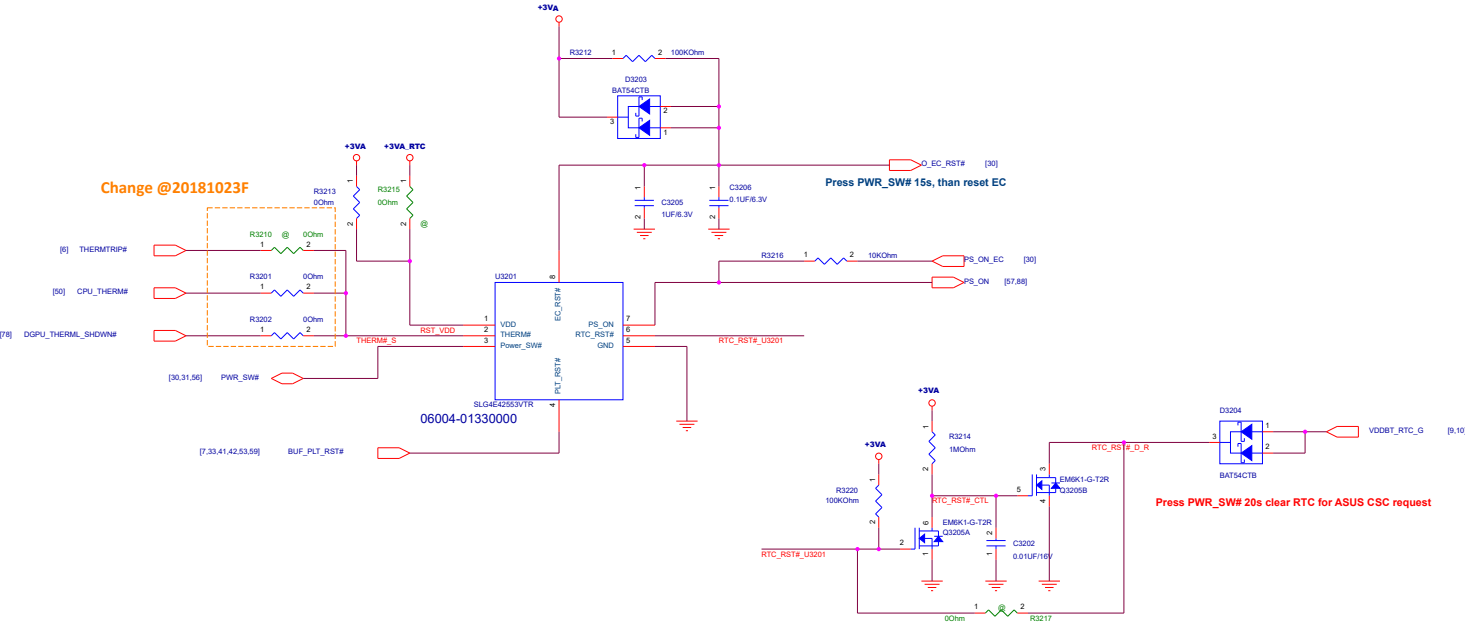
<Core Design>

Modern standby project should use Silego solution for EC/RTC reset (Microsoft hardware requirements)

6.6.2 Power button behavior

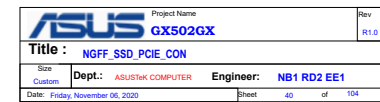
<https://docs.microsoft.com/en-us/windows-hardware/design/minimum/minimum-hardware-requirements-overview#section-60--shared-minimum-hardware-requirements-for-components>

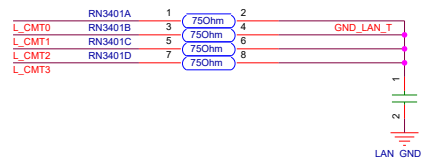
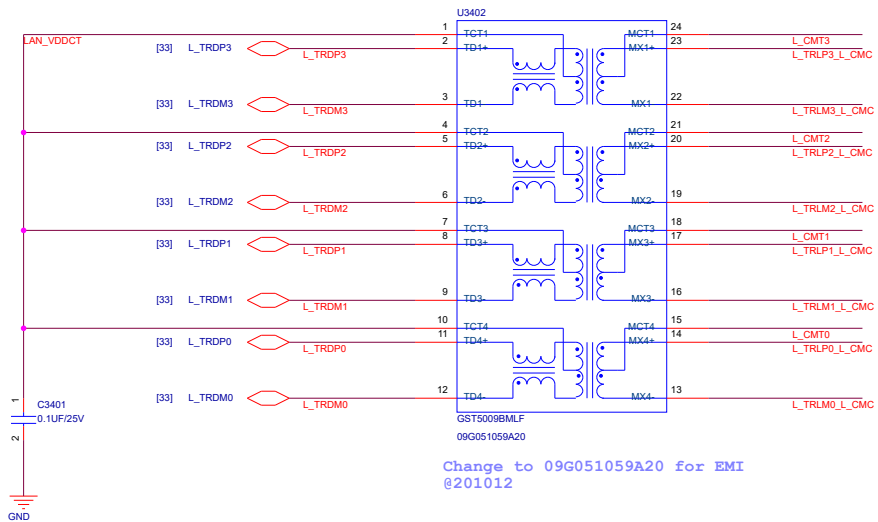
UX362FA R1.3 board will verify this circuit 7/E



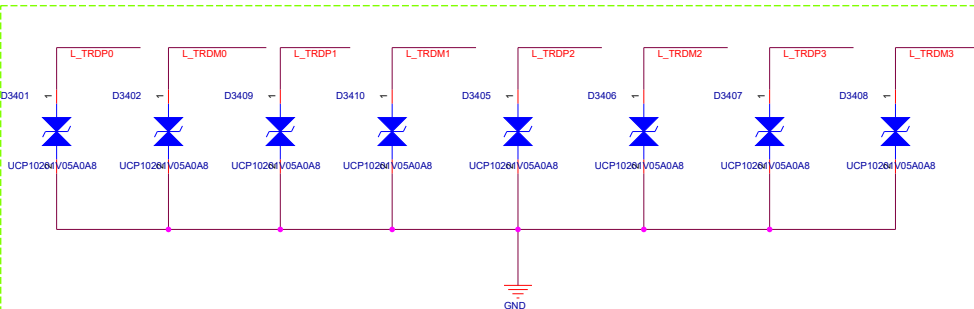
<Variant Name>

ASUS		Title : RST_Reset Circuit	
ASUSTek COMPUTER INC. N64		Engineer: SZNB1	
Size	Project Name	Rev	
II	FX505DY	R1.0	
Date: Friday, November 06, 2020	Sheet	32	of 104

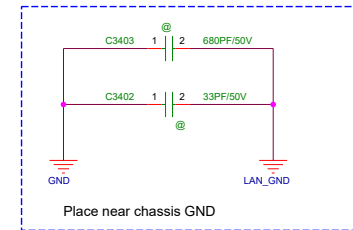
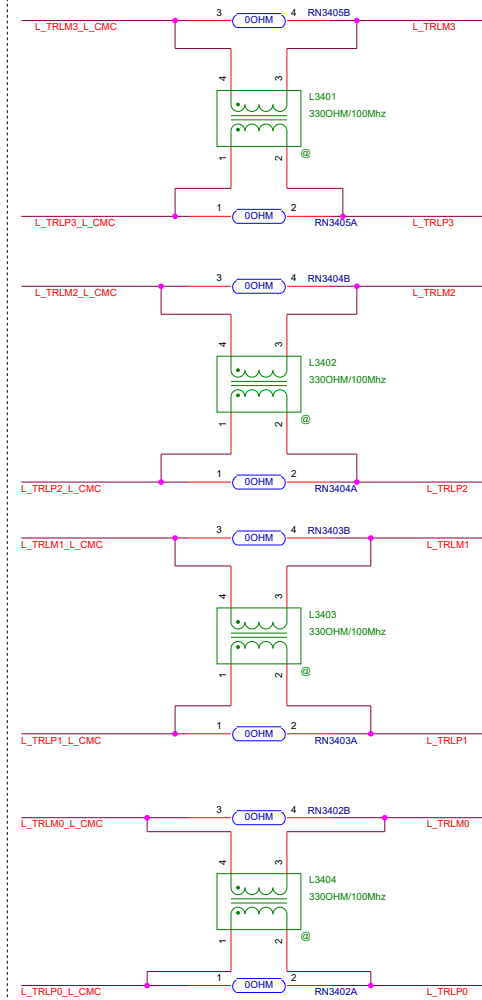




ESD diode change to discrete @0619

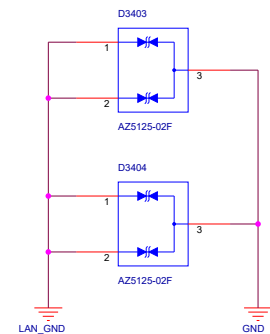


Main Board

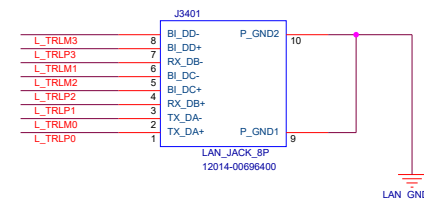


C3402 Change to 33pF mount @200618

C3402 change to 11204-00747000 @200805



LAN Connector



<Variant Name>

Title

<Title>

Size

B

Document Number

GA401

Rev

R1.0

Date:

Friday, November 06, 2020

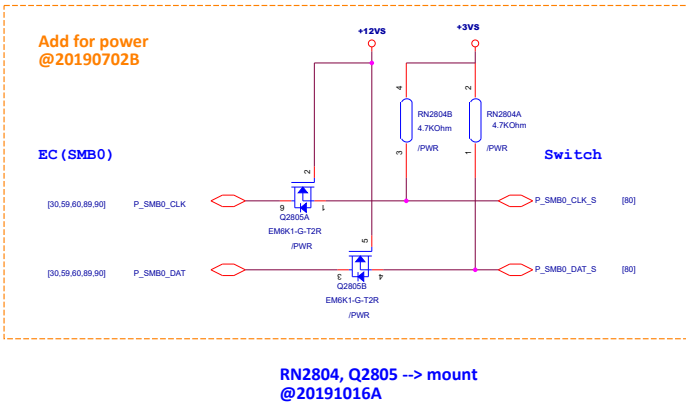
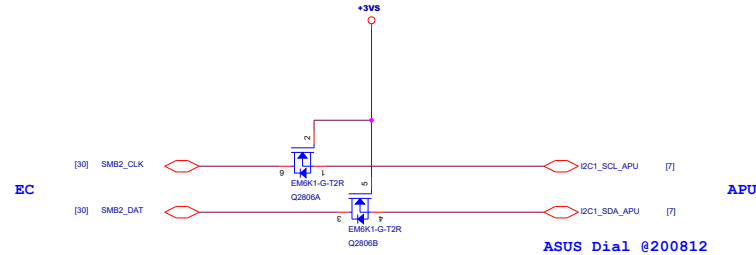
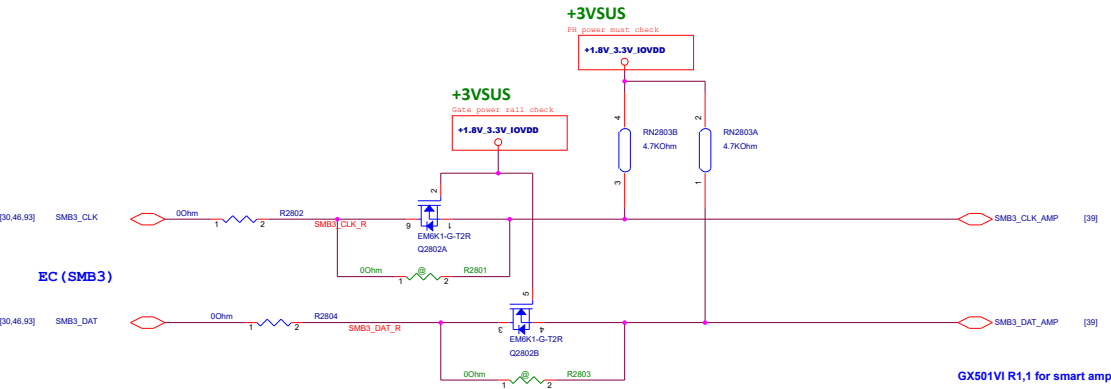
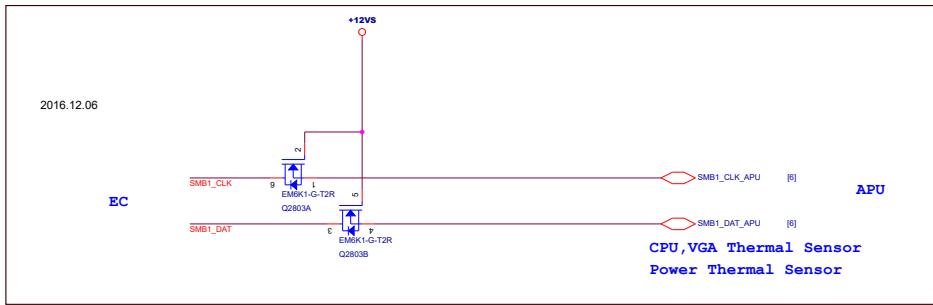
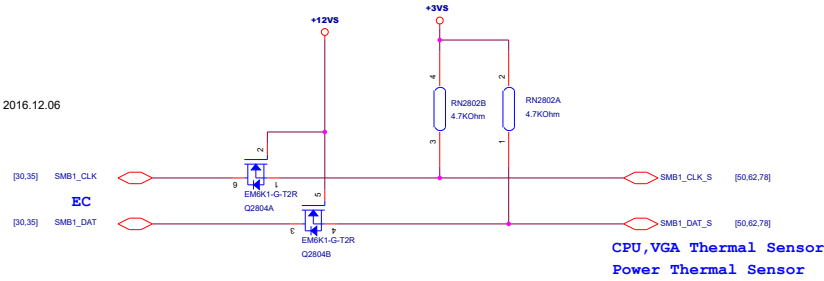
Sheet

27

of

104

Avoid SIC, SID leakage
@20191119D



NKEY_預留0 OHM對接

EC_PU +3VA

APU I2C3_PU +3VSUS

DDR4 SO-DIMM_對接

EC (SMB3)

Type-C PD

Slave charger

EC (SMB1)

Isolation

+3VS

GPU sensor

VRAM sensor

CPU sensor

HDMI_預留

EC (SMB3)

M_B_SMB_DAT

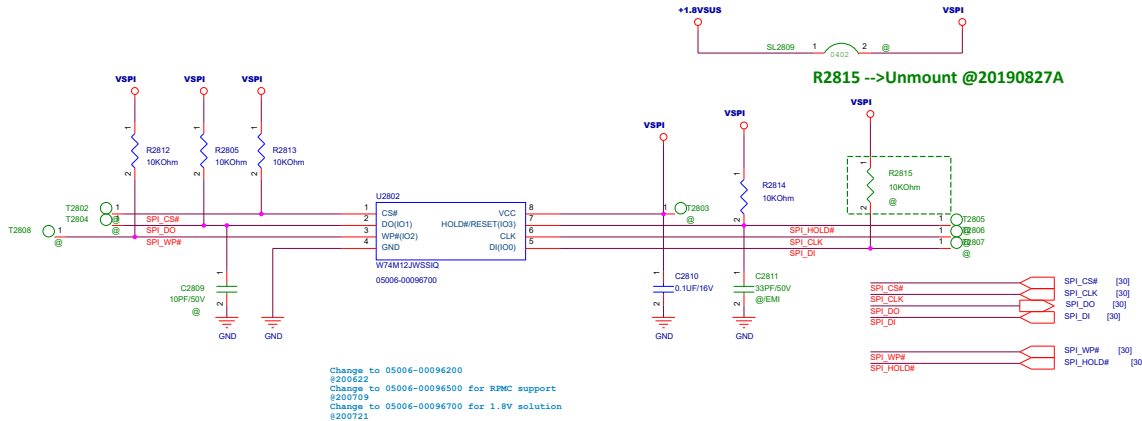
Isolation

+3VSUS
SMB3_CLK_AMP

Audio AMP

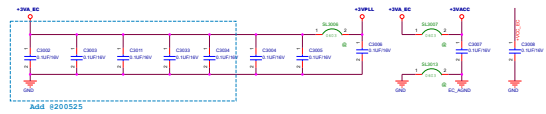
SPI ROM change to P.28
@20190731C

SPI ROM

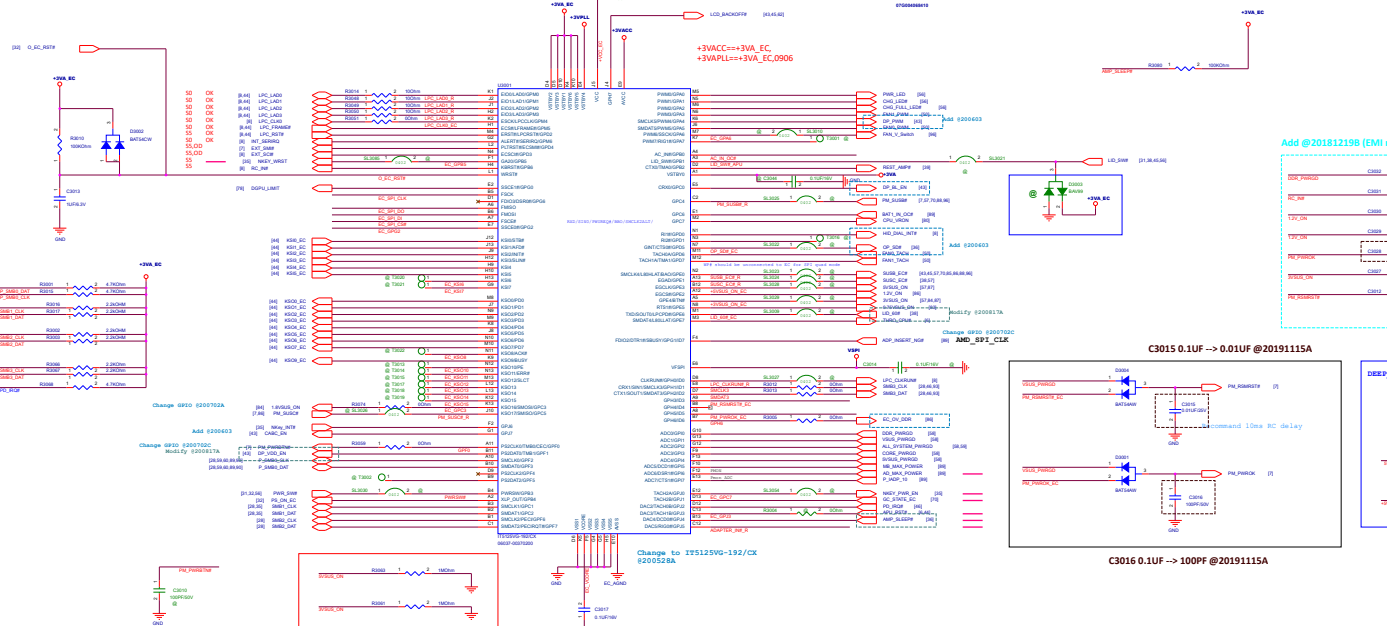


EC Chip - IT8225

EC Power



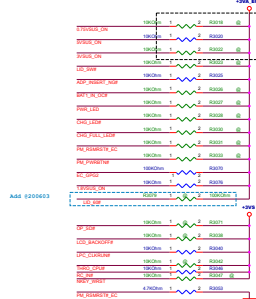
```
VCC => +3VS system power ; LPC
VSTBY=>+3VA_EC ;Power supply of EC power
```



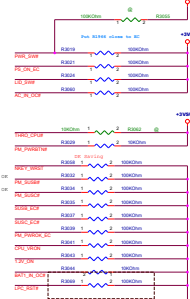
```
for load code
Del 1.8V_ON_EC NET, 0910
```

R3018 & R3022 unmount (shipping mode OD test)
@20200427

Del 1.8V_ON_EC NET, 0910



LPC_CLKRUN# OD, LPC Power Rail +3VS

 Springer

Add R3069 (EC HW Strap Pin)
@20191115A

```
built-in Battery: mount R1937
```

SPI_CLK 10k change to 10 OHM @20181029G

Short Land & 0 ohm

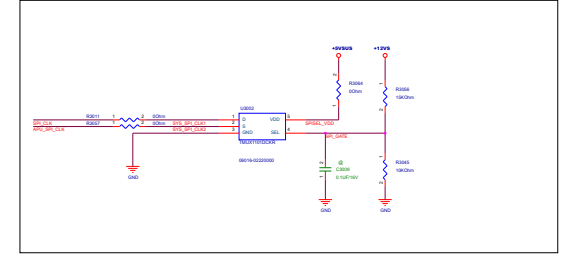
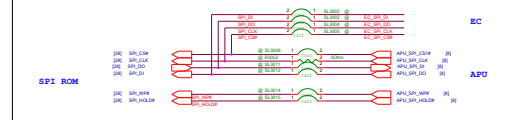


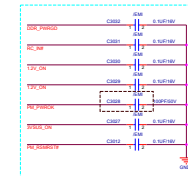
Table 1. TMUX1101 Truth table

SEL	SWITCH STATE
0	OFF (HI-Z)
1	ON

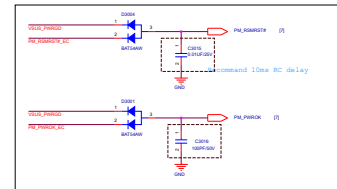
Table 2. TMUX1102 Truth table

SEL	SWITCH STATE
0	ON
1	OFF (HI-Z)

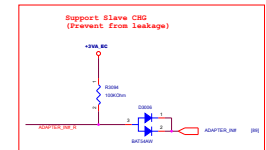
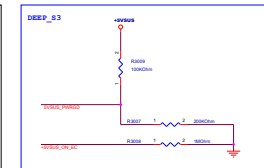
Add @20181219B (EMI request)



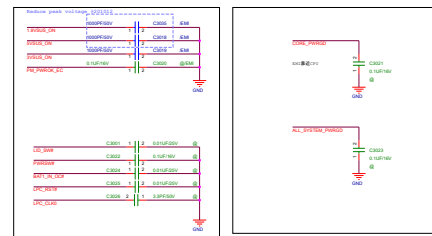
C3015 0.1UF --> 0.01UF @20191115A



C3016 0.1UF --> 100PF @20191115A



Add @20190702A (From GX502)

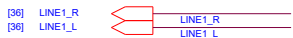


*** POWER

**** [P.36] +12VS_AUDIO**
**** [P.30] +3VA_EC**
**** [P.36] +1V8_AUD_DVDD_IO**

***** SINGAL**

** Line to Codec [36]



** Headset from Codec [36]



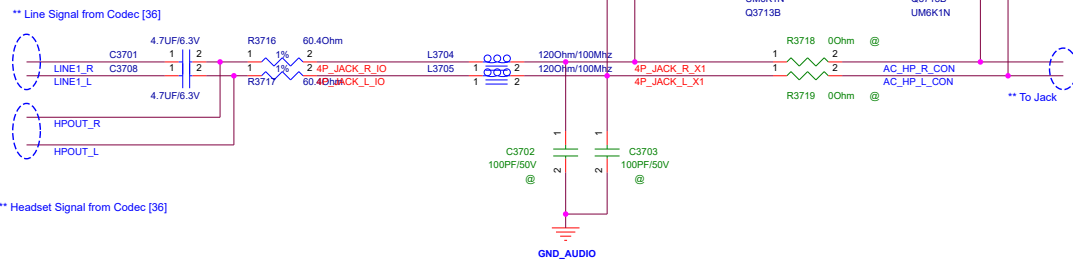
** Control Pin from Codec [36]



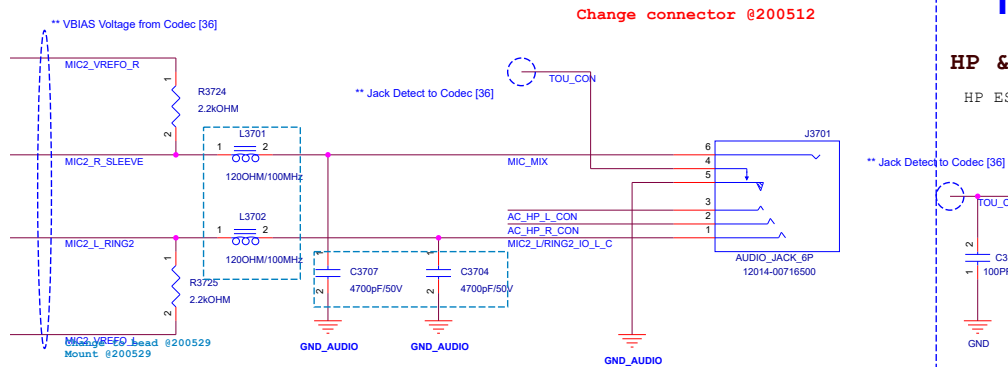
** Control Pin from APU [7]



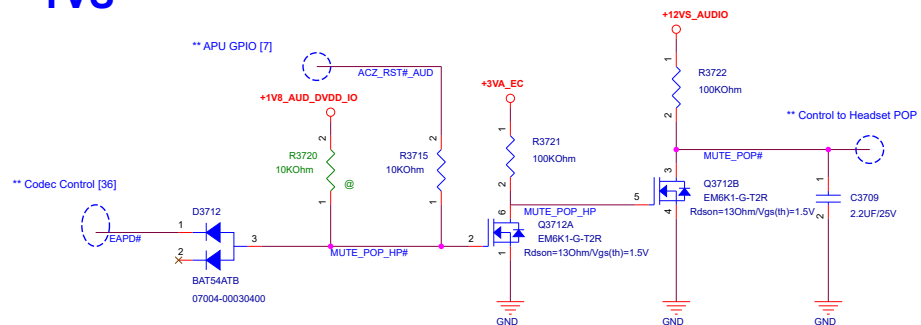
**** Headset and Line**



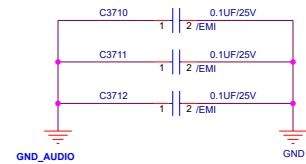
**** Jack and MIC**



**** TVS**



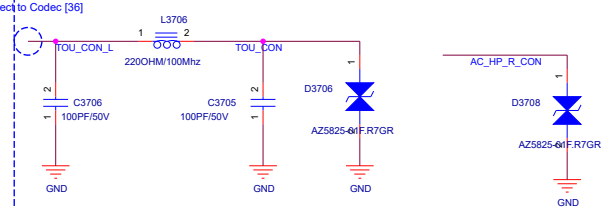
**** A_GND / GND**



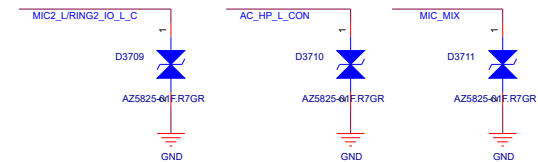
**** TVS**

HP & MIC Connector


HP ESD Protect

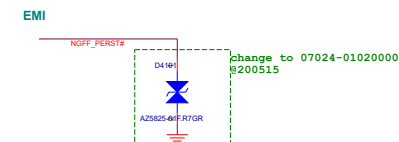


EXTERNAL MICROPHONE



Change to 07024-01152200 for EMI
@200522

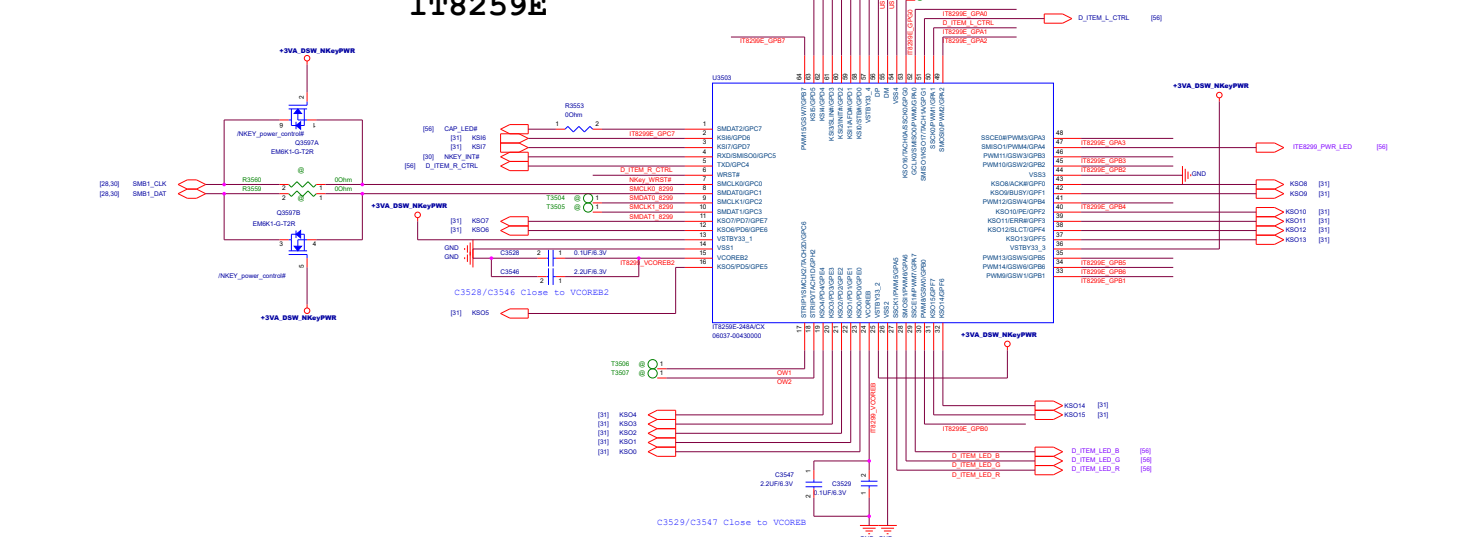
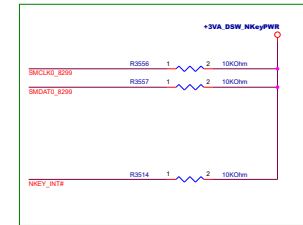
		Project Name GX531GX		Rev R1.0	
Title : AUDIO ALC3236-CG/VB2 Jack					
Size B		Dept.: ASUSTeK COMPUTER INC. Engineer:			
Date: Friday, November 06, 2020			Sheet 37 of 104		



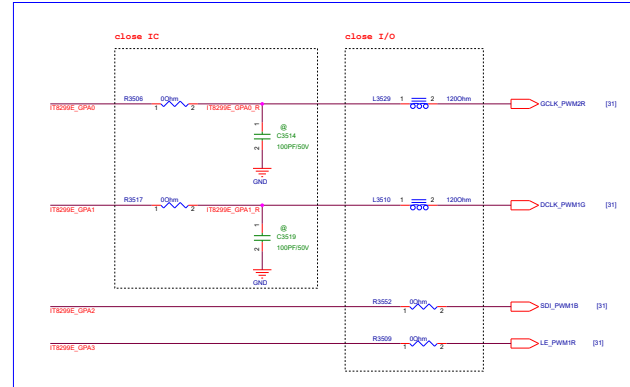
Close to Device connector



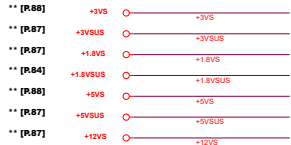
Page 10 of 10



PerKey Signal

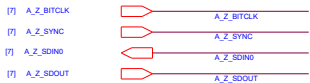


*** POWER



*** SINGAL

** PCH Control



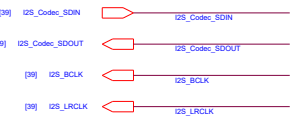
** EC Control



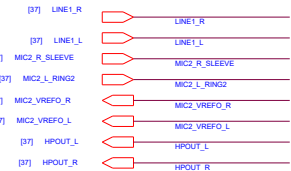
** Jack Control



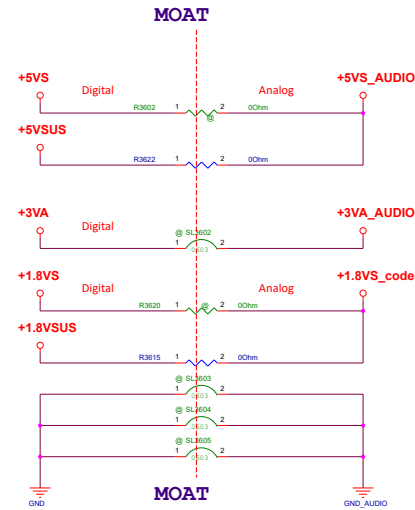
*** To EXT. Amp.



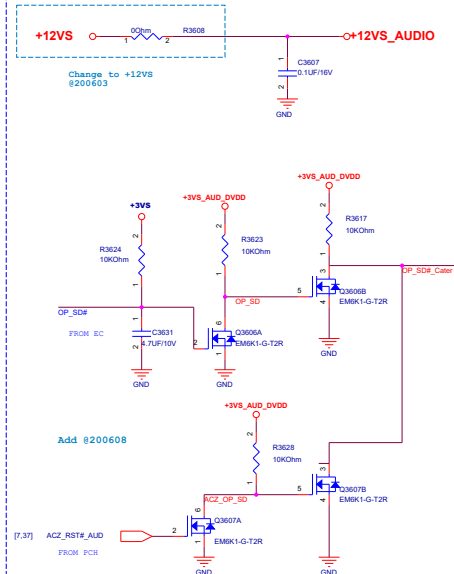
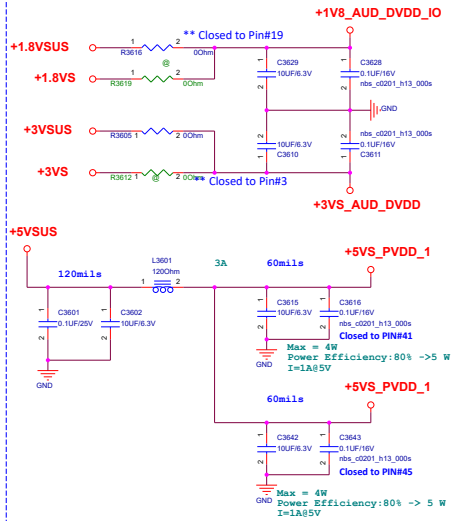
** Headset Connection



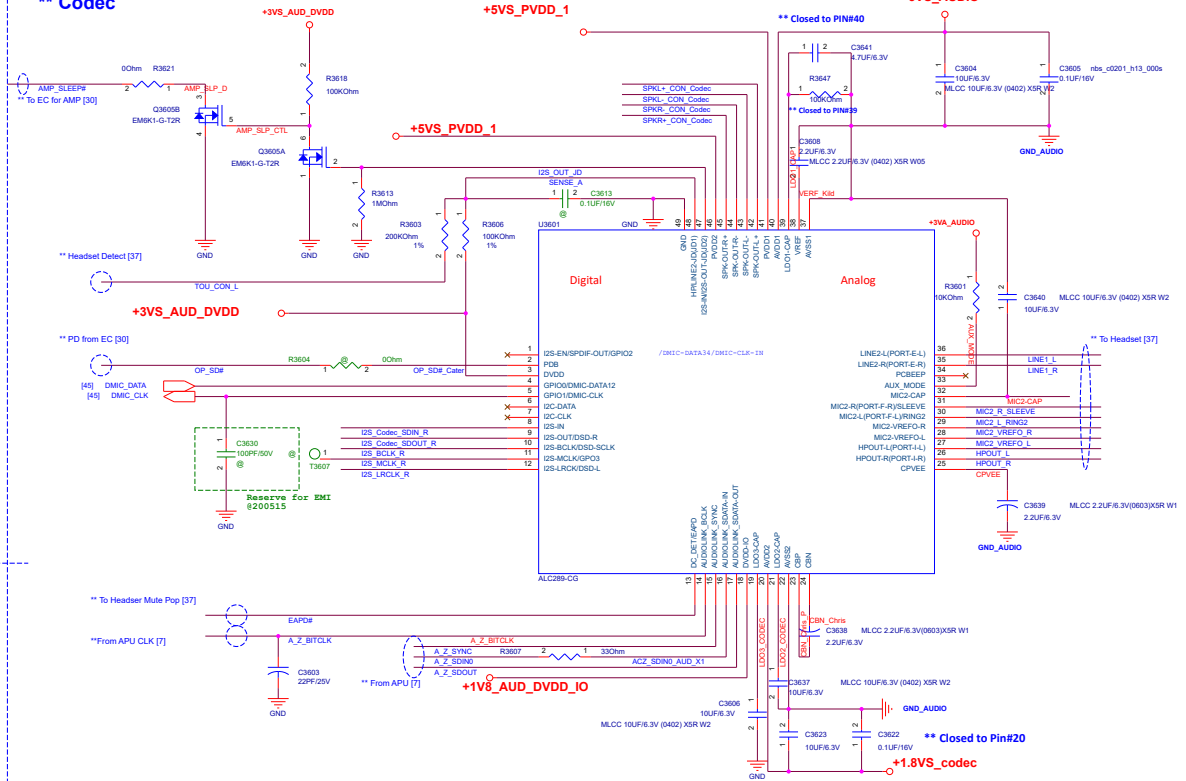
** PWR DISTRIBUTION (ANALOG)



** PWR DISTRIBUTION (DIGITAL)

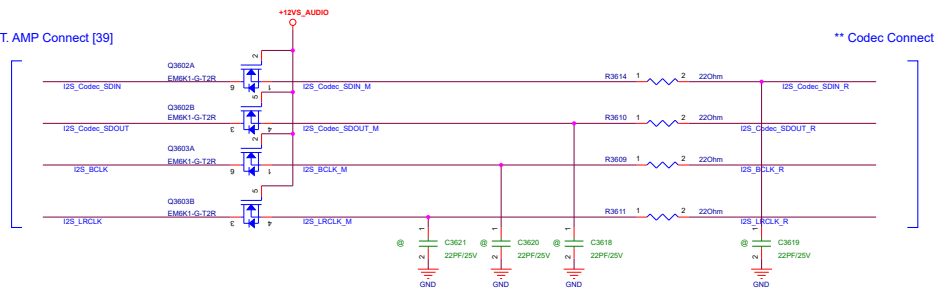


** Codec

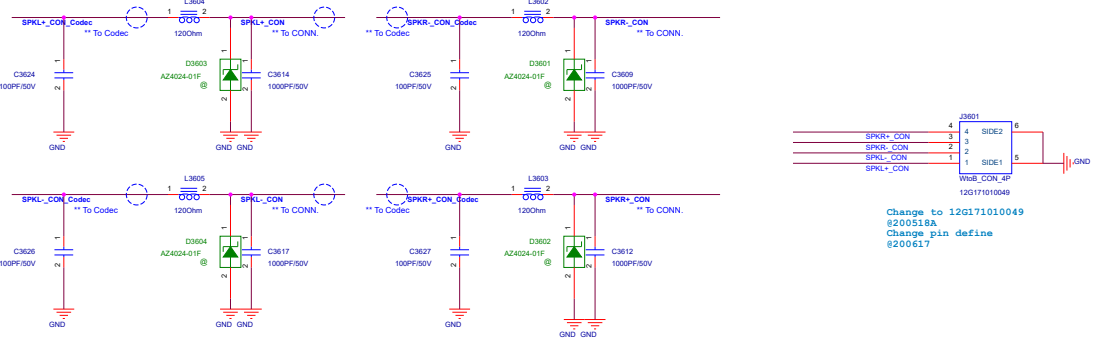


** EXT. AMP Connection

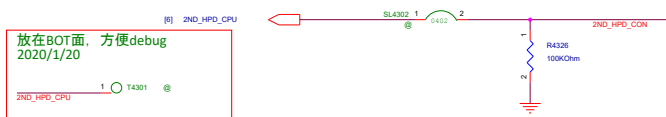
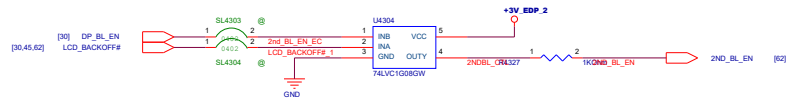
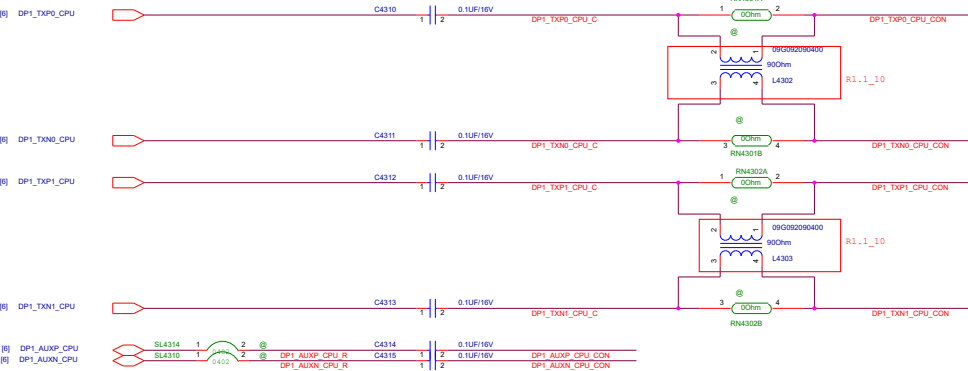
** EXT. AMP Connect [39]



** Tweeter AMP CONN.



<Core Design>

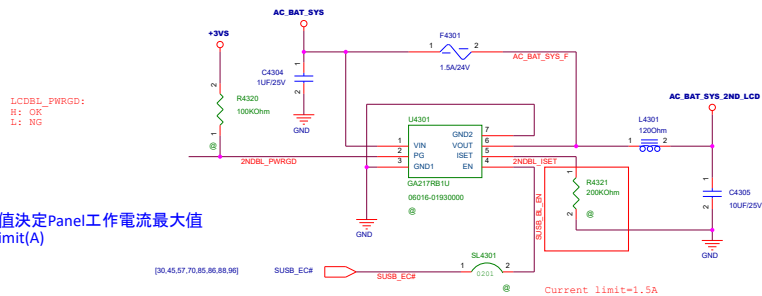


LCD Power switch

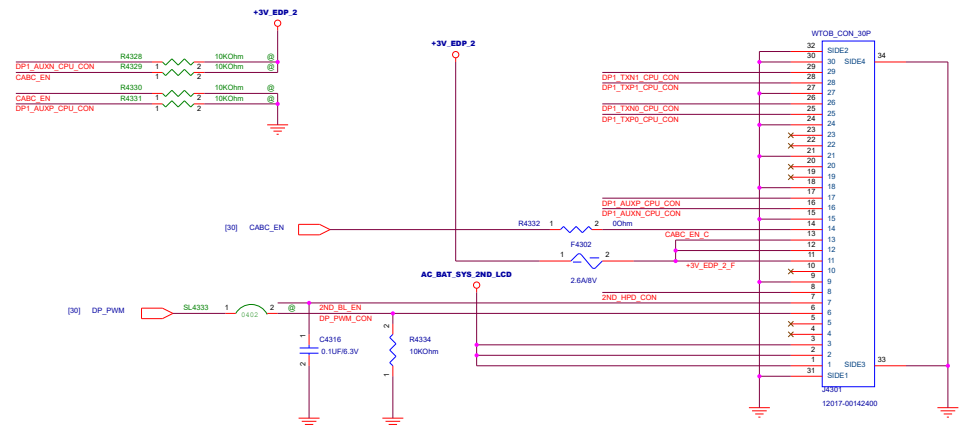
Power Switch IC Protection Circuit

180423 Holton
Add Power Switch circuit with GA217 06016-01930000

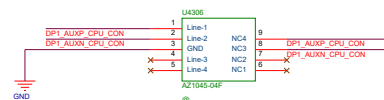
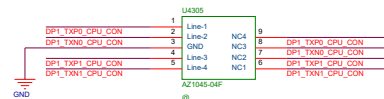
Mark Copy UX461FN 1129



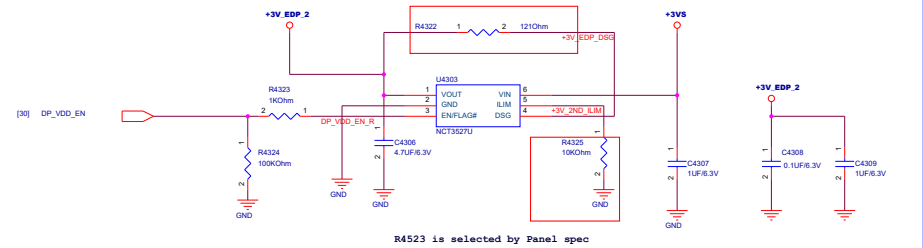
※R_iset (R4541)的阻值決定Panel工作電流最大值
 $R_{iset}(\text{Kohm}) = 300 / I\text{-limit(A)}$



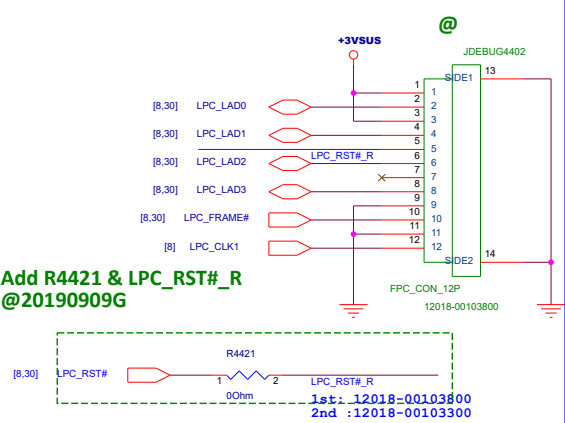
For ESD



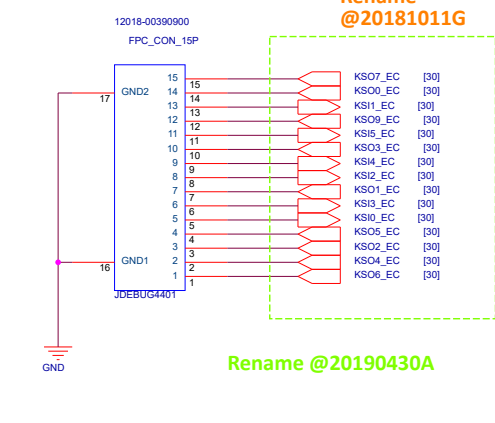
LCD Power switch



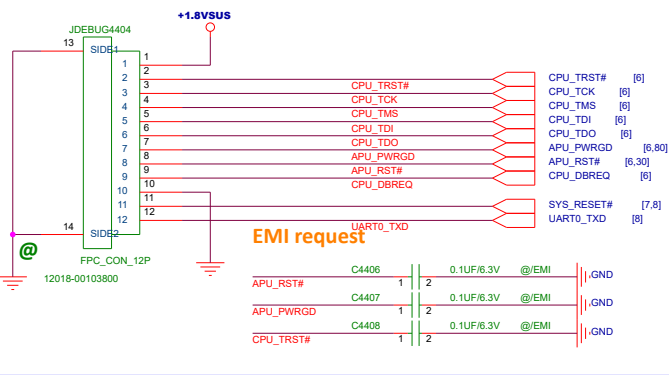
LPC Debug Port 2017/11/10



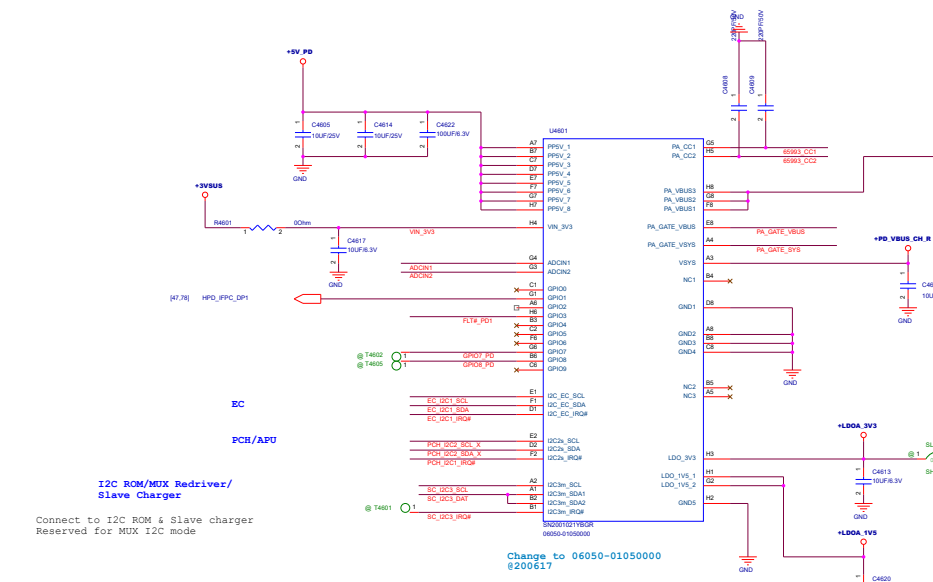
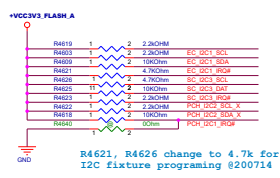
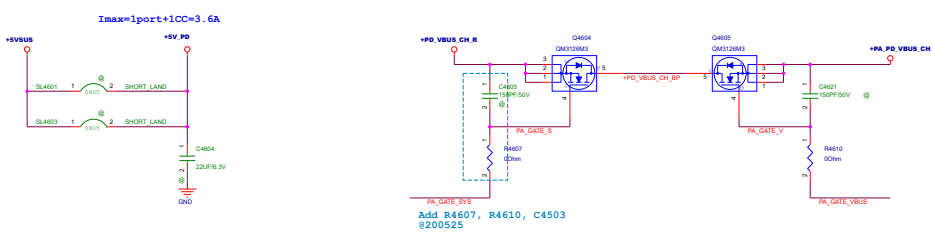
2017/11/10 Flash BIOS



HDT + UART Debug



<Core Design>

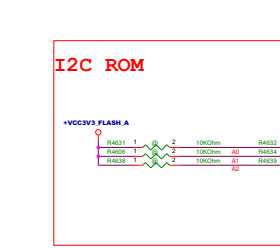


I2C ROM/MUX Redriver/
Slave Charger

Connect to I2C ROM & Slave charger
Reserved for MUX I2C mode

	W/O I2C ROM	W/ I2C ROM
R4620	4.7K ohm	umount
R4612	1K ohm	1K ohm
R4608	4.7K ohm	umount
R4605	1K ohm	1K ohm

Supported Slave Charger



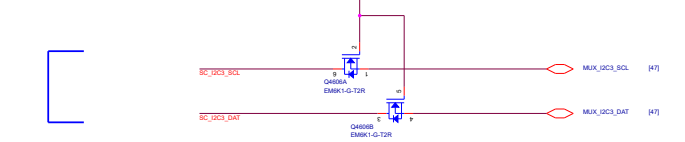
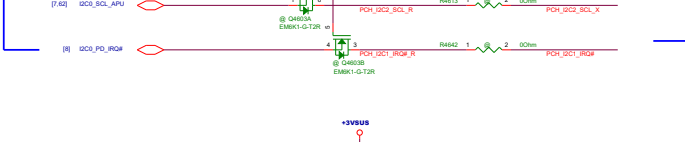
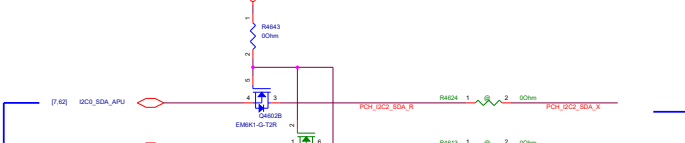
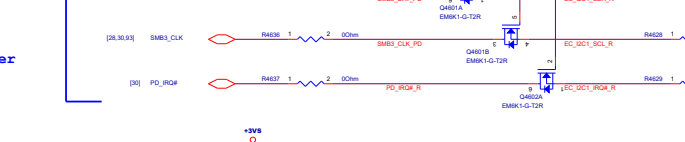
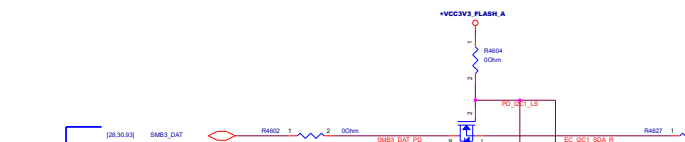
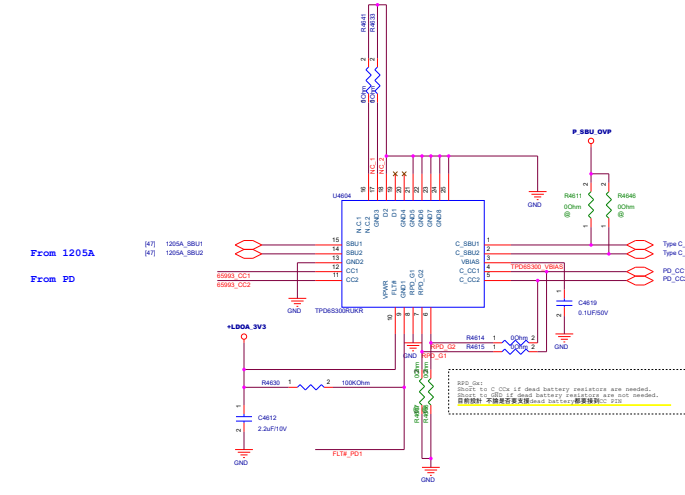
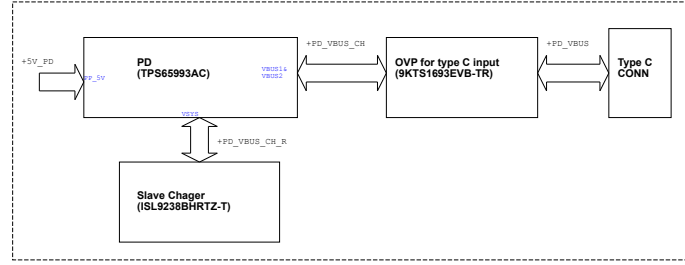
EC & Slave Charger



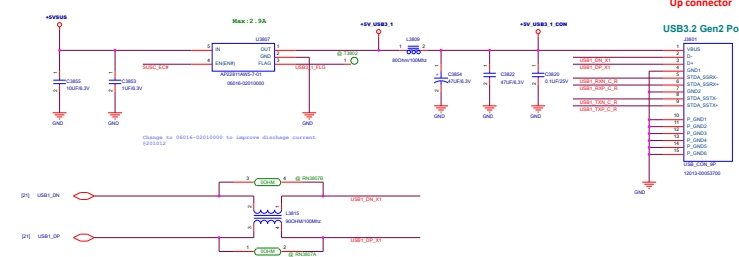
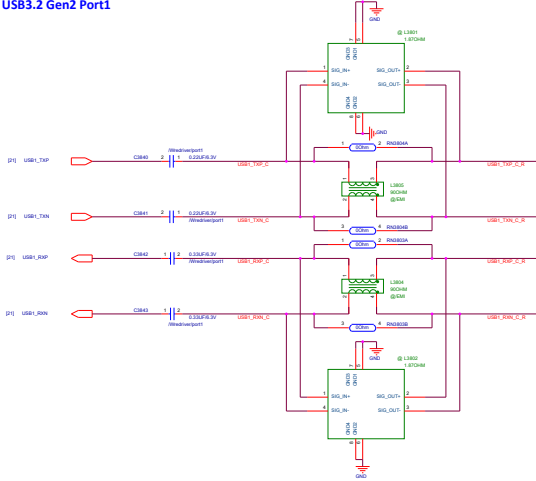
PD I2C ROM



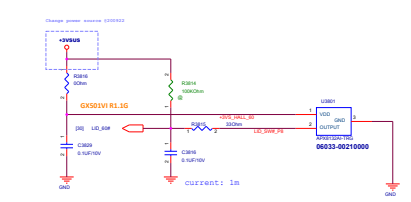
Power Flow Chart



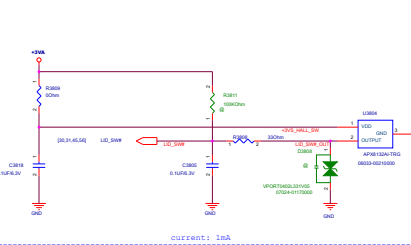
USB3.2 Gen2 Port1



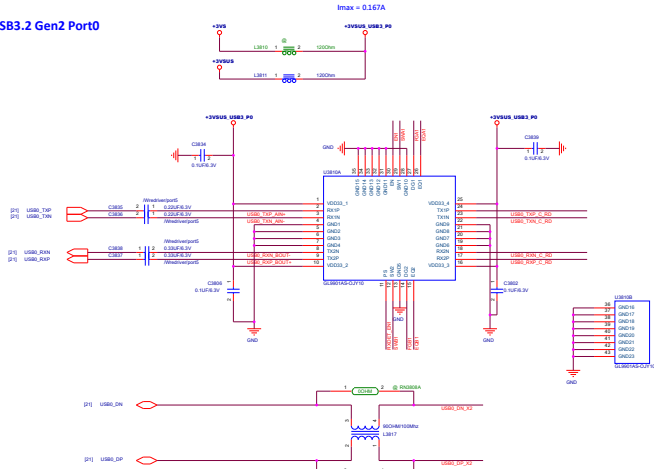
HALL Sensor for 60 degree



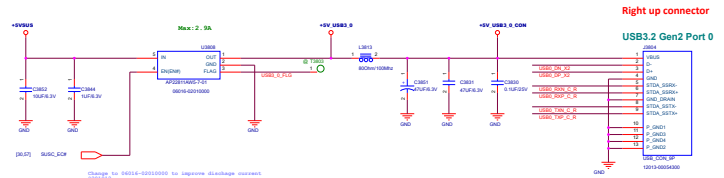
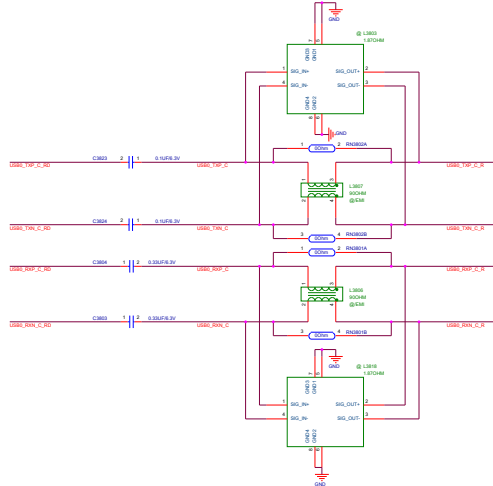
HALL Sensor



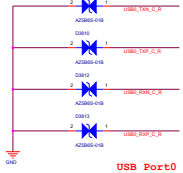
USB3.2 Gen2 Port0



Close to Connector side



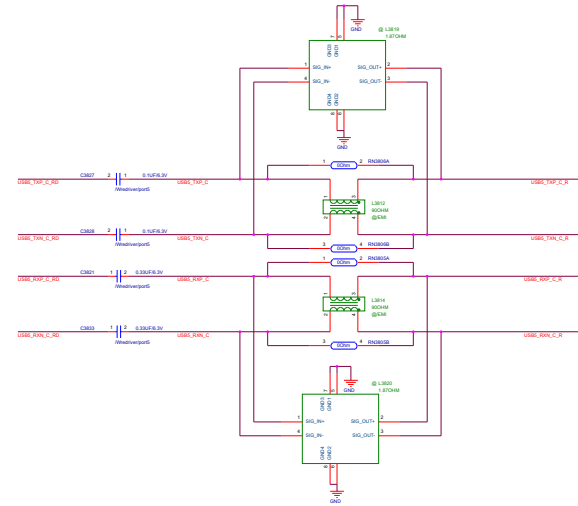
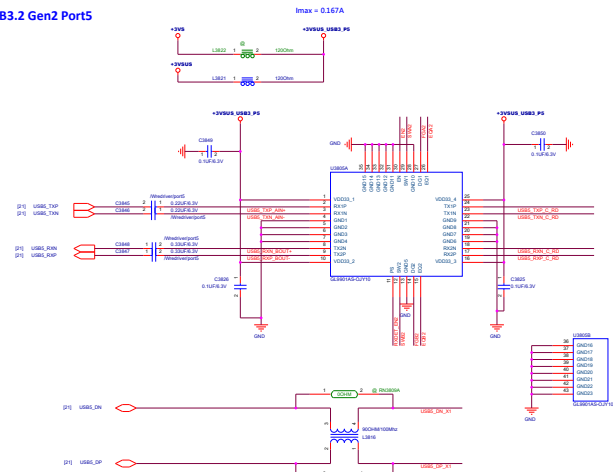
USB3.0 ESD-Protection



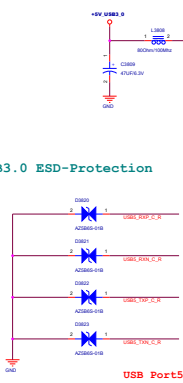
USB2.0 ESD-Protection



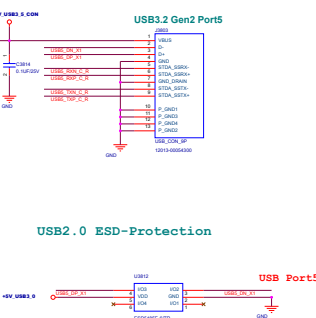
USB3.2 Gen2 Port5



USB3.0 ESD-Protection

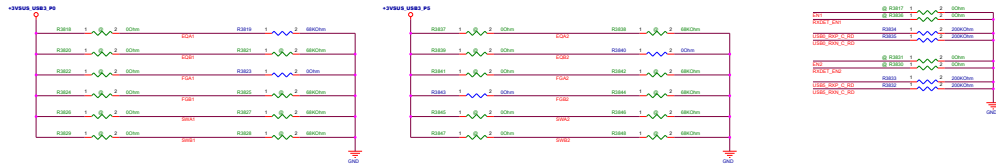


USB2.0 ESD-Protection



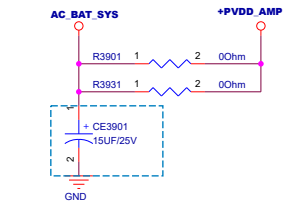
< Fine tune table for Pericom (One port Gen2) >

< EQ table for Pericom 1002B >			
RZ(A,B)	Gen 1 @2.5Gbps	Gen 2 @5Gbps	
0 : 0 Ω to GND	5.1	10.9	
R : Rest to GND	1.9	6.7	
F : Leave Open	3.5(Default)	8.9(Default)	
1 : 0 Ω to VDD	6.8	13.1	
Note : With internal 100kOhm pull-up Res and 200kOhm pull-down Res. Rest = 50kOhm			
< FG table for Pericom 1002B >			
RZ(A,B)	Flat Gain (dB)		
0 : 0 Ω to GND	-3.0		
R : Rest to GND	-1.5		
F : Leave Open	0 (Default)		
1 : 0 Ω to VDD	+2.0		
< SW table for Pericom 1002B >			
SW(A,B)	Output Linear Swing (mV)		
0 : 0 Ω to GND	800		
R : Rest to GND	1200		
F : Leave Open	1000 (Default)		
1 : 0 Ω to VDD	1300		
< Channel / Receiver setting for Pericom 1002B >			
Setting	Channel Enable [EN]	Receiver Detection [RDET_EN]	
0 : 0 Ω to GND	Disable	Disable	
1 : 0 Ω to VDD	Enable(Default)	Enable(Default)	
Note	Channel Enable / Receiver detection With internal 300K pull-up R.		



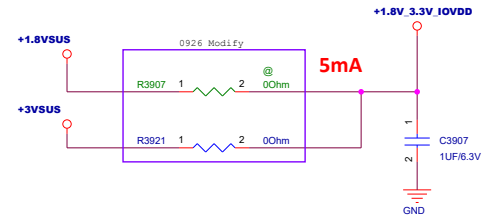
©Giga Design

SPK Power



Add to follow design IP @200612A
Change to 11020-00084000 (H=2.1mm) @201006A

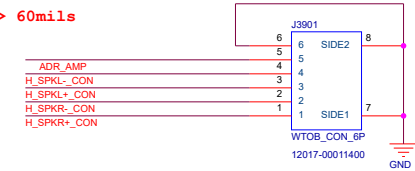
IO Power



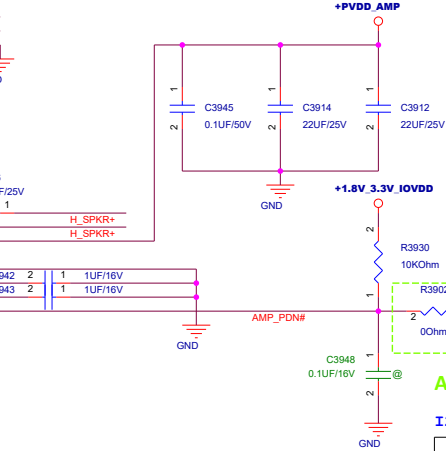
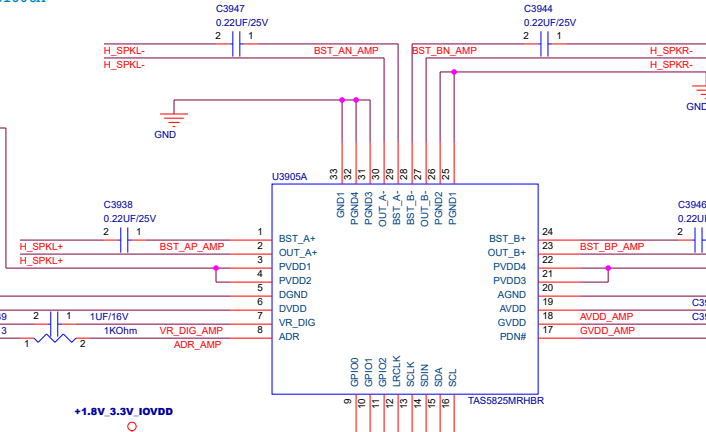
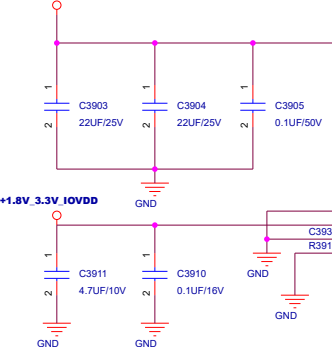
INTERNAL SPK1 Conn.

SPK L+ L- R+ R- trace width
Speaker 8 ohm
Max = 1.5W / Channel
I = 0.43 A

(Smart AMP MAX 2A/Channel) ==> 60mils



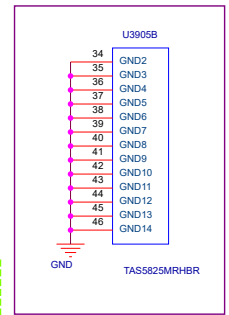
+PVDD_AMP



Add REST_AMP#@20190430A

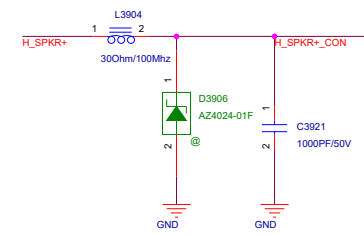
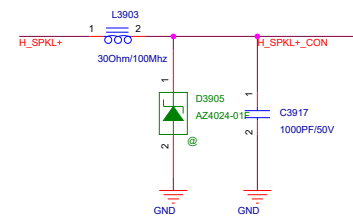
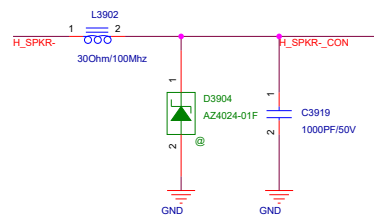
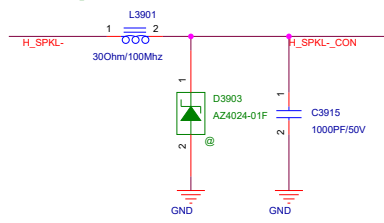
I2C Address Table

	ADR_AMP (SPK)	Address 8bit
Main (N.C.)	Open	0x9A
Second	Short	0x98



0926 Change for additional 13 VIA

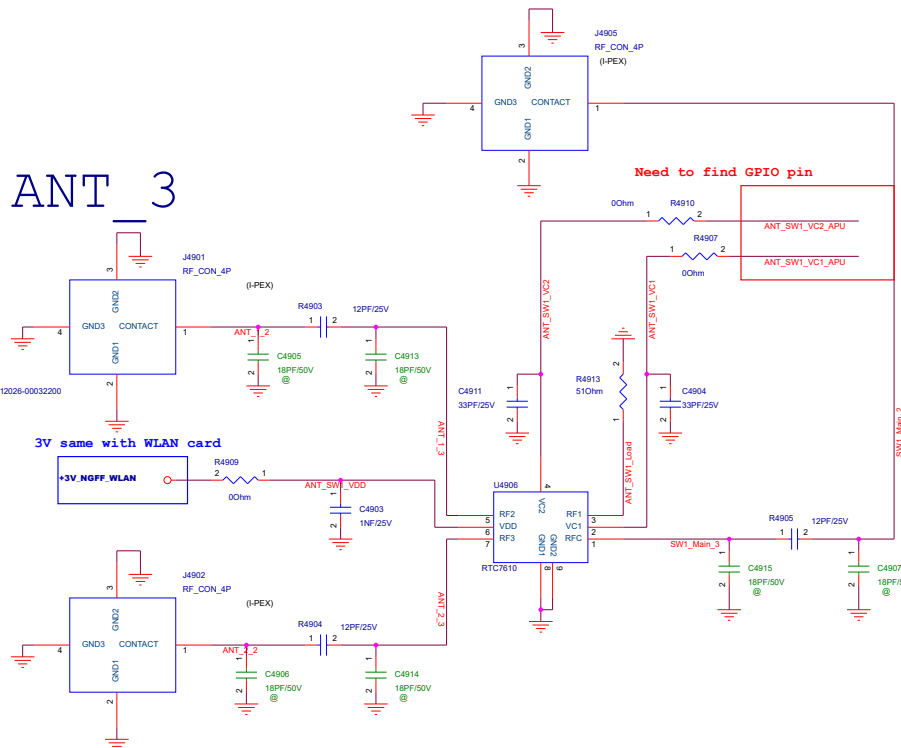
SPK Output



Module_AUX

Module_MAIN

ANT_3

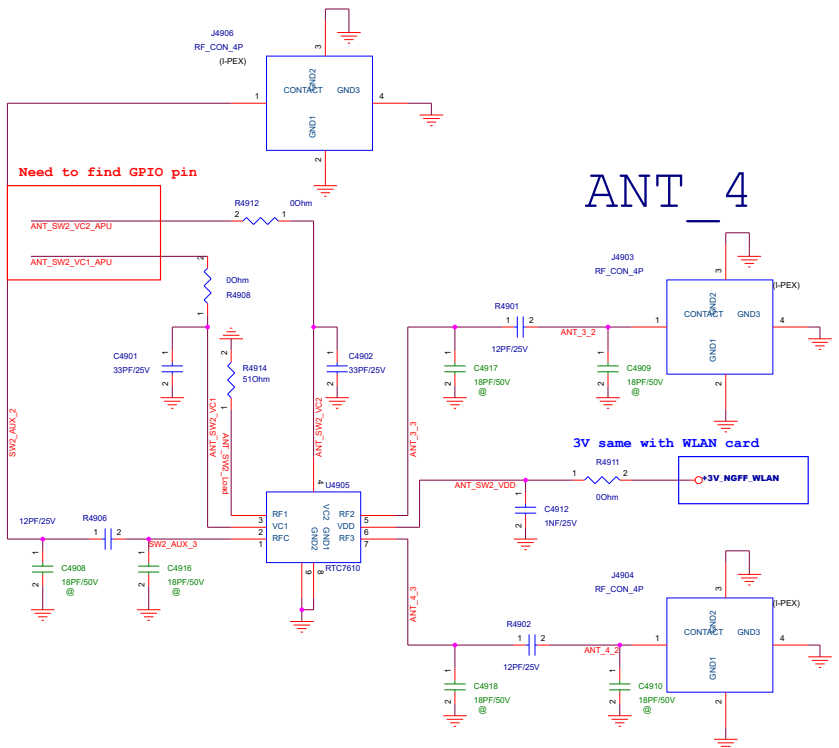


ANT_1

U4906 RTC7610			
ANT	Port	VC1 GPP_B2	VC2 GPP_A19
50 Ω	RF1	1	0
ANT_3	RF2	X	1
ANT_4	RF3	0	0

X: don't care
0: -0.2v~0.3v
1: 1.6v~3.6v

ANT_4



ANT_2

U4905 RTC7610			
ANT	Port	VC1 GPP_B0	VC2 GPP_A18
50 Ω	RF1	1	0
ANT_1	RF2	X	1
ANT_2	RF3	0	0

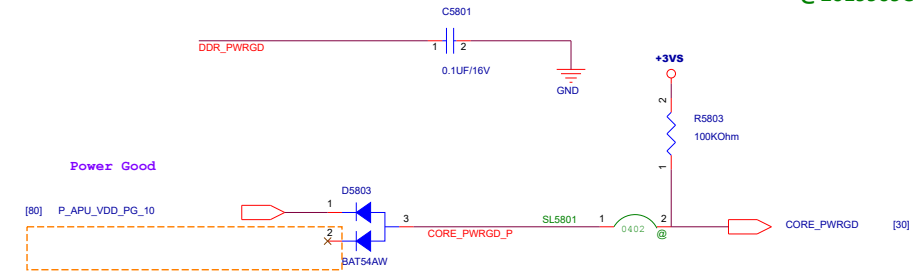
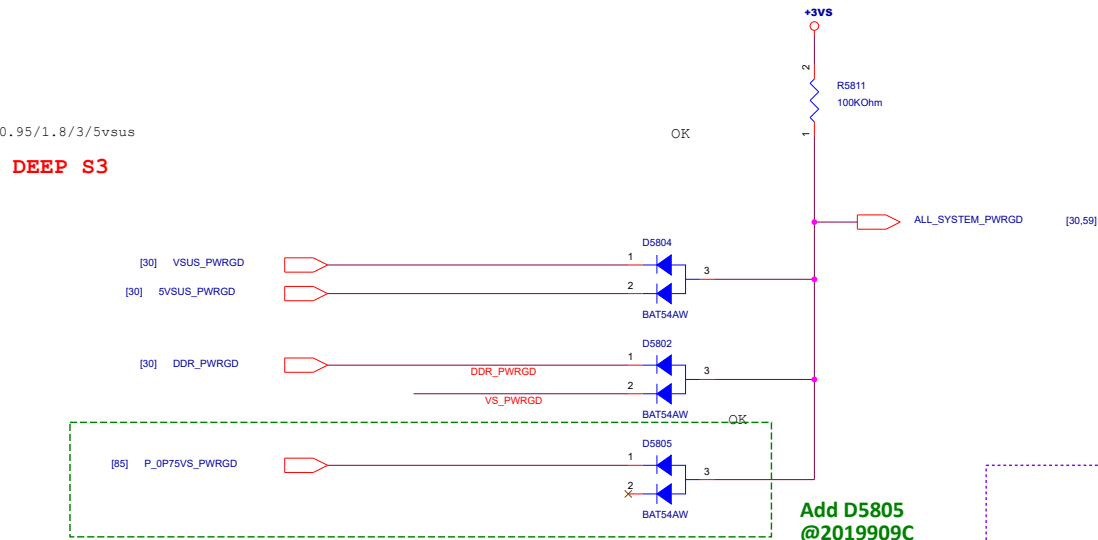
X: don't care
0: -0.2v~0.3v
1: 1.6v~3.6v

<Core Design>

POWER GOOD DETECTOR

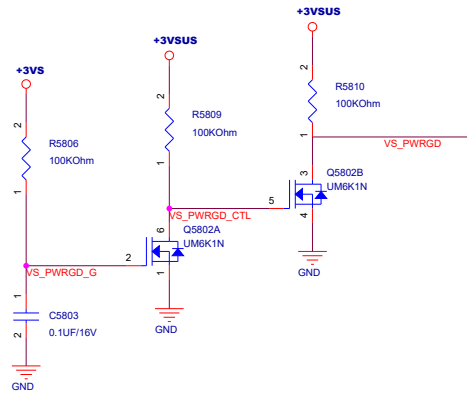
0.95/1.8/3/5vsus

DEEP S3

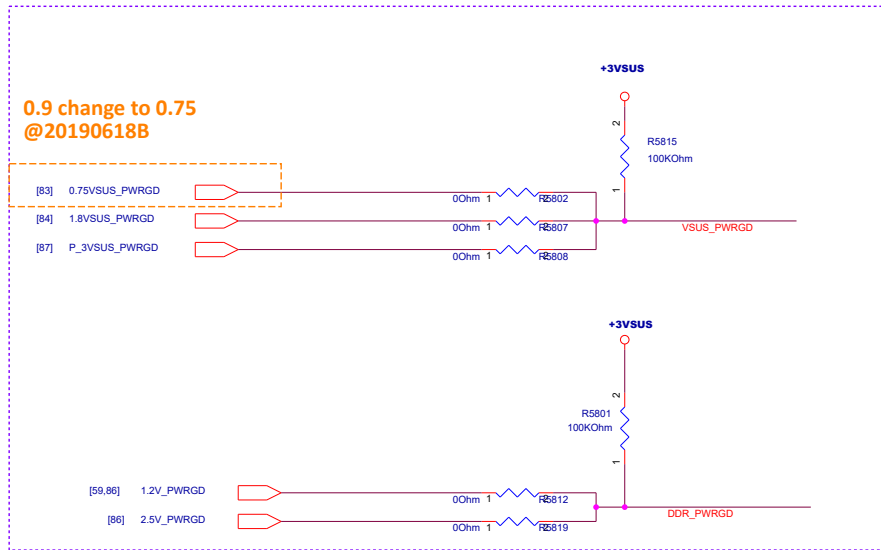


Delete P_APU_VDDSOC_PGA_10
@20190626A

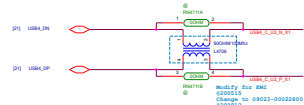
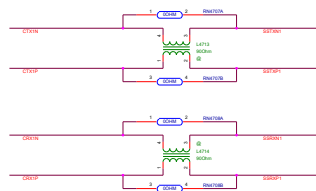
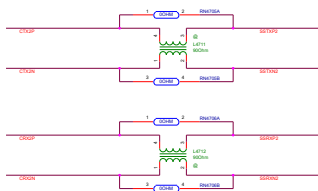
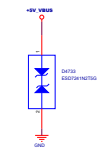
Remove AMD GPU PWRGD
@20181009K



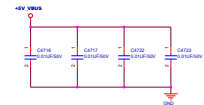
Power Good



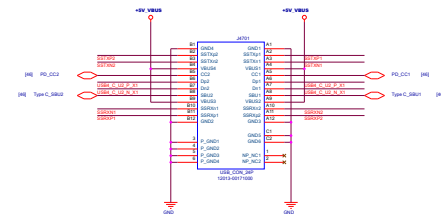
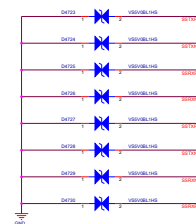
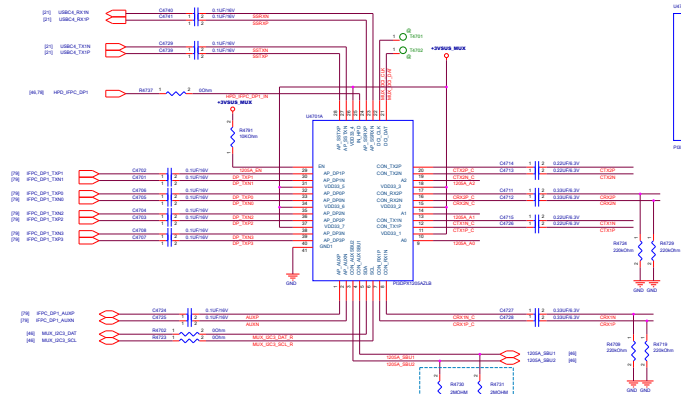
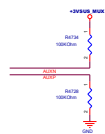
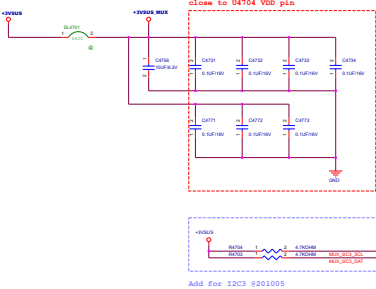
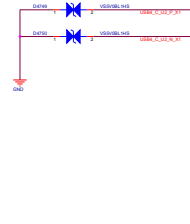
USB EMI-Protection



VBUS capacitor, Close to Connector for VBUS1 to VBUS4



TYPE-C Connector

USB3.0
ESD-ProtectionUSB2.0
ESD-Protection

Follow reference schematic



Address 0x56 with SPI ROM

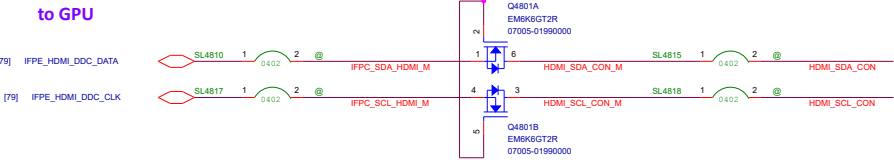
1.8.1 I2C Address	Register Bits						
	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1
Slave address (first byte is slave address)	1	0	1	0	A2	A1	A0

NOTE 8. PIN ASSIGNMENT (FRONT VIEW)

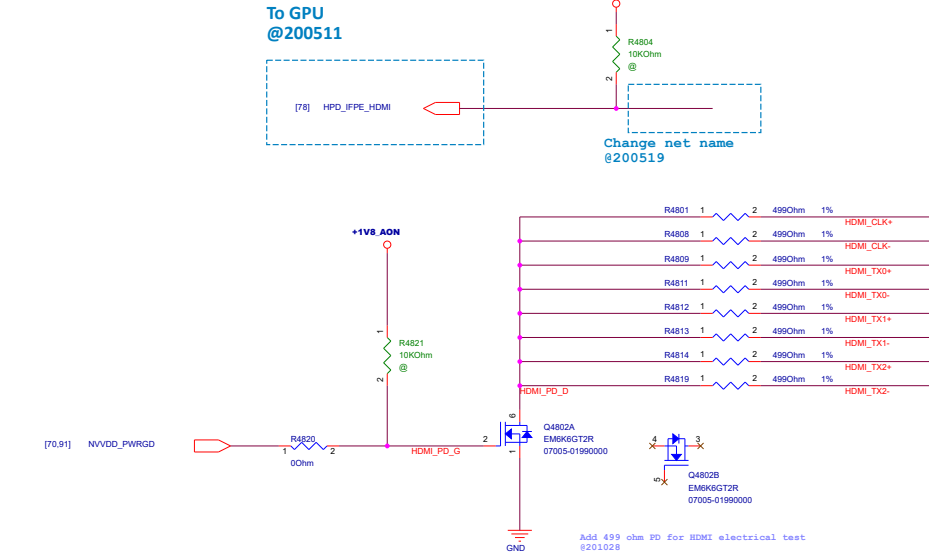
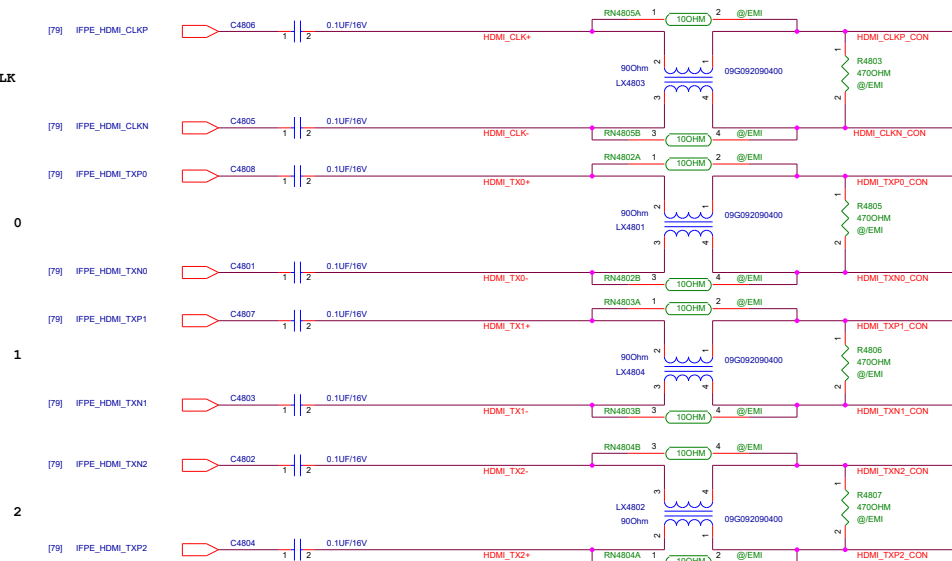
Pin No.	A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
	GND	RX1+	TX1-	V _{BUS}	CC1	D+	D-	SBU1	V _{BUS}	RX2-	TX2+	GND
Pin No.	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1
	GND	RX1+	TX1-	V _{BUS}	SBU2	D-	D+	CC2	V _{BUS}	TX2-	TX2+	GND

NOTE 9. LASER WELD POINTS MAY BE DISCOLORED.

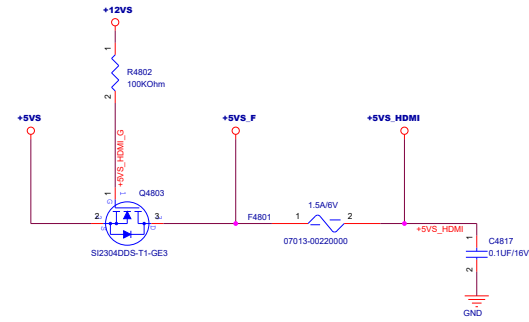
HDMI Active-Level Shift



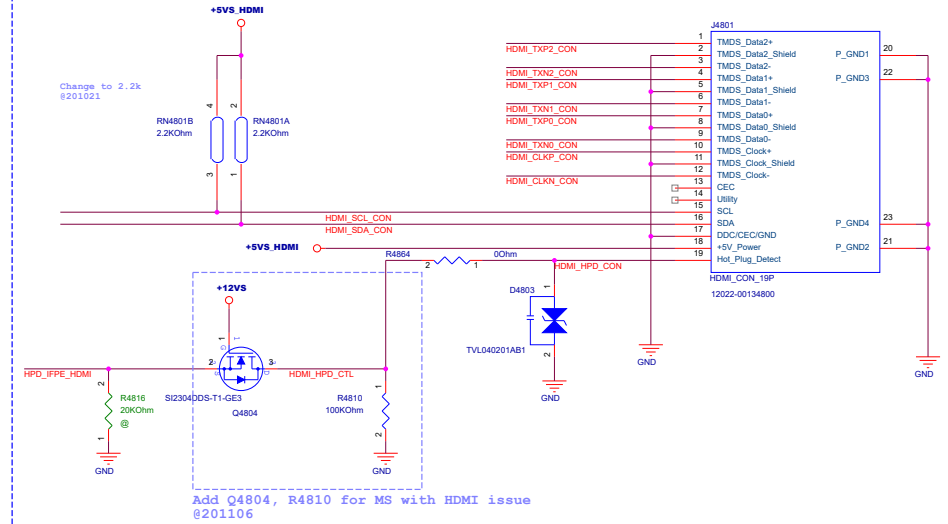
From GPU



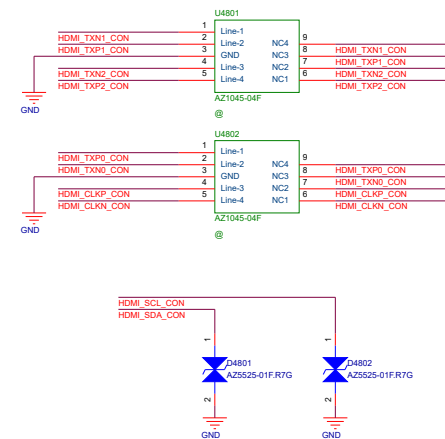
HDMI PWR_+5VS_HDMI



HDMI Conn.




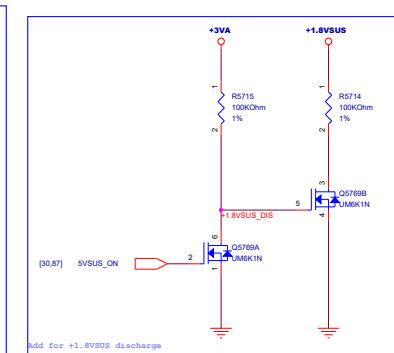
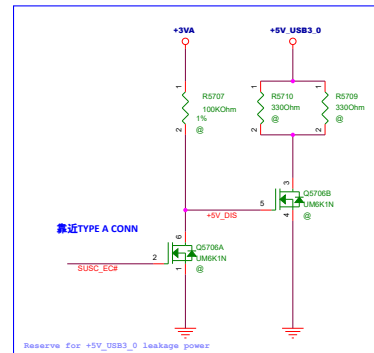
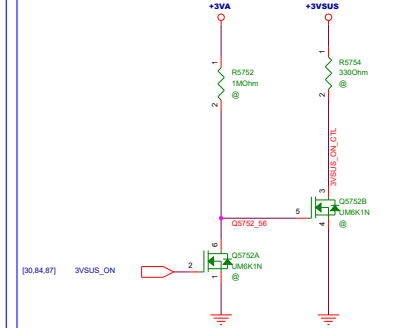
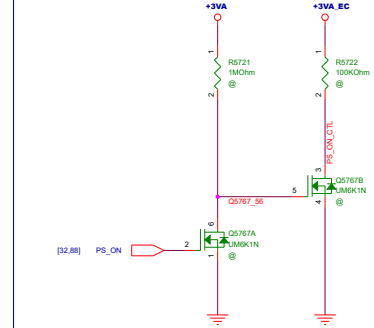
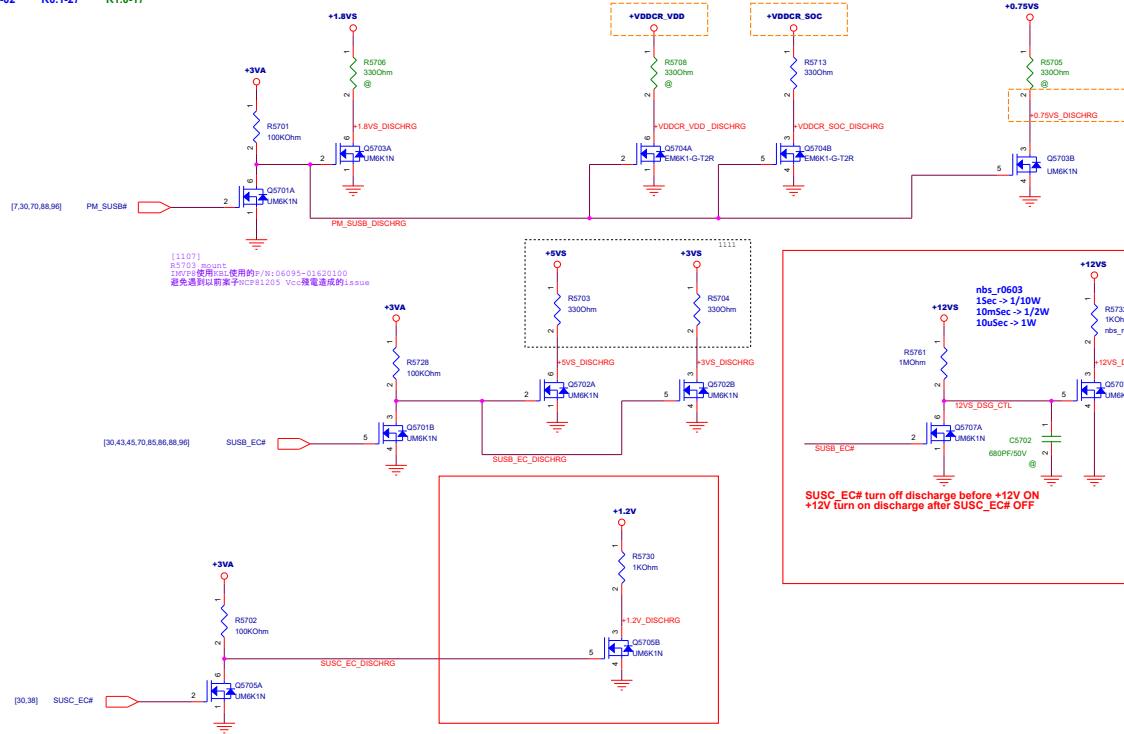
ESD Protect



Main Board

Title			
<Title>			
Size	Document Number		Rev
A	<Doc>		R1.0
Date:	Friday, November 06, 2020	Sheet	54 of 104

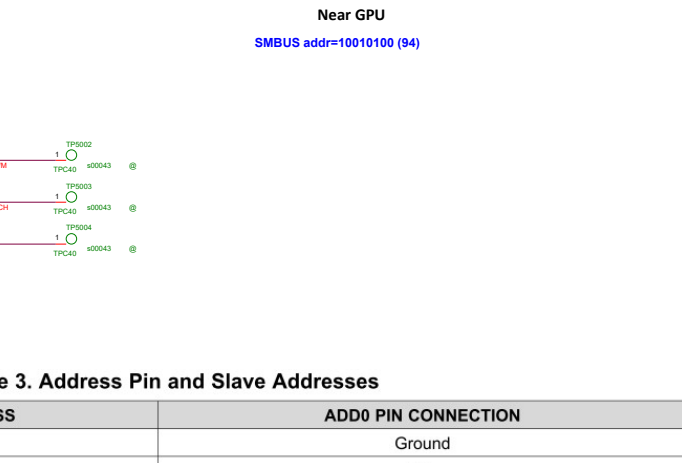
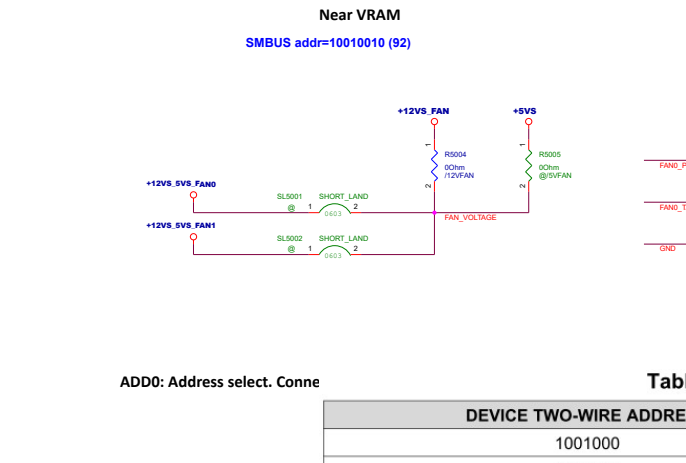
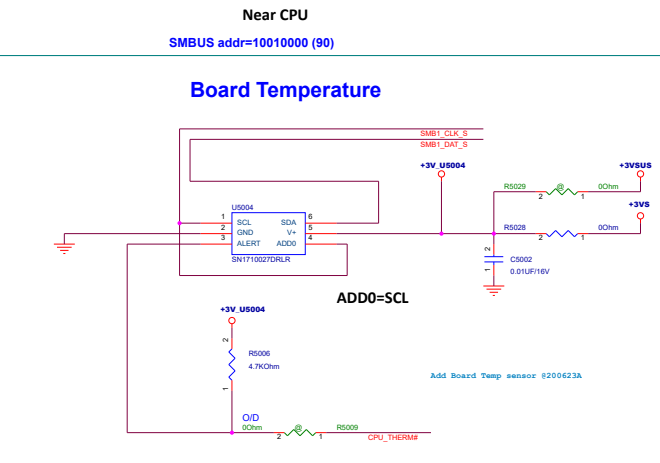
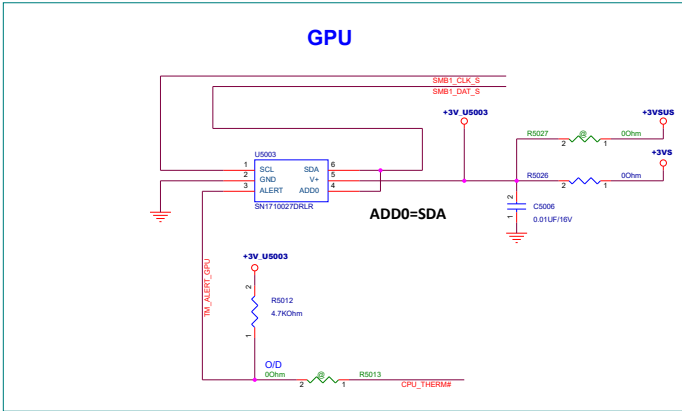
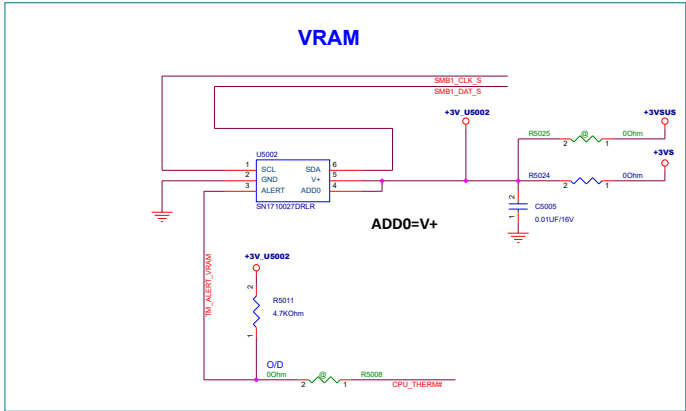
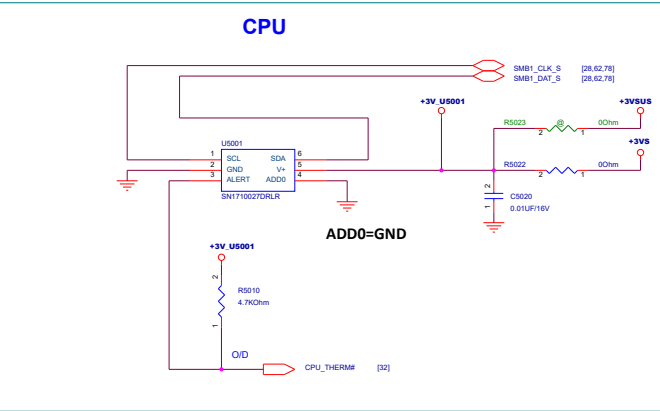
		Title :	
ASUSTeK COMPUTER		Engineer:	EE
Size	Project Name		Rev
A	GX502GX		R1.0
Date: Friday, November 06, 2020		Sheet 55 of 104	



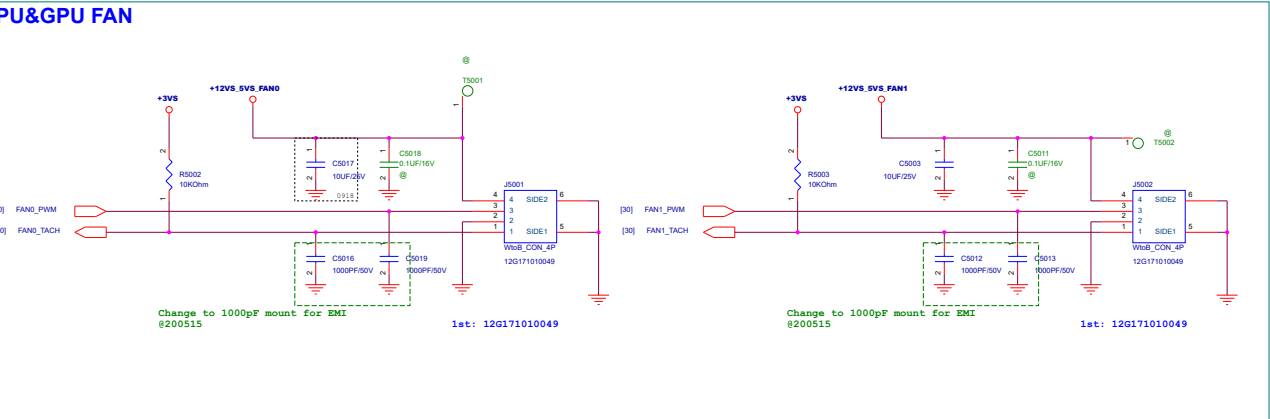
Thermal Sensor : SN170027


ALERT/SDA/SCL: Open-drain output; pullup resistor 5Kohm

Pin function Supply voltage.: 1.62 V to 3.6 V



DEVICE TWO-WIRE ADDRESS	ADD0 PIN CONNECTION
1001000	Ground
1001001	V+
1001010	SDA
1001011	SCL

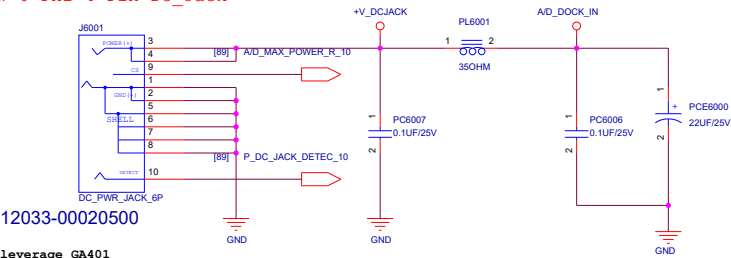


		Title : IO Con. to MB	
ASUSTeK COMPUTER		Engineer: EE	
Size A	Project Name GX502GX		Rev R1.0
Date: Friday, November 06, 2020		Sheet 66 of 104	

DC-IN Connector

DC Jack使用請詢用River_Hsu

New 6 Phi 4 Pin DC_Jack



12033-00020500

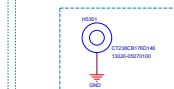
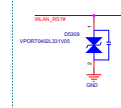
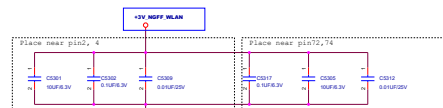
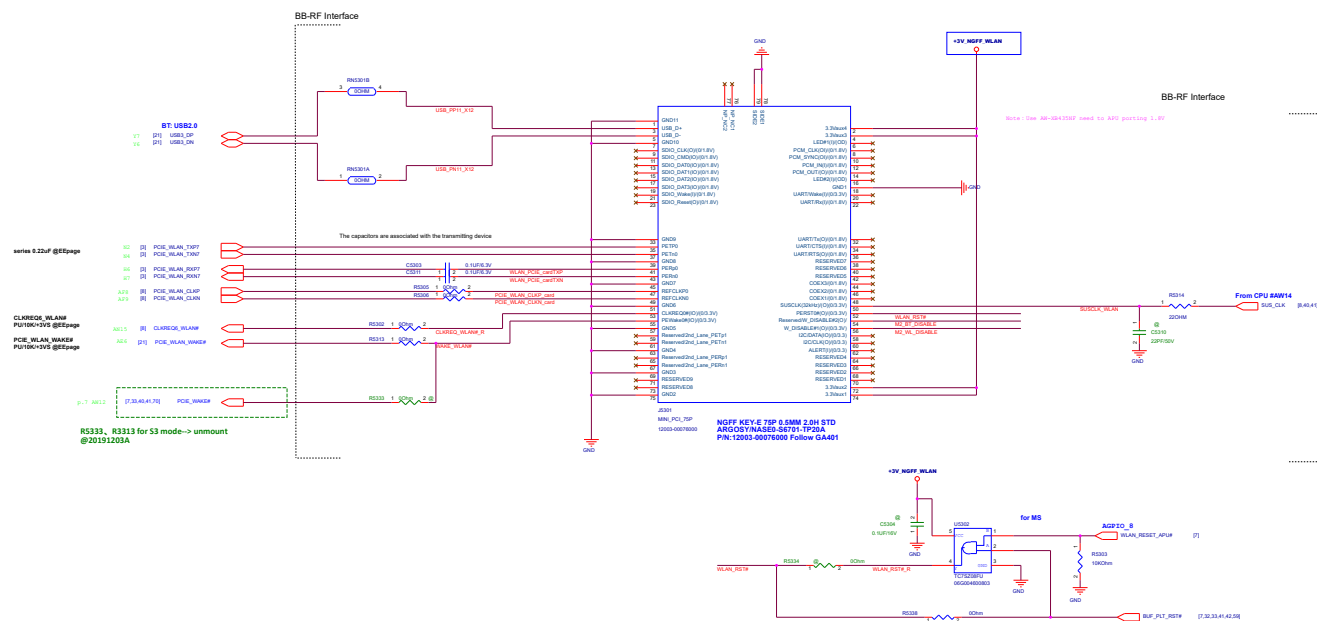
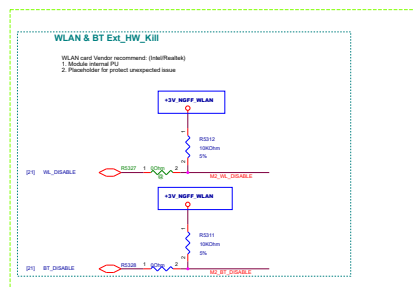
1evezage GA401

J6001	3.4CH	1.55CH
	12033-00020200	12033-00020300


Battery Connector



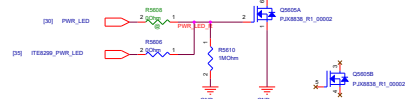
Note:Battery Connector 正確性與BAT1_IN_OC#是否預留!



Richard Blumenthal

		Title : BT_Blueetooth	
ASUSTeK COMPUTER		Engineer: EE	
Size C	Project Name GX502GX		Rev R1.0
Date: Friday, November 06, 2020		Sheet 61 of 104	

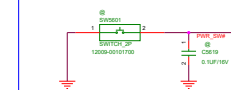
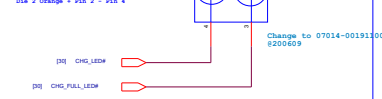
RWR LED



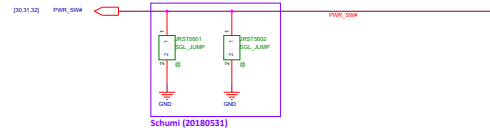
PCIE SSD IOPS



Charger LED

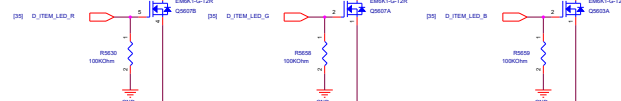


OS LED



D item- RGB LED

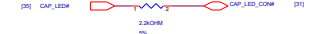
< D case I F D R >



< D case I FD I >



CAP LED





Title : I/O_Main board Conn.

ASUSTeK COMPUTER

Engineer: EE

Size

Project Name

Rev

A

GX502GX

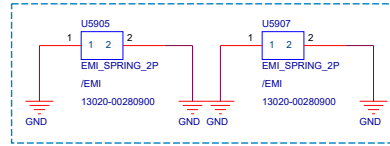
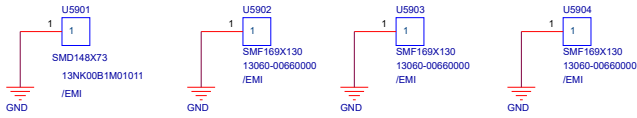
R1.0

Date: Friday, November 06, 2020

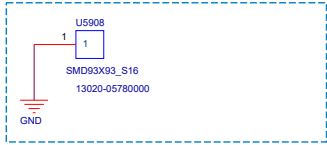
Sheet 69 of 104

Change to 13060-00660000 @200805

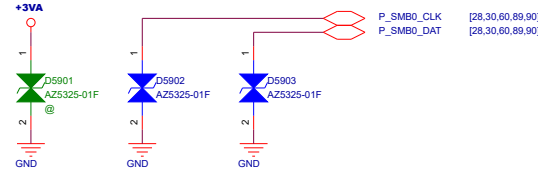
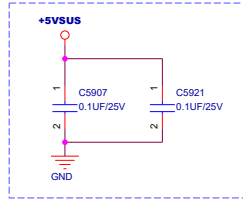
Change to 13020-00280900 @201012



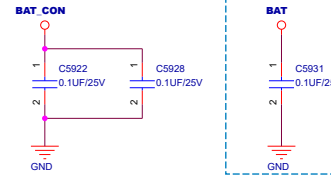
Add @200609



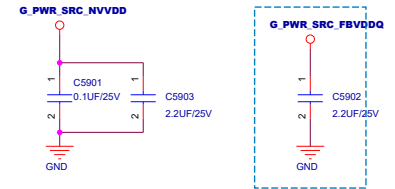
Change to +5VSUS @201005



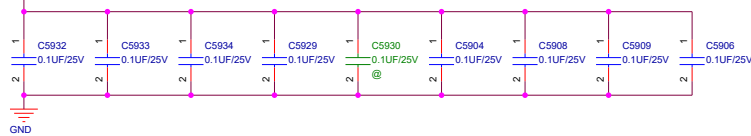
EMI request @2006308



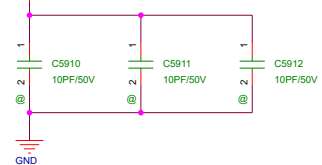
EMI request @2006308



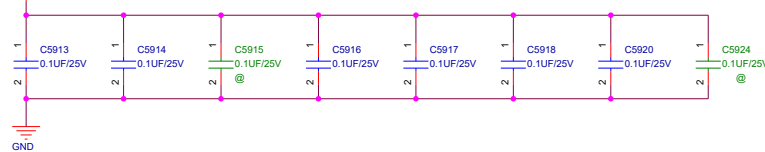
AC_BAT_SYS



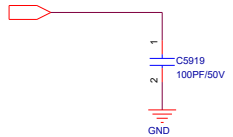
+NVVDD



AC_BAT_SYS



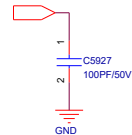
[58,86] 1.2V_PWRGD



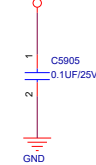
[30,58] ALL_SYSTEM_PWRGD



[7,32,33,41,42,53] BUF_PLT_RST#

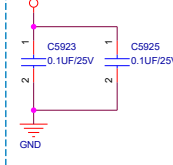


+1.8VSUS



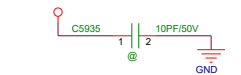
EMI request @200701

+3VS





EMI request @2006308

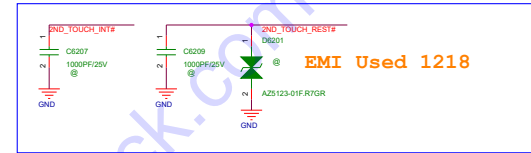
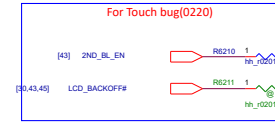
+5VS_PWR



<Core Design> 2017.05.02 EMI Reserve

		Title : ME_Screw Hole & Nut	
ASUSTeK COMPUTER		Engineer: EE	
Size A	Project Name GX502GX		Rev R1.0
Date: Friday, November 06, 2020		Sheet 67 of 104	

		Title : OTH_for test only	
ASUSTeK COMPUTER		Engineer: EE	
Size A	Project Name GX502GX		Rev R1.0
Date: Friday, November 06, 2020		Sheet 68 of 104	





Title : **NGFF SSD(MAXIM)**

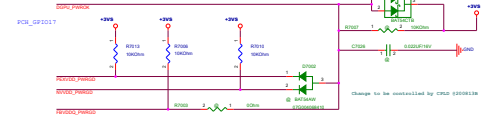
ASUSTeK COMPUTER

Engineer: **Wendell_Lo**

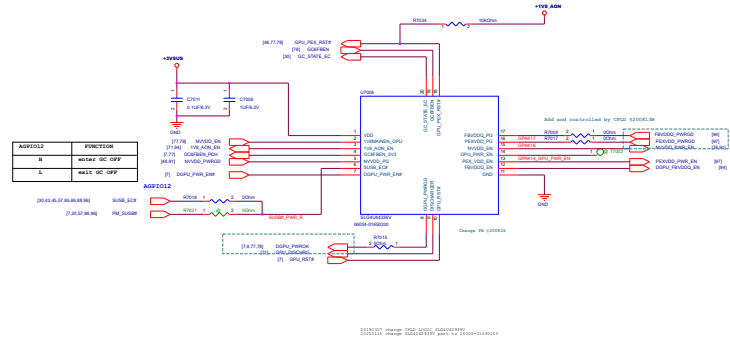
Size	Project Name
A	GL752VW

Rev
R1.0

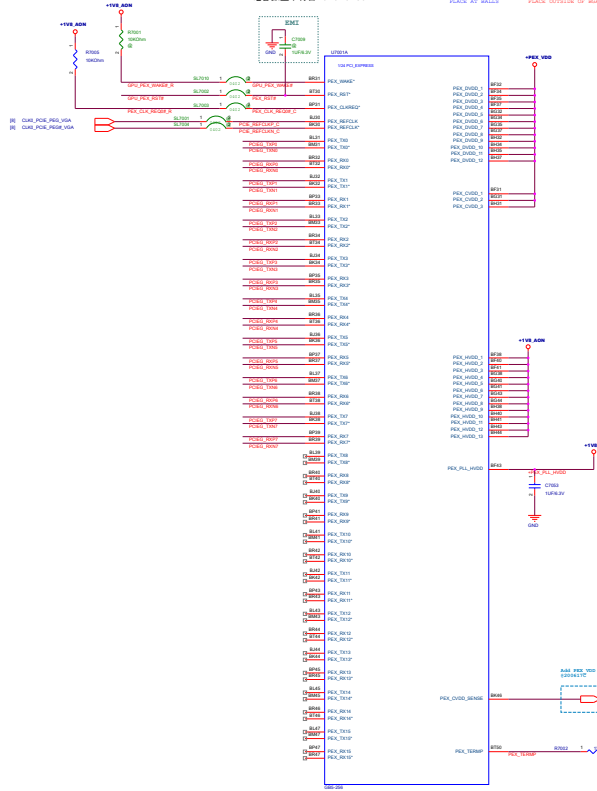
GPU POWER GOOD Signal



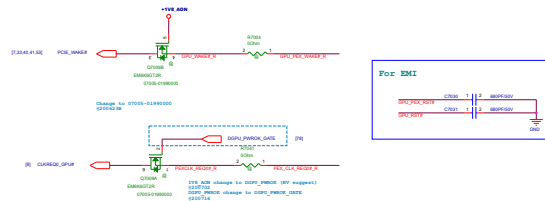
GPU POWER SEQUENCE CONTROL



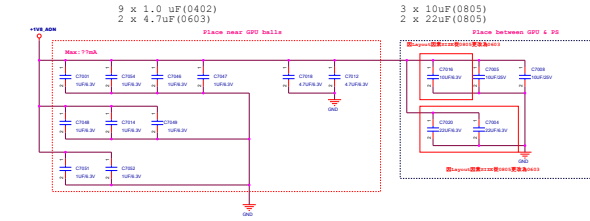
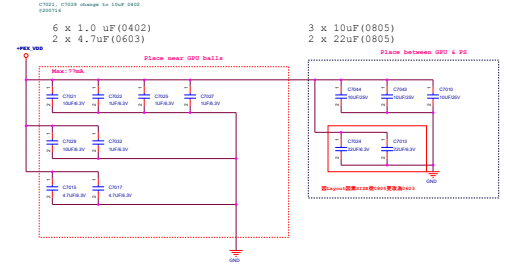
电容数量未符合Reference



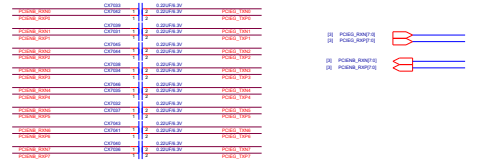
PLACE AT BALLS PLACE OUTSIDE OF BALL

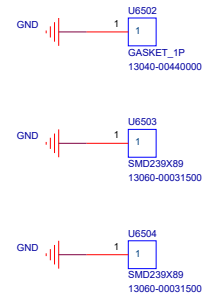
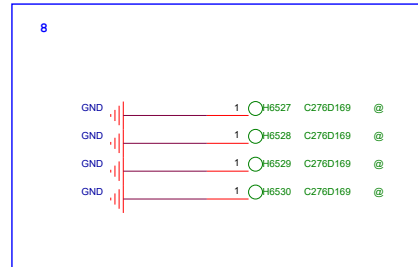
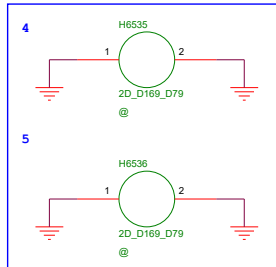
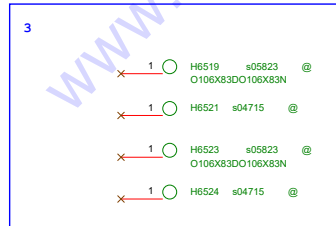
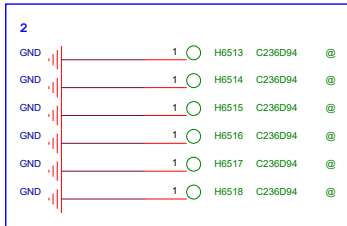
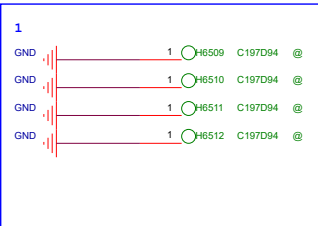
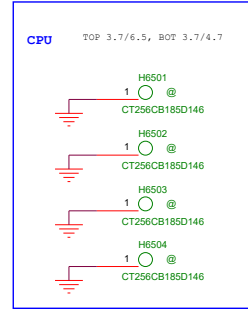
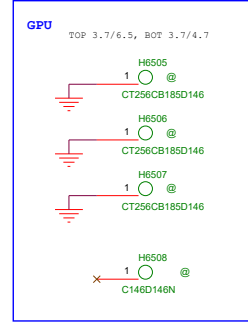
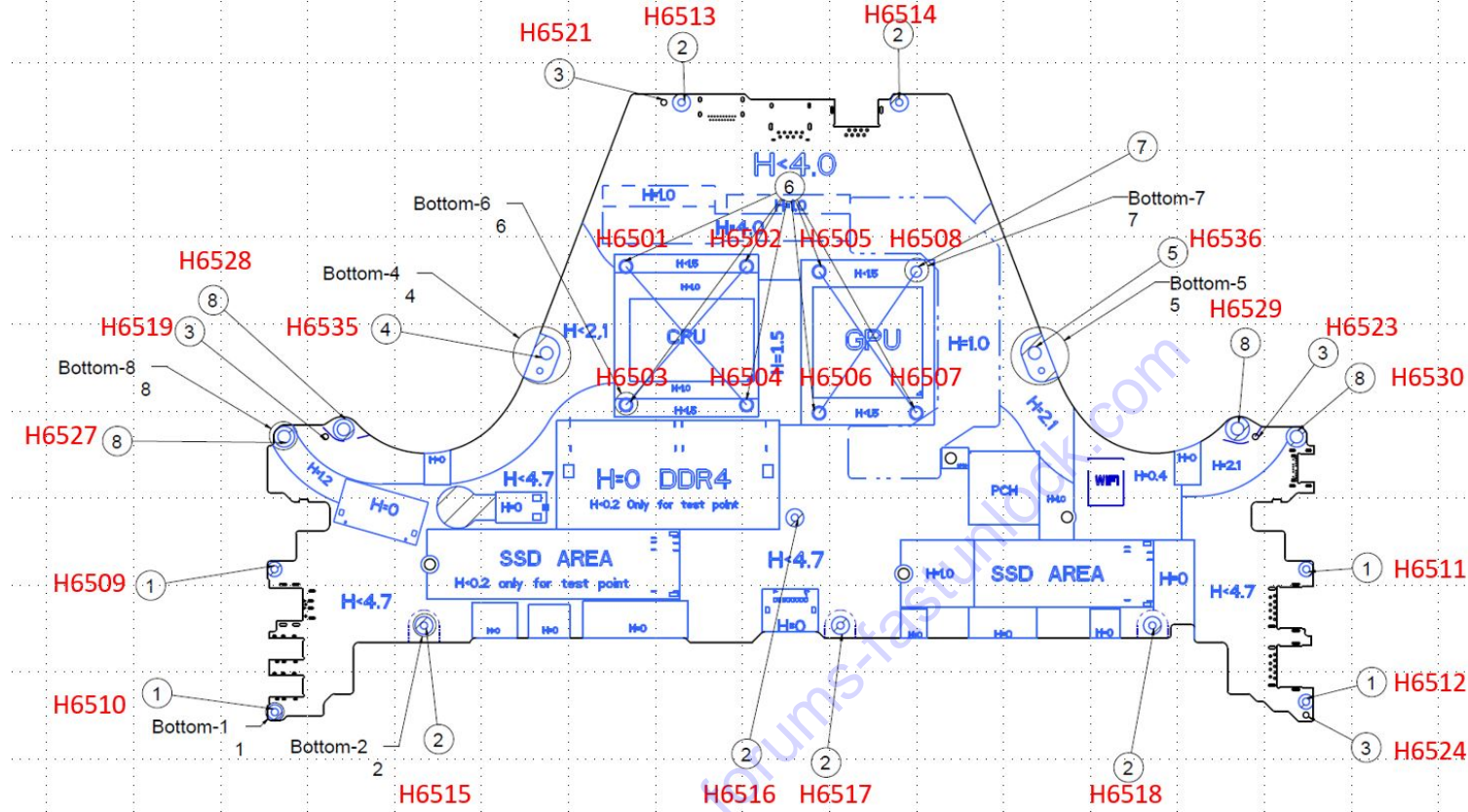


Main Board

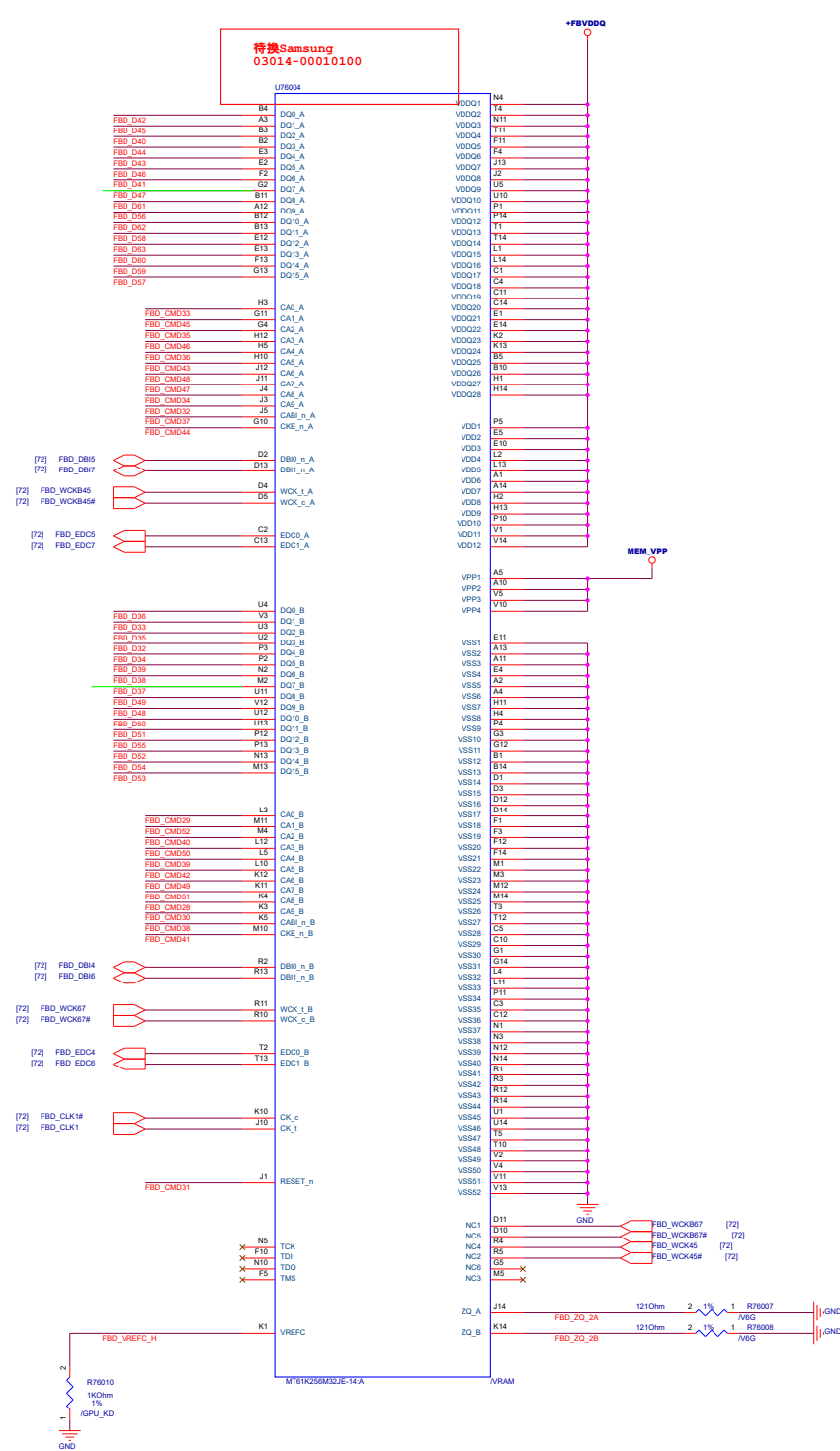


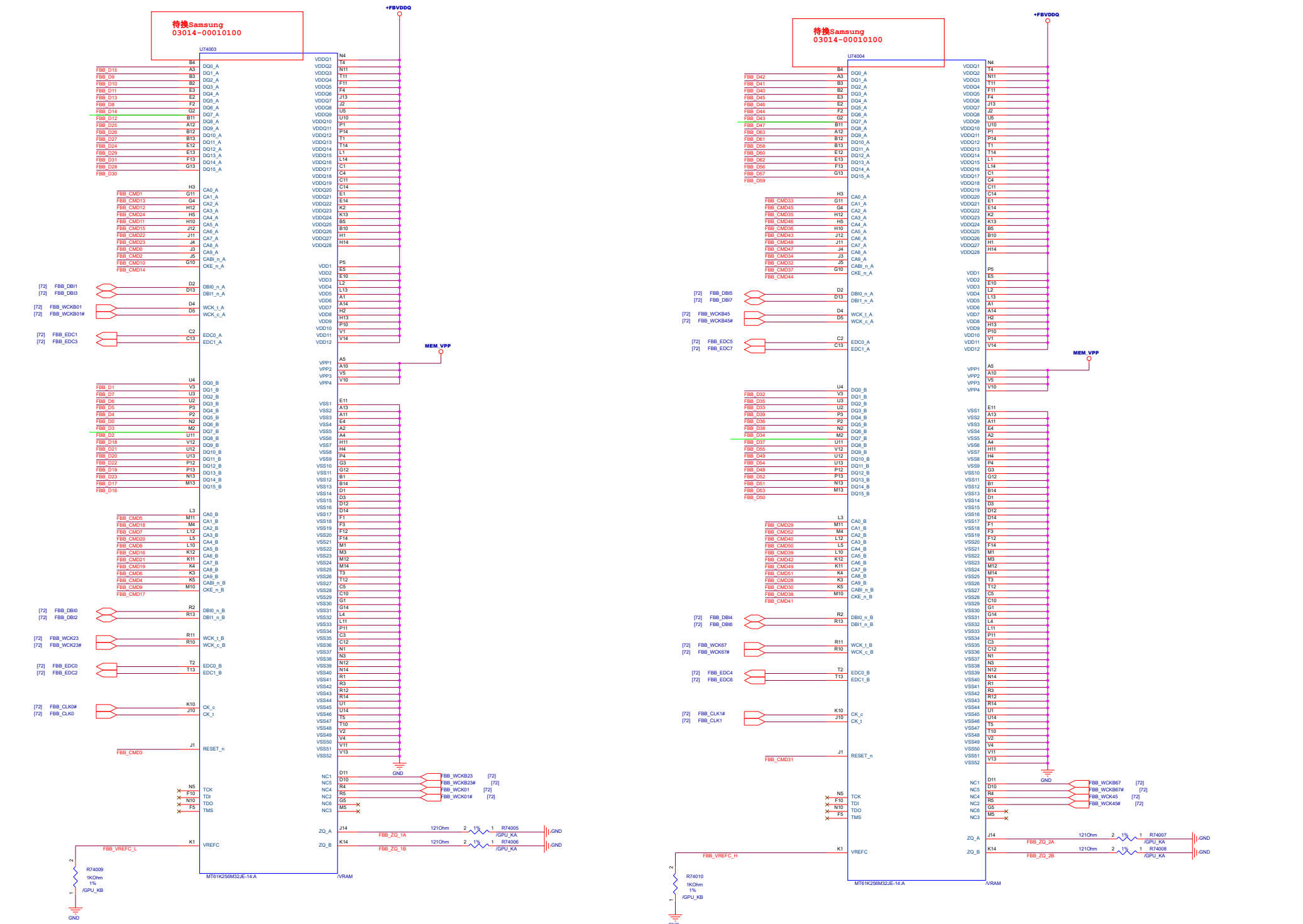
PCBS x8 TX Capacitors

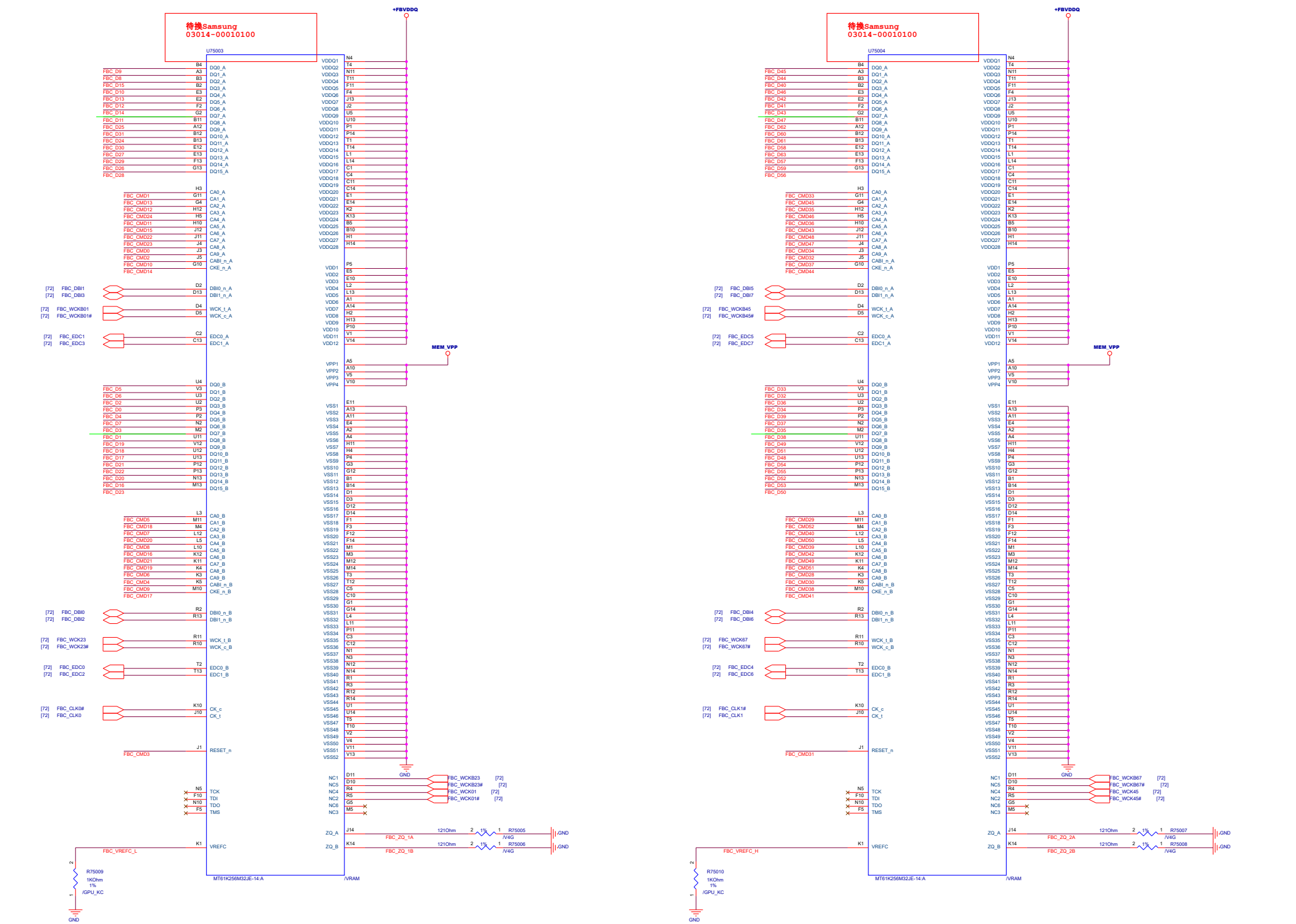




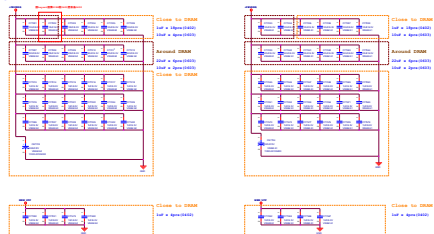
<Core Design>



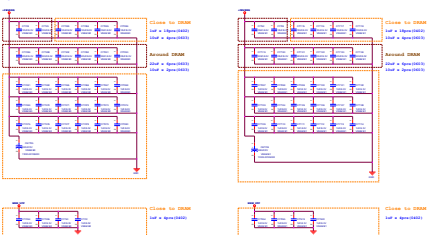




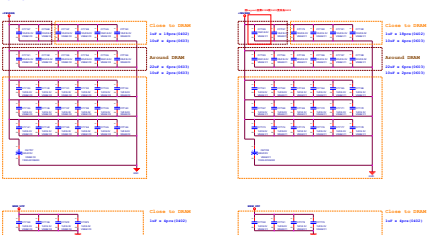
Channel A



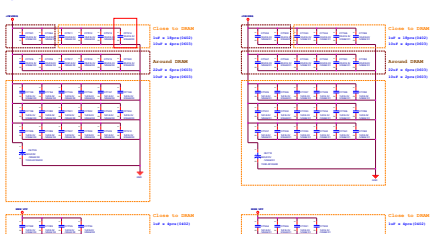
Channel B



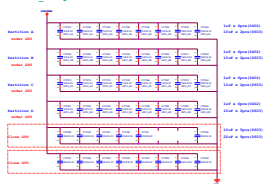
Channel C



Channel D



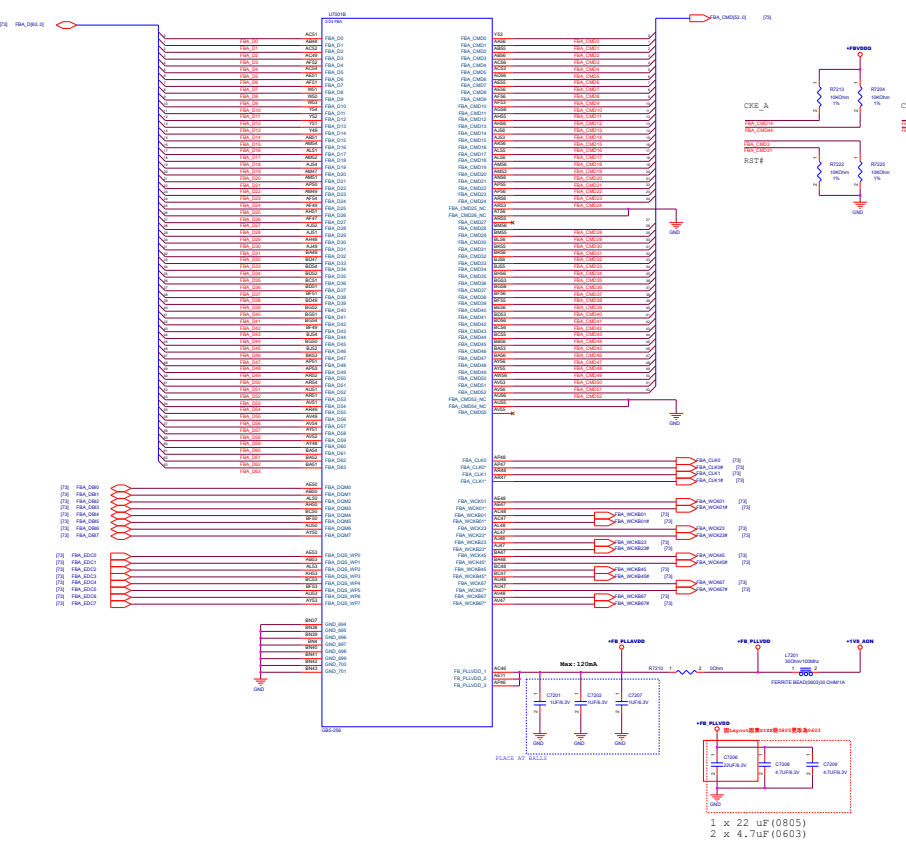
VLAN FW_FVSDQ

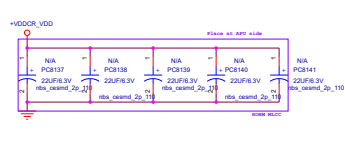
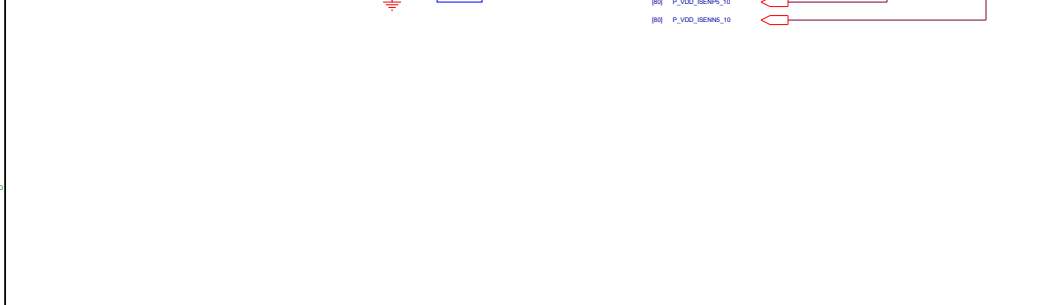
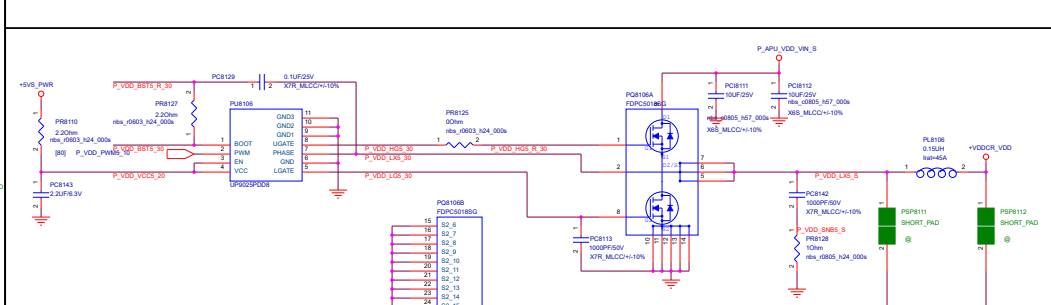
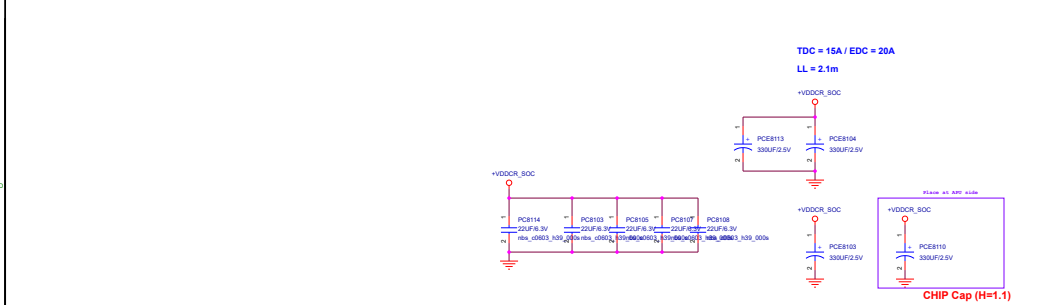
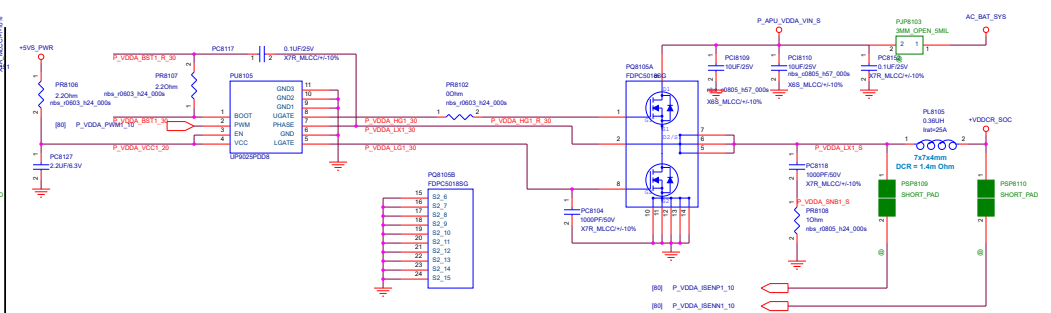


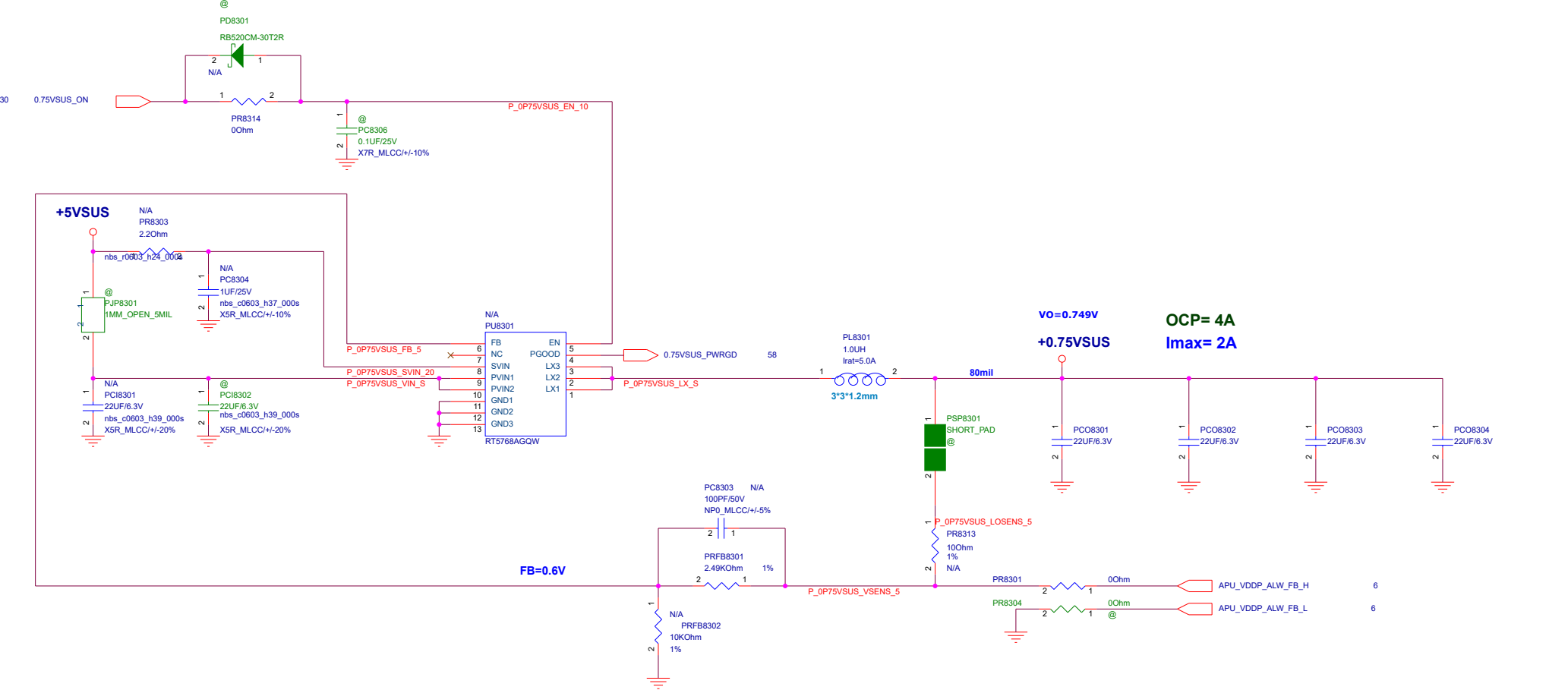
For power sequence measurement



MEMORY: GPU FB Partition A

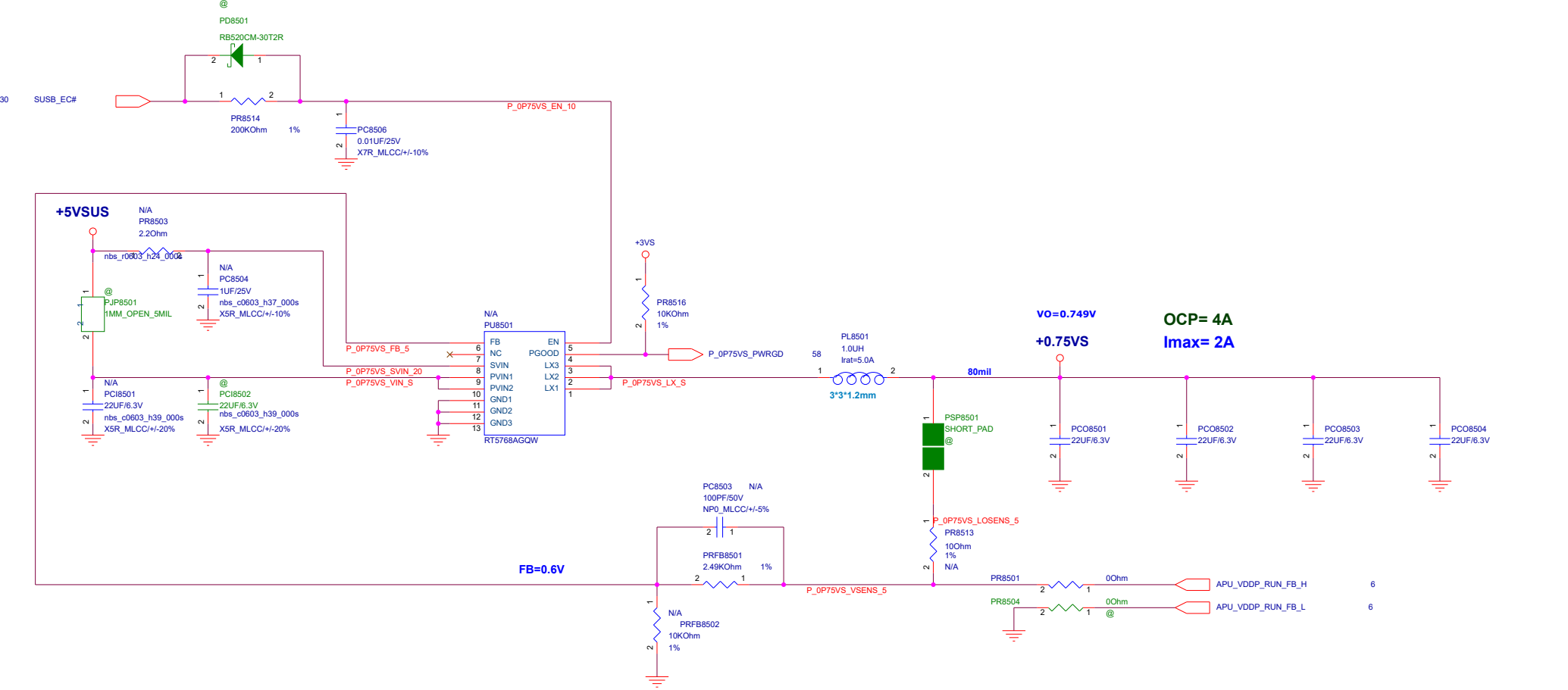






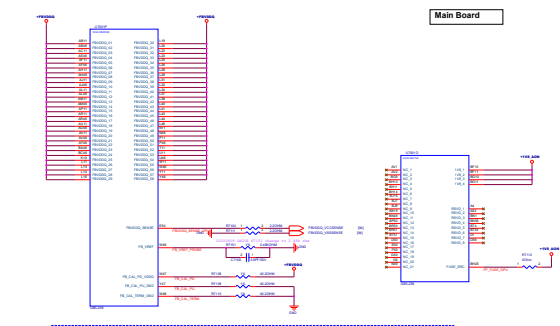
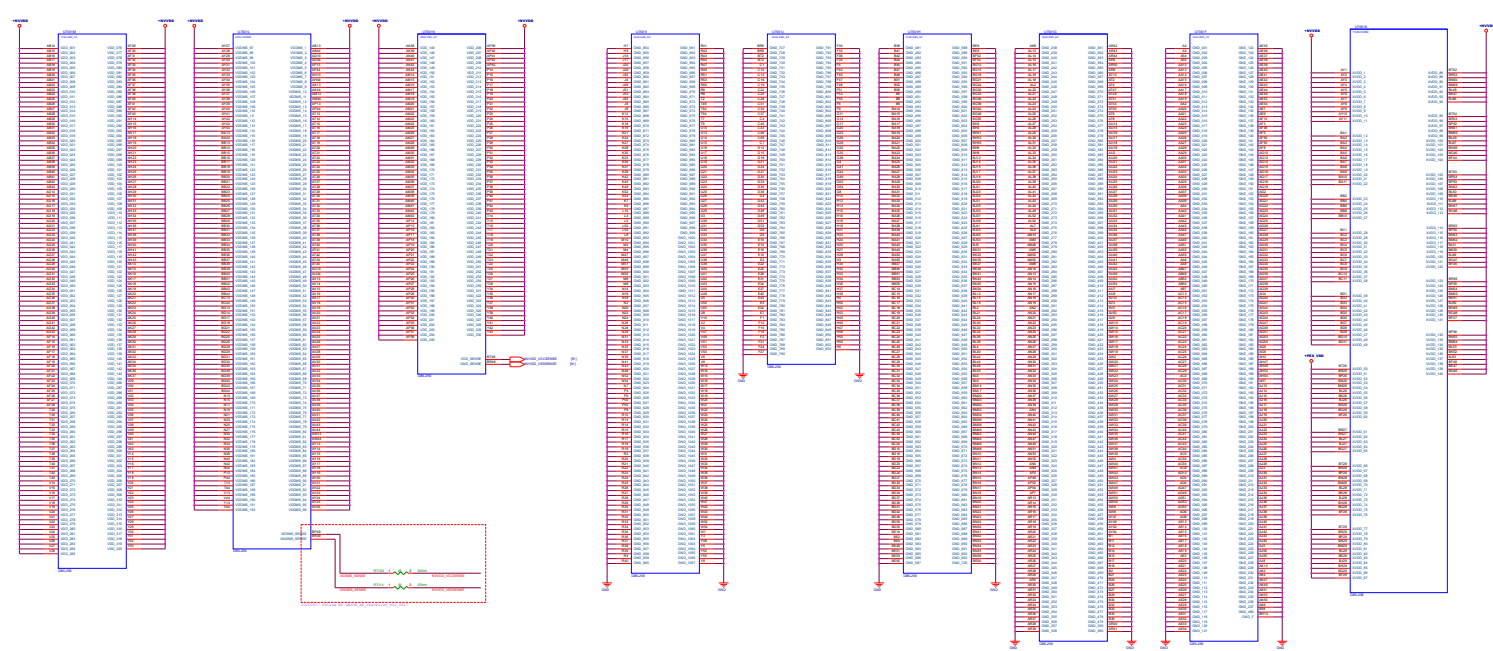
<Variant Name>

ASUS		Project Name	Rev
GA503QS			R1.0
Title : PW_+0.75VSUS			
Size	Dept.:	Engineer:	
A3	NB Power team	CS Lin	
Date:	Friday, November 06, 2020	Sheet	83 of 104

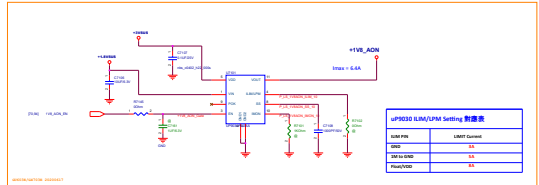


<Variant Name>

ASUS		Project Name	Rev
GA503QS			R1.0
Title : PW_+0.75VS			
Size	Dept.:	Engineer:	
A3	NB Power team	CS Lin	
Date: Friday, November 06, 2020		Sheet	85 of 104

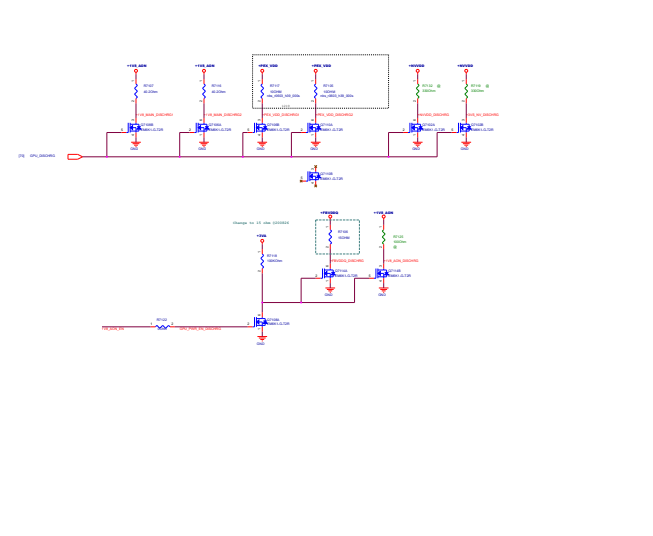


1V8 Power Control

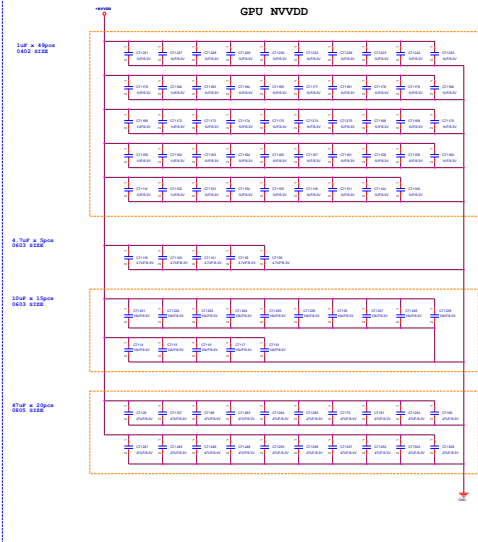


AP5000 SLM/LPM Setting 調整表	
SLM PPM	LIMIT Current
SLM	12
SLM VDD	12
SLM VDD	12

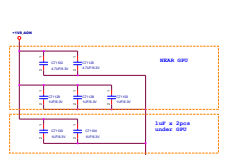
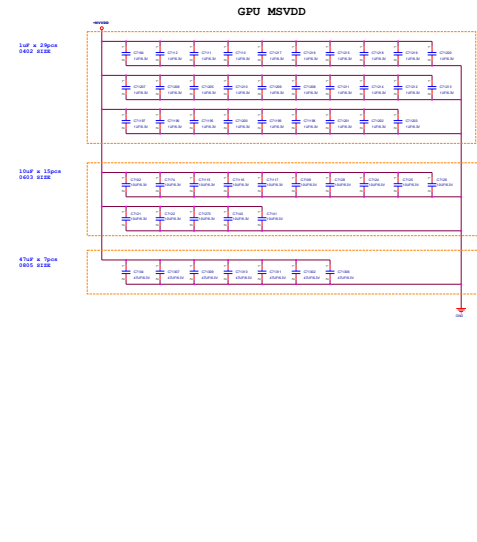
Discharge

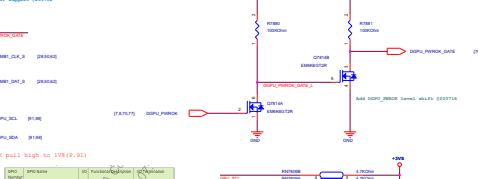
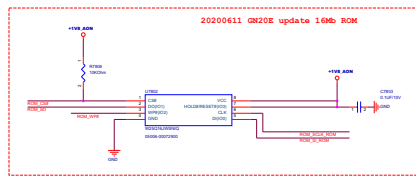


GPU NVVDD

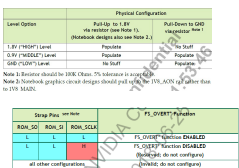
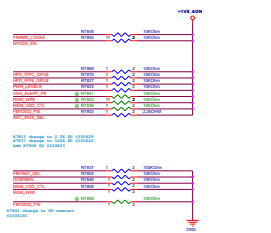
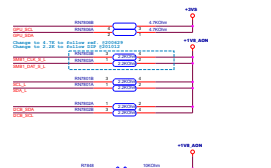


GPU MSVDD





The schematic diagram illustrates a 1-bit DAC circuit. It features a PMOS transistor (M1) and an NMOS transistor (M2) with gates connected to a common input 'in'. The source of M1 is connected to a PMOS load (M3) and the source of M2 is connected to an NMOS load (M4). The drains of M1 and M2 are connected to a common output node 'out'. The output buffer section includes a PMOS transistor (M5) and an NMOS transistor (M6) with gates connected to 'out' and 'in' respectively. The source of M5 is connected to a PMOS load (M7) and the source of M6 is connected to an NMOS load (M8). The drains of M5 and M6 are connected to a common output node 'out2'. The feedback path is connected from 'out2' back to 'in' through a feedback resistor 'Rf'.



RFID Invert

DP Type-C Port 1 (right)

(a) DP Type-C Port 1 (right) configuration 1. The circuit includes a 5V regulator, a 10k pull-up, a 100nF capacitor, and a 100ohm resistor. The output is labeled DP Type-C Port 1 (right).

(b) DP Type-C Port 1 (right) configuration 2. The circuit includes a 5V regulator, a 10k pull-up, a 100nF capacitor, and a 100ohm resistor. The output is labeled DP Type-C Port 1 (right).

(c) DP Type-C Port 1 (right) configuration 3. The circuit includes a 5V regulator, a 10k pull-up, a 100nF capacitor, and a 100ohm resistor. The output is labeled DP Type-C Port 1 (right).

(d) DP Type-C Port 1 (right) configuration 4. The circuit includes a 5V regulator, a 10k pull-up, a 100nF capacitor, and a 100ohm resistor. The output is labeled DP Type-C Port 1 (right).

Memory Density	Aligned Memory Configuration	FVWQD	Vendor	Manufacturer Part Number	Die Revision	Storage	Memory Speed	Data Code	Qual. Plan	Status
16 GB	2C8x256MB	1.5V	Samsung	K4M7208H-EC14	A-0	64	1.5 GBps	2007	OK	Production candidate
		1.2V	Hyundai	TH0	300	64	1.5 GBps	2007	OK	Production candidate
		1.2V	Hyundai	TH0	300	64	1.5 GBps	2007	OK	Production candidate
8 GB	2C8x256MB	1.5V	Samsung	K4M7208H-EC14	A-0	64	1.5 GBps	2007	OK	Production candidate
		1.2V	Hyundai	H5G08080AR-EC	A-0	64	1.5 GBps	N/A	OK	Production candidate
		1.2V	Hyundai	TH0	A-0	64	1.5 GBps	10027	OK	Production candidate

Assorted Configuration Straps:-

- 1. SMB, AIT, ADDR Enable: "0" signal (PI setting) (CS address add), "1" (bad PI) setting (CS address add), used when second SPI.
- 2. DEVID_SEL: 0-sync function-->"0"normal GPU ID, "1" support 0-sync GPU ID.
- 3. PCIE_CFG: PCIE Swing-->"0" PCIE Swing default, "1" PCIE swing reduce.
- 4. VGA_DEVICE: Graphics circuit-->"0",MS-Hybrid, "1" Discrete.

```
1 SMB_ALT_AIDR Enable // @api01 setting 0=disabled, 1= enabled @api02 setting 0=disabled, 1= enabled @api03
```

```
2 DEV_ID_SEL 0-sys function = "Normal GPU ID," 1-support 0-sys GPU ID-
```

```
3 PCI_CFG_OG being -1=PCI being default, 1=PCI being reduce-
```

```
6 VGA_DEVICE {graphics circuit = "C8M-Hybrid," 0-Discrete-
```

```
1SMB_ALT_AIDR ENABLE
```

```
0SMB_ALT_AIDR DISABLE
```

```
1DEV_ID_SEL REBRAND
```

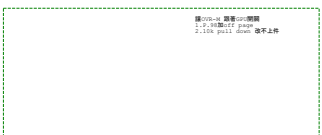
```
0DEV_ID_SEL ORIGINAL
```

```
1PCIE_CFG LOW POWER
```

```
0PCIE_CFG HIGH POWER
```

```
1VGA_DEVICE ENABLE
```

```
0VGA_DEVICE DISABLE
```

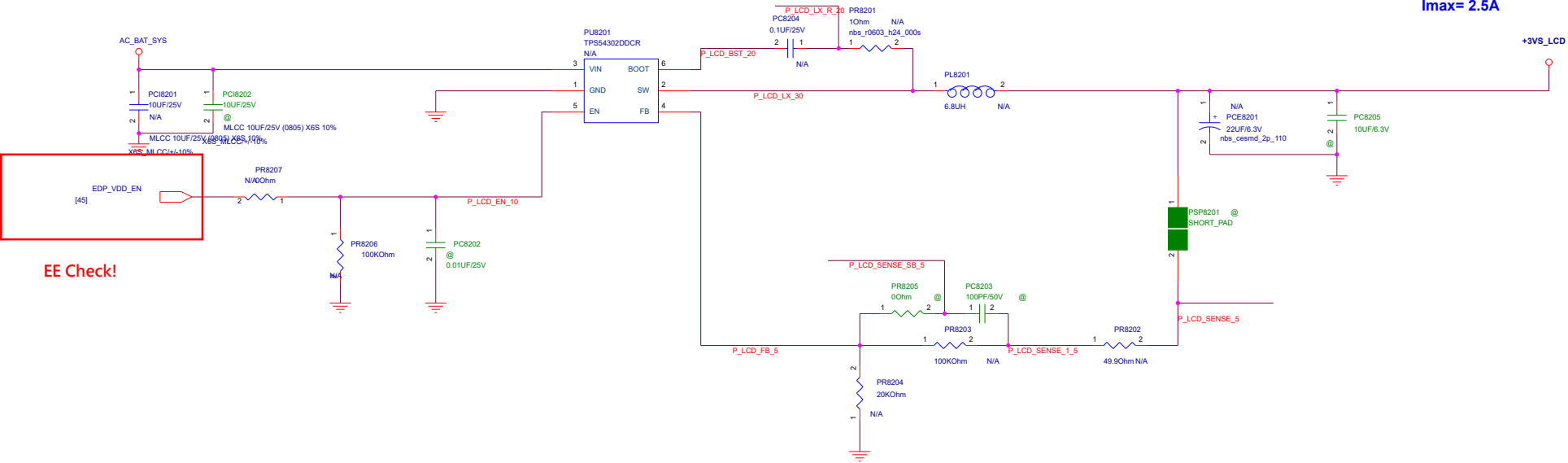


```
NVIDIA GCS 2.0 follow DG-07290-001_v01
GPU_GPIO 5--> FRAME_LOCK# (Input, Open Drain)
High-->driver display_Low Normal
```



+3VS_LCD

$I_{max} = 2.5A$



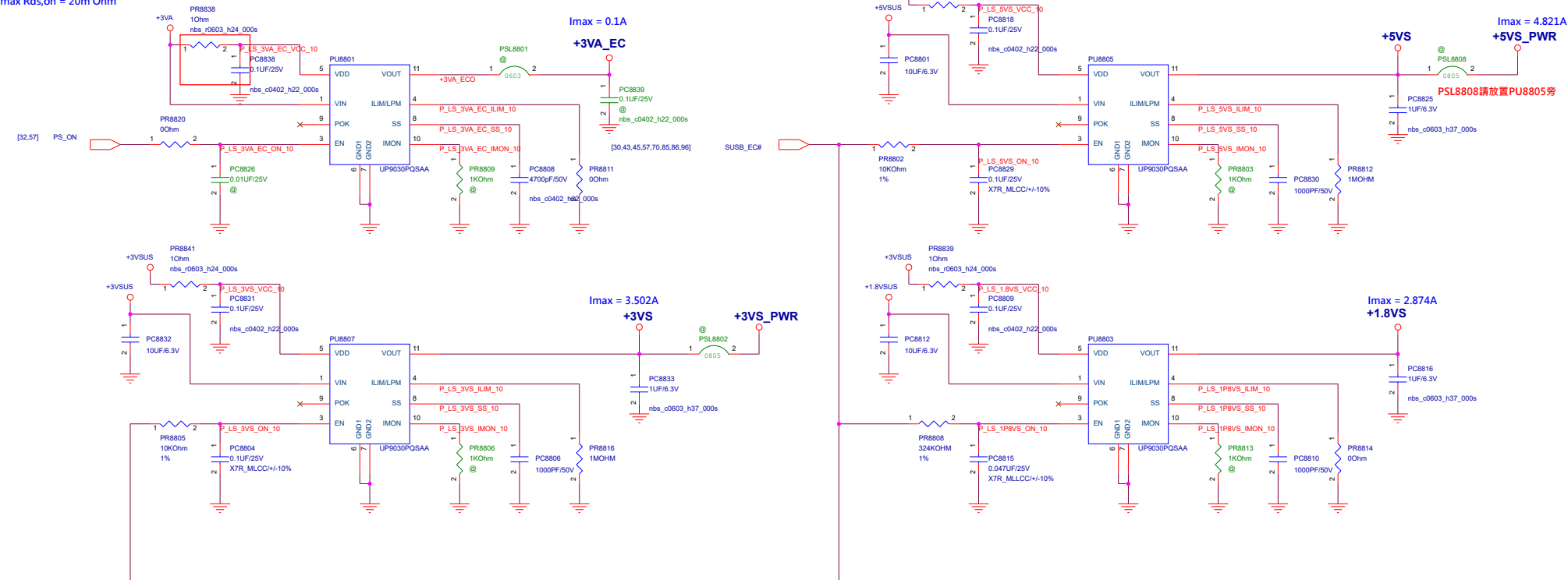
EE Check!

Title <Title>			
Size A3	Document Number <Doc>		Rev <RevCode>
Date:	Friday, November 06, 2020	Sheet	82 of 104

uP9030 ILIM/LPM Setting 對應表		
ILIM PIN	LPM	LIMIT Current
GND	Off	3A
1M to GND	Off	5A
Float/VDD	On	8A

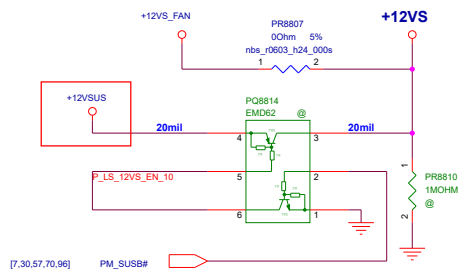
Conti = 6A
Imax Rds,on = 20m Ohm

PR8838 & PC8833 close VDD PIN



+12VS 的 Vin 對應 BOM 表

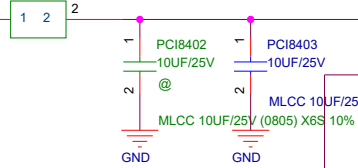
	+12VS_FAN	+12VSUS
PR8807	N/A	@
PR8810	@	N/A
PQ8814	@	N/A



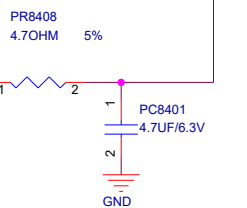
+1.8VSUS [For PCH]

AC_BAT_SYS

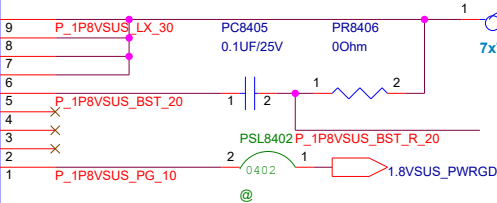
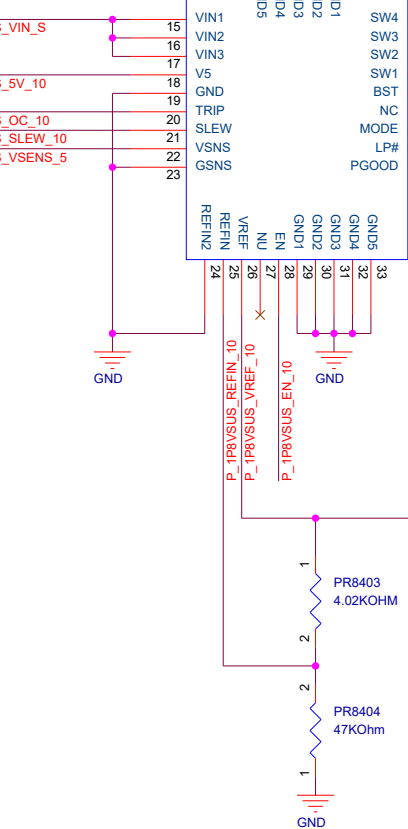
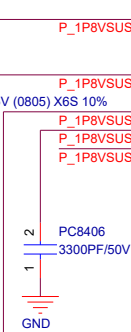
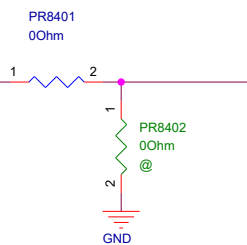
PJP8401
1MM_SHORT_PIN
@



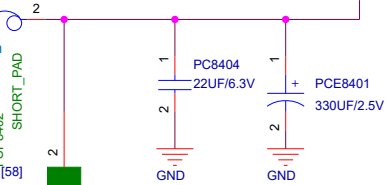
+5VSUS



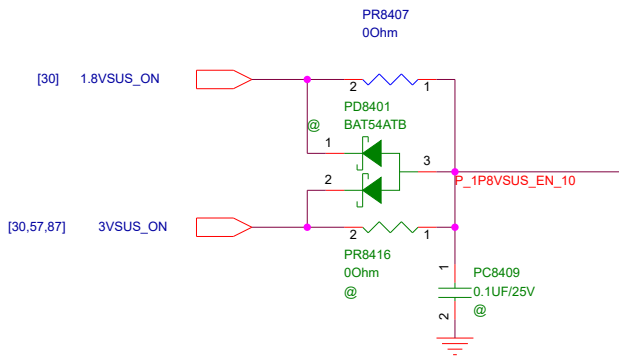
+5VSUS



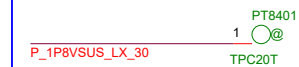
PL8401
1.0UH
N/A
Irat=15A



I_{max} = 8.3A
OCP = 12A
+1.8VSUS



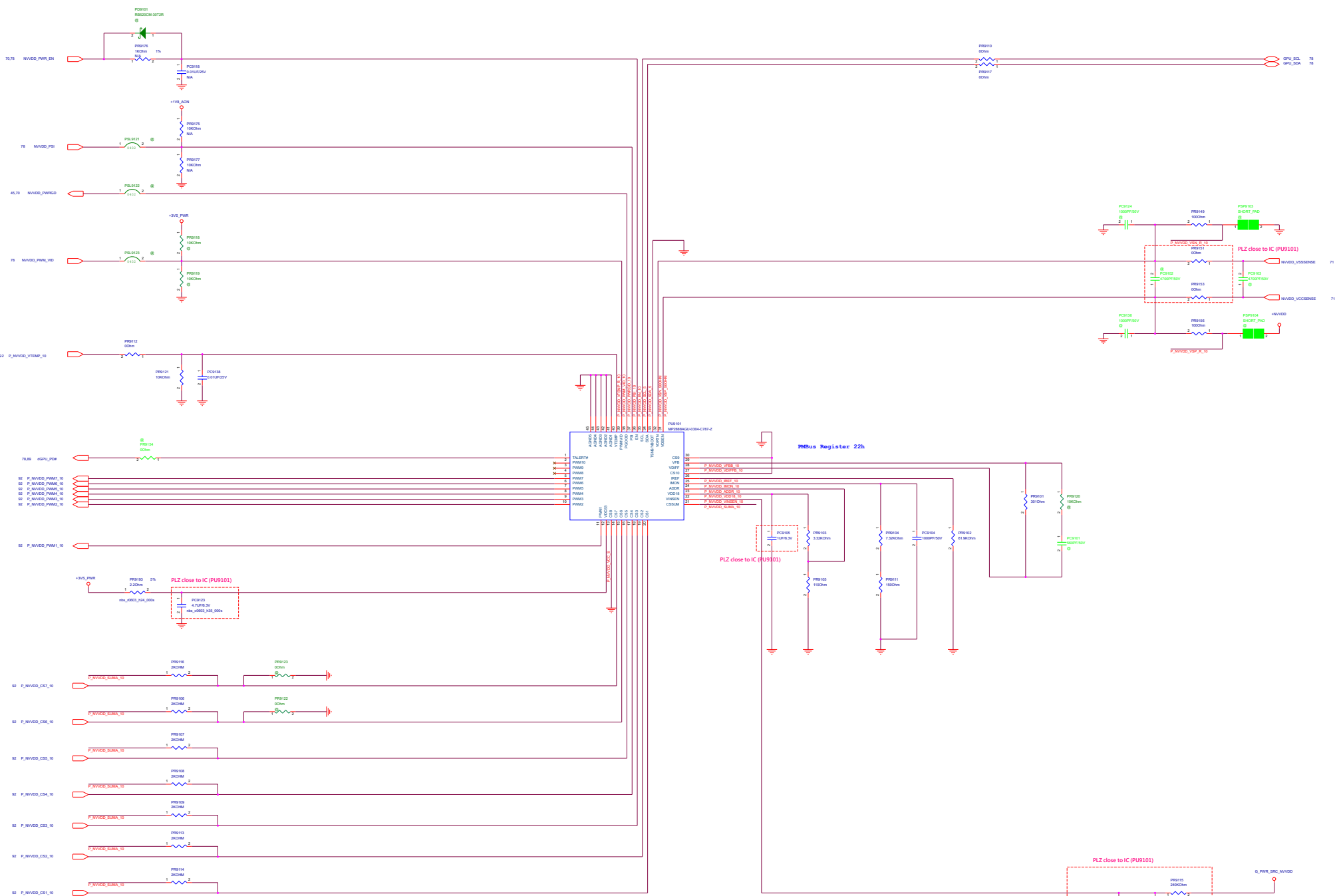
PT840* 請放置 PU8401旁;並請放置Trace 上!



<Variant Name>

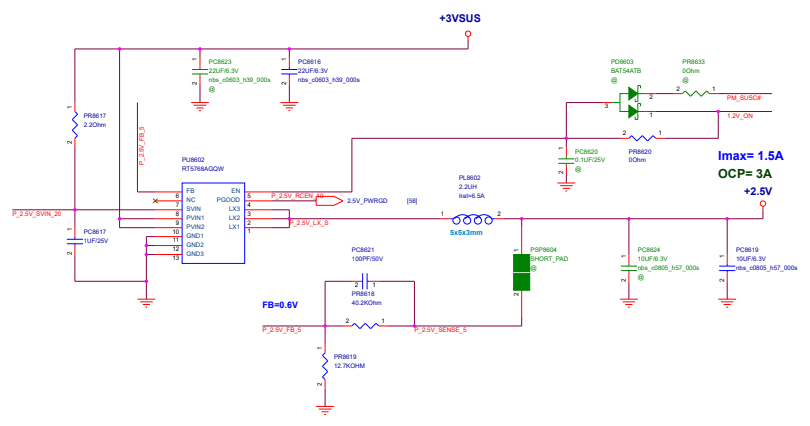
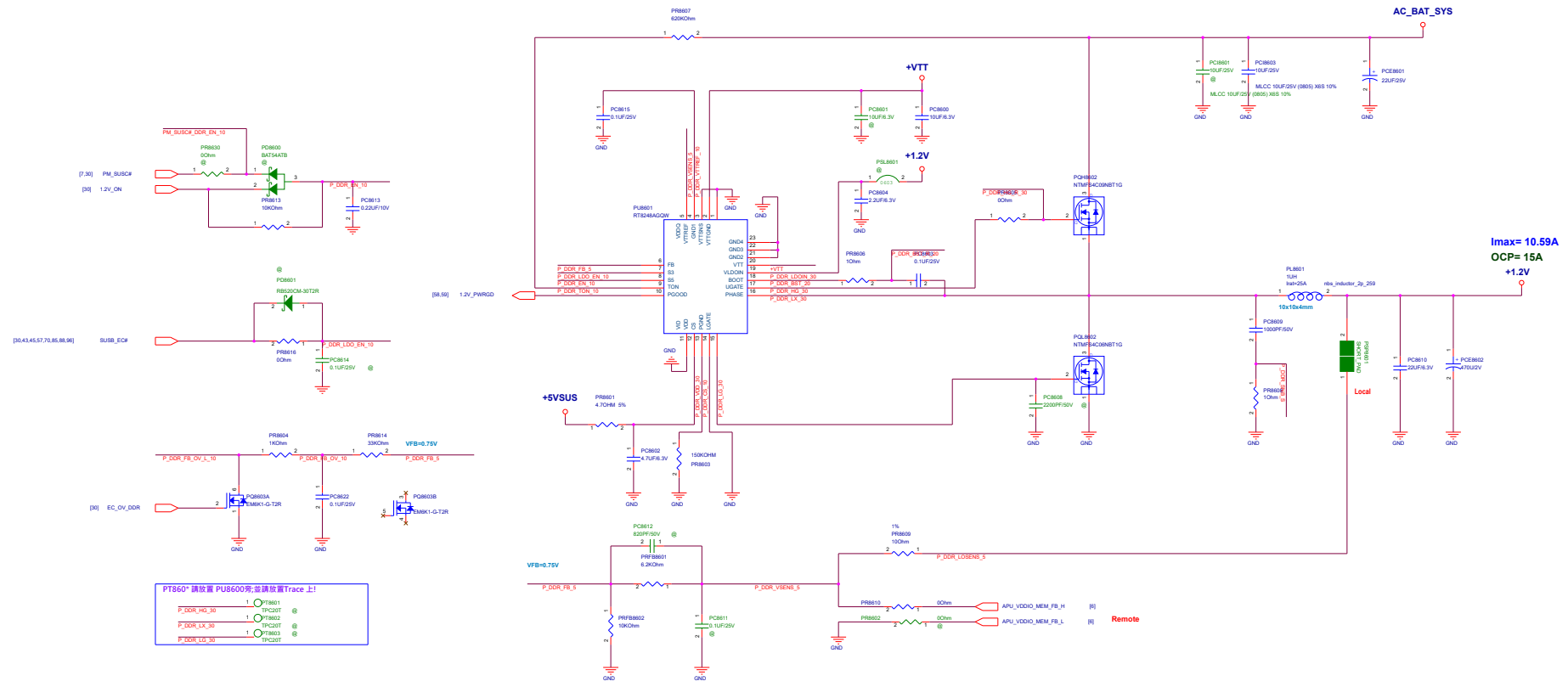
Project Name		Rev
ASUS Project Name		R1.0
Title : PW_+1.8VSUS		
Size A4	Dept.: NB Power team	Engineer: Power RD
Date: Friday, November 06, 2020	Sheet 84	of 104

+NVVDD [For DGPU]



< SW Auto-Phase setting > TBD
 PWM2 : APL Hys = 16A
 PWM3 : VAPL1 = 17A (1 Phase)
 PWM4 : VAPL2 = 34A (2 Phase)
 PWM5 : VAPL3 = 68A (4 Phase)
 PWM6 : VAPL4 = 102A (6 Phase)

+1.2V / +VTT / +VTT / +2.5V[For Memory]





※需要55番前PD充電
判斷ADP有插入用)

[pin] ADAPTER_IN

※需要55番前PD充電
(2AC_IN_OC用)

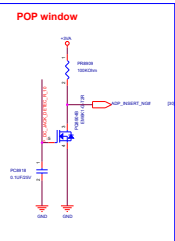
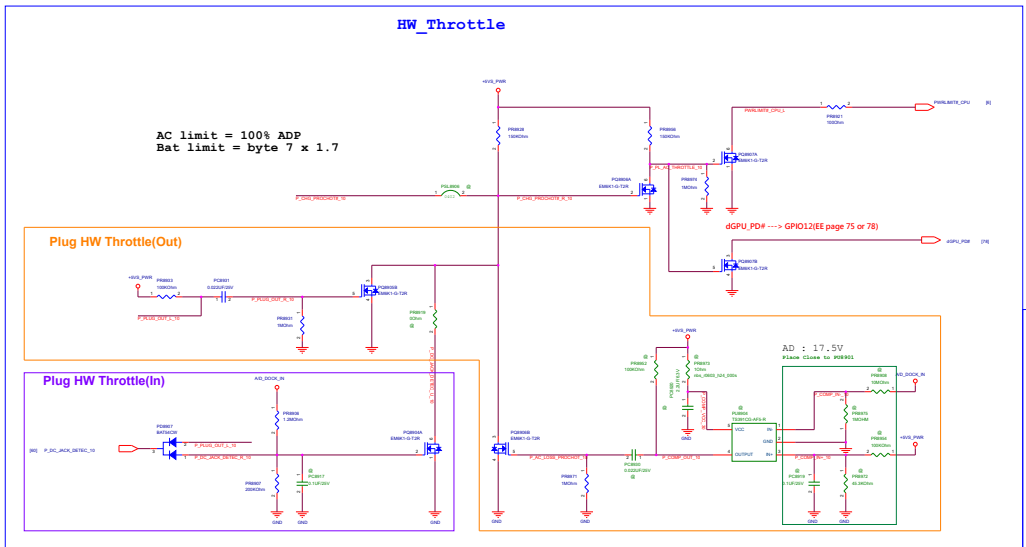
[pin] MAIN_CHG_AC_IN_OC

Figure 10-10 shows two signal traces. The top trace, labeled 'ADAPTER_IN', shows a pulse from a red arrow and is connected to pin 1 of a component labeled 'P90001'. The bottom trace, labeled 'MAIN_CHG_AC_IN_OC', shows a pulse from a red arrow and is connected to pin 2 of a component labeled 'P90000'. Both components have pins 1 and 2 labeled. The top component also has a label 'P_CHG_ADAPTER_IN_50' near pin 1.

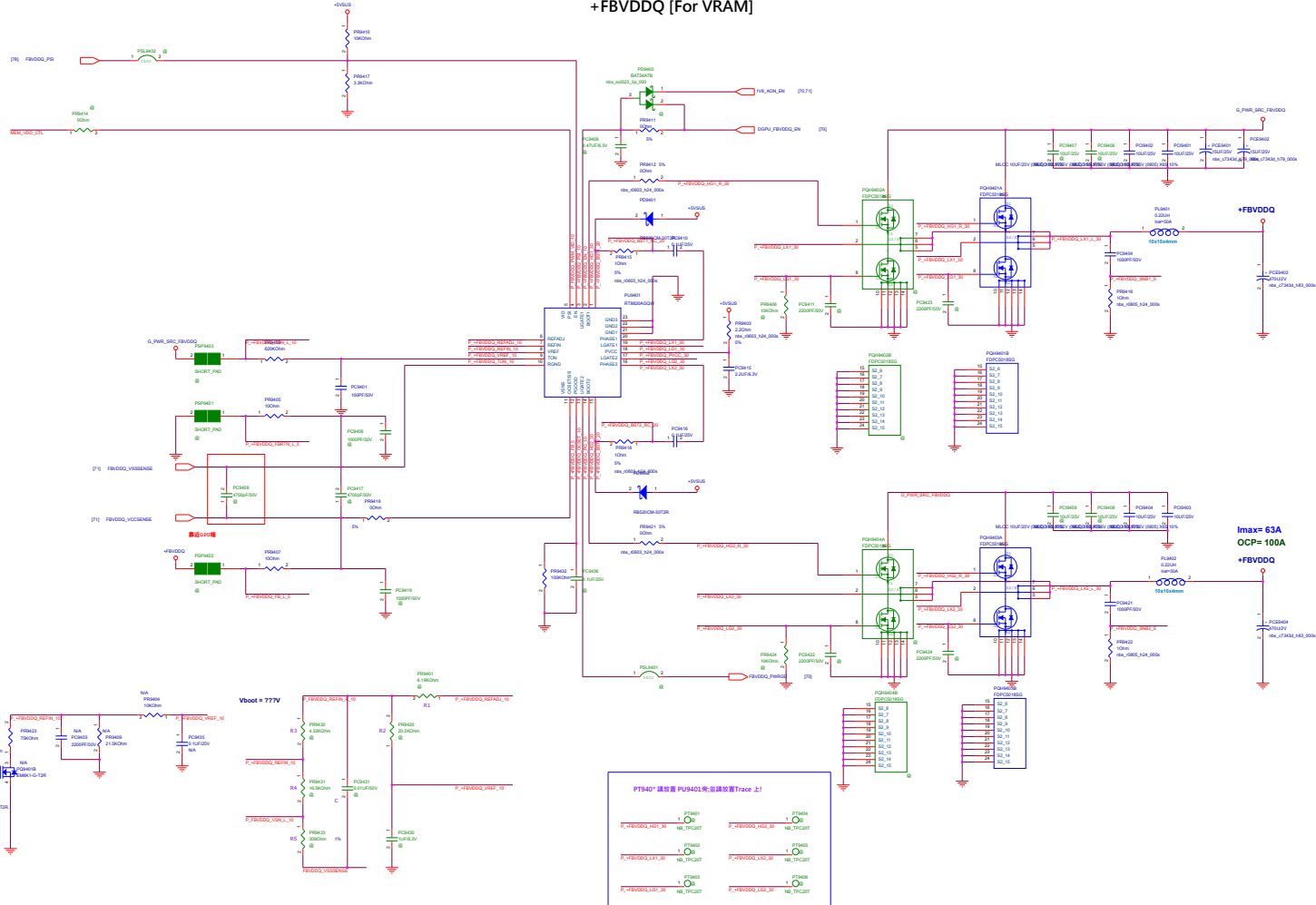


The figure contains two circuit diagrams labeled [1] and [2].
Diagram [1] shows the internal connection of the ADXL345. It features a pin labeled VDDIO connected to a resistor R10 (10K). The other end of R10 is connected to a pin labeled VDDA. A second resistor, R9 (100K), connects VDDA to GND. A third resistor, R8 (100K), connects VDDIO to GND.
Diagram [2] shows the external connection. It features a pin labeled VDDIO connected to a resistor R1. The other end of R1 is connected to a pin labeled VDDA. A second resistor, R2 (100K), connects VDDA to GND.

Adaptor select			
		4 Series	5 Series
FR8901		10m	5m
FR8936			
14E CONNECTOR (FR8936-01)	0.4V	45W	120W
31.6E CONNECTOR (FR8936-02)	0.8V	50W	150W
54E CONNECTOR (FR8936-03)	1.2V	180W	180W
82.1E CONNECTOR (FR8936-04)	1.6V	65W	230W
150E CONNECTOR (FR8936-05)	2.0V	NA	270W
270E CONNECTOR (FR8936-06)	2.4V	90W	330W
560E CONNECTOR (FR8936-07)	2.8V	120W	240W



+FBVDDQ [For VRAM]



DVS Setting		
MEM_VDD_CTL	H	L
Voltage	1.35V	1.25V
P93404	10KOhm	
P93409	21.5KOhm	
P93423	75KOhm	

DVS Setting		
MEM_VDD_CTL	H	L
Voltage	1.35V	1.2V
P99404	10W0hm	
P99409	21.5W0hm	
P99423	53.0W0hm	

DVS Setting		
MEM_VDD_CTL	H	L
Voltage	1.25V	1.2V
P9404	10KOhm	
P9409	16.2KOhm	
P9423	140KOhm	

Fixed Vout		
Q	PC9403/PR9423/PQ9401 PR9402/PR9414	
Voltage	1.25V	1.2V
PR9404	10KOhm	
PR9409	1.6. 9KOhm	1.5. 4KOhm

Title			
<Title>			
Size	Document Number		Rev
A	<Doc>		<RevCode>
Date:	Friday, November 06, 2020	Sheet	95 of 104

GM531GX R1.0 SKU Table

Option	PCB	SKU	CPU	Power	DRAM	VRAM			
60MB0810-MB1030	R1.0	GM531GX SKU1	/17-7700HQ	/230W	TRD	VRD_Micron			
60MB0810-MB2000	R1.0	GM531GX SKU2	/25-7300HQ	/230W	TRD	VRD_Samsung			

9. Card Reader: A06435--02G630002400 (Page42)

10. USB Charger IC: (Page52) Silago S1G55584VTR -- 06016-00040000
MAXIM MAX14566AETA+ -- 06G016196011

11. USB3.0 Repeater IC: (Page67)
Parade : P88710B -- 06053-00200000
Maxim : MAX14972CTG+ -- 06053-00030000

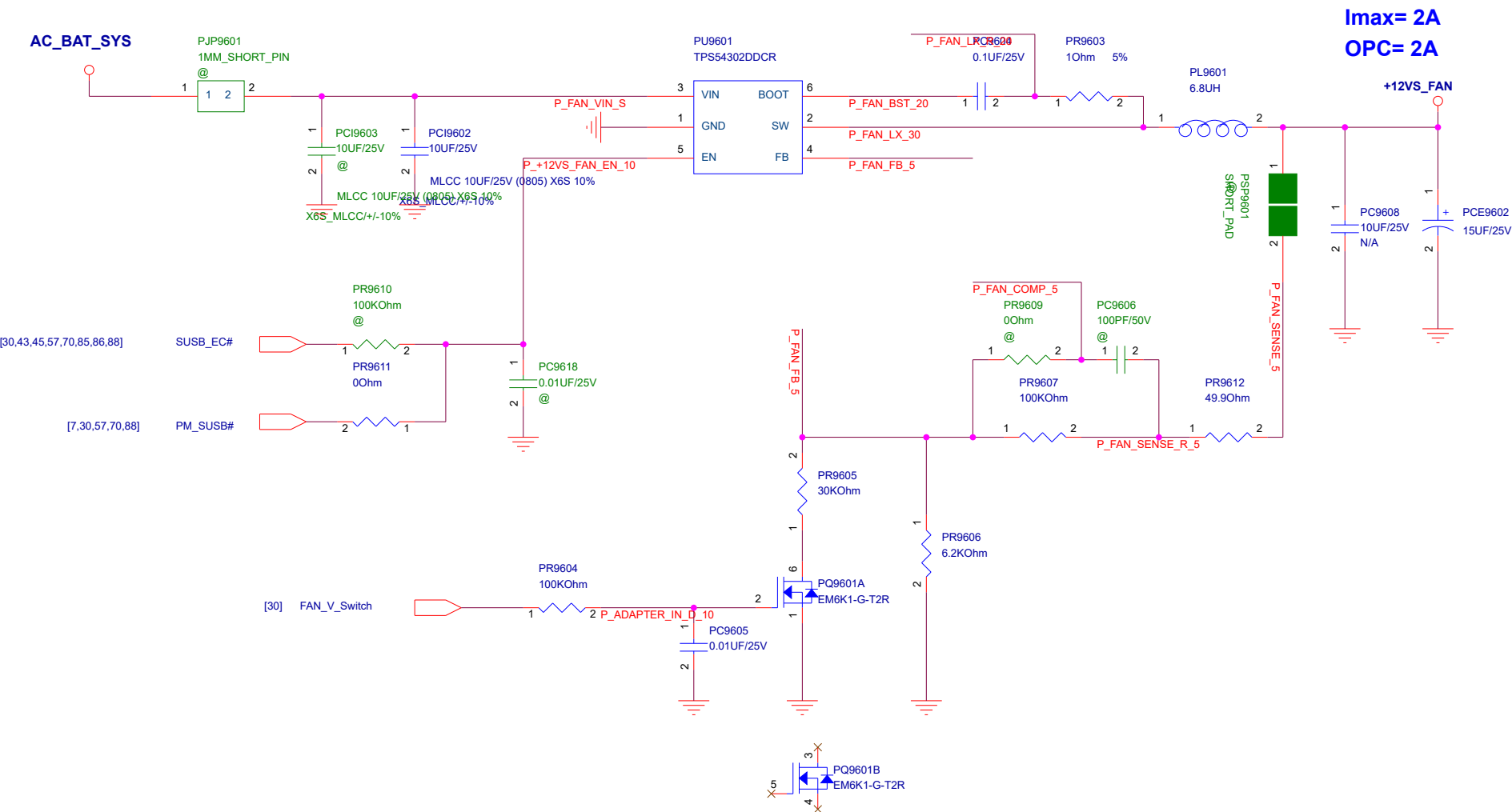


Title : [ASUS R1.0 Rev 01](#)


Engineer: EE

Rev	Engineer	Rev
1.0	EE	1.0

+12VS_FAN [For FAN]



<Variant Name>

		Project Name Project Name	Rev R1.0
Title : PW_+12VS_FAN			
Size A4	Dept.: NB Power team		Engineer: Power RD
Date: Friday, November 06, 2020		Sheet 96	of 104

1. P.01-30 reference FA50500, P.11-104 reference GX502_(WV39_20180927C)
2. Ref. connection_WV79_20180928a)
20181004
P.03
P.07
P.30 Copy FX5050DY P.30
P.32 Modify Reset circuit
P.34 Modify LAN connector
P.35 Modify N-KEY I78291E to I78299E
P.36 修图
P.37 Modify Headphone_Mic, ESS
P.39 Remove Mute control
P.40 Modify circuit
P.41 Modify circuit 4 喇叭, 0 ohm电阻
P.43 Add Mic and HDR circuit
P.48 Keep SL4802
P.49 Modify circuit
P.50

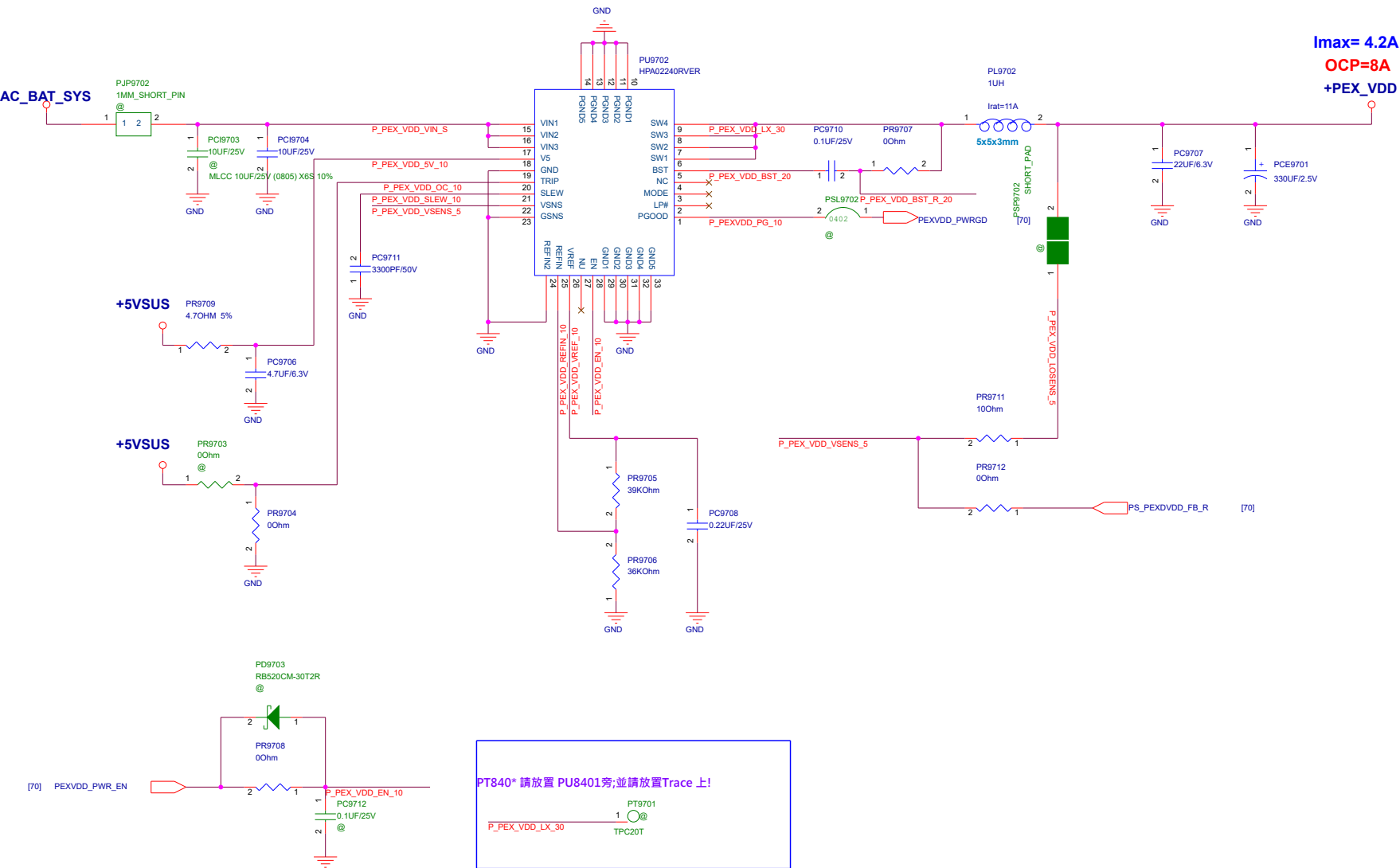
9. Card Reader: AD6435--020630002400 (Page42)

10. USB Charger IC: (Page52) Sillego SLG55584AVTR -- 06016-00040000
MAXIM MAX14566AESTA+ -- 060016196011

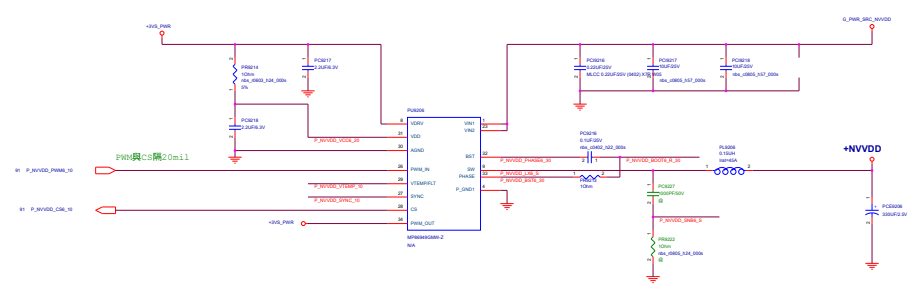
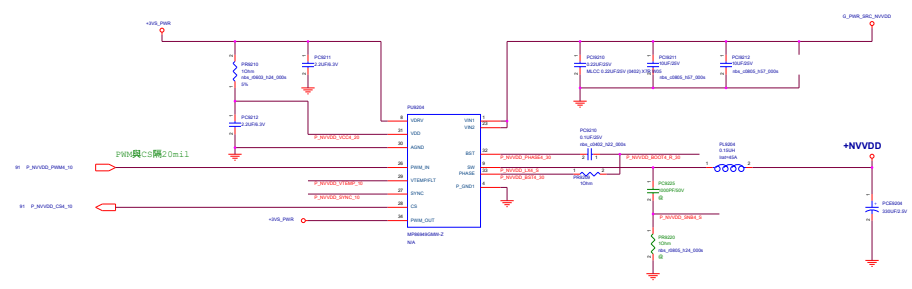
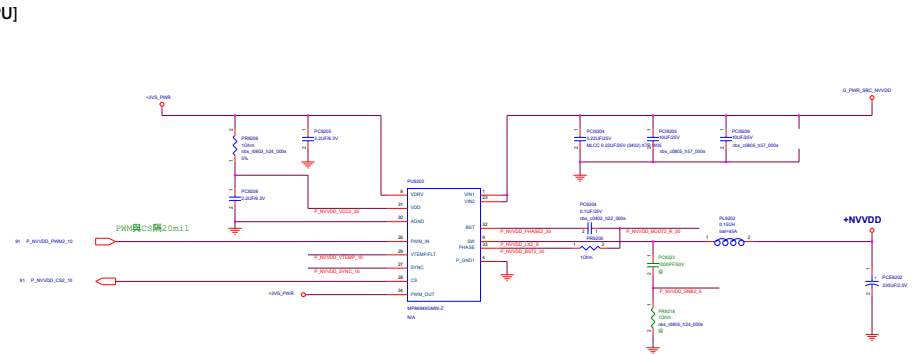
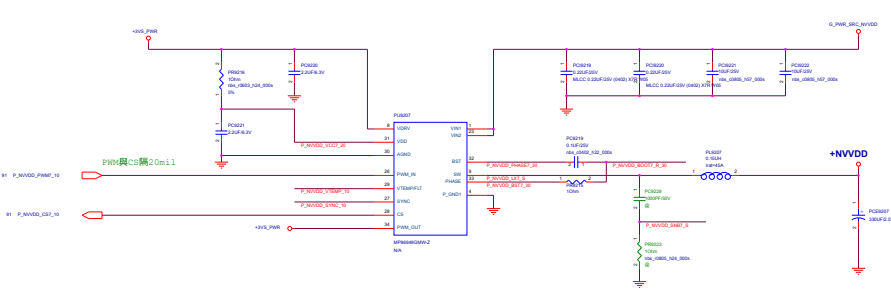
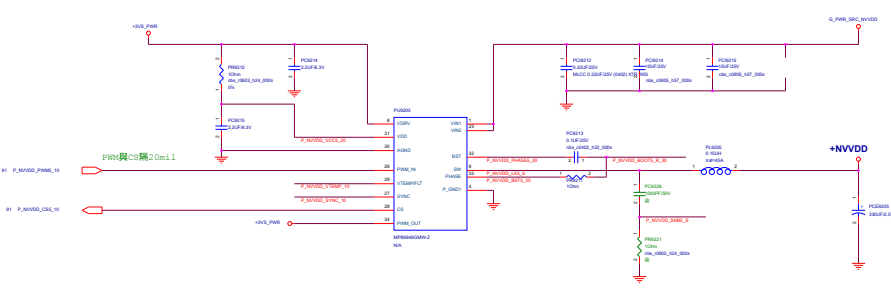
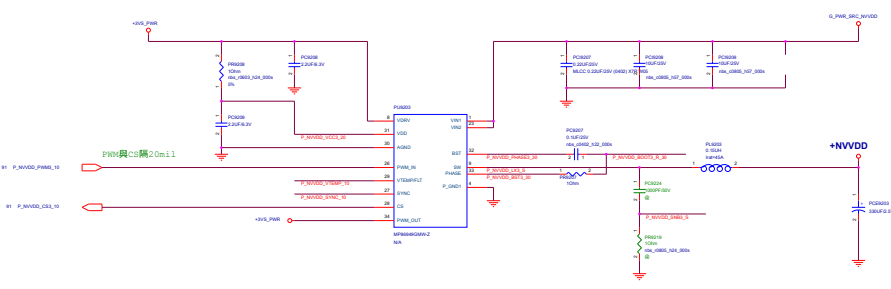
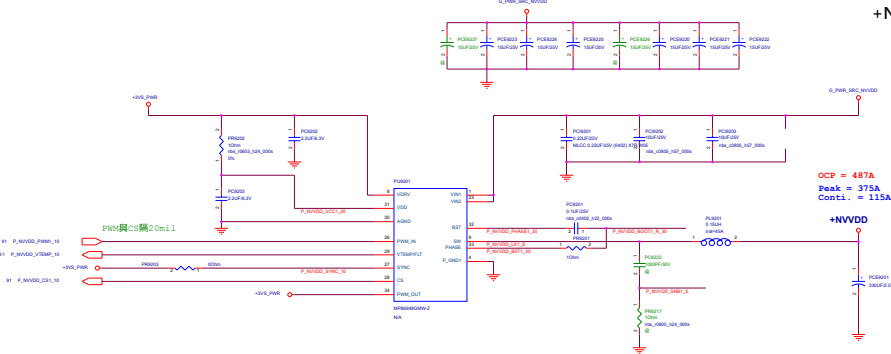
11. USB3.0 Repeater IC: (Page67)
Parade : P88710B -- 06053-00200000
Maxim : MAX14972CTG+ -- 06053-00030000

		Title : ASUS MAXIM 900	
Engineer : EE			
Rev	Revision	GX5020X	Rev
01	1.0		1.0

PEX_VDD [For GPU]



+NVVDD (For DGPU)



©2020 Design

AC-IN Mode

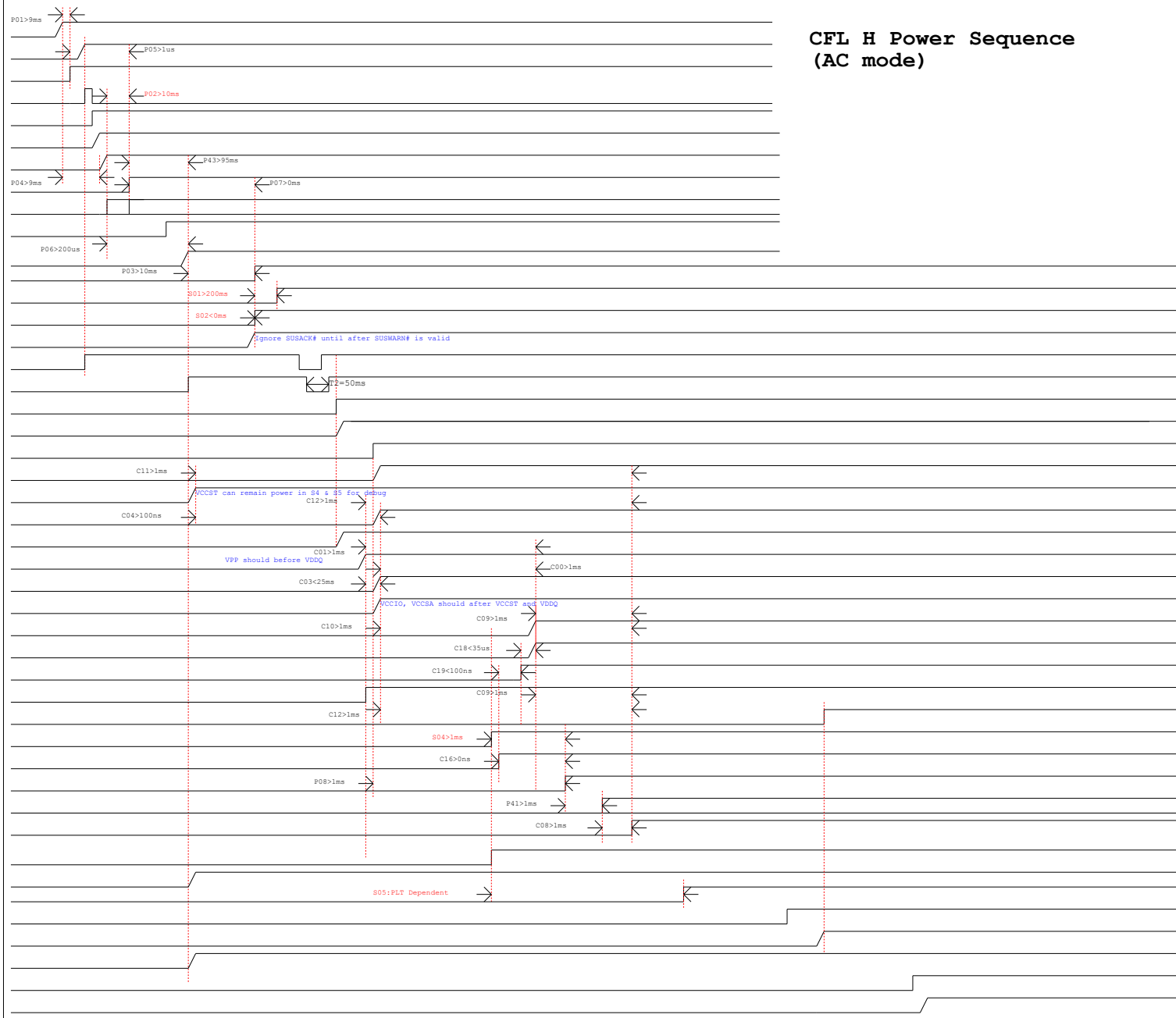
C:CPU
P:PCH
S:PLT
Power
Signal

(+RTCBAT)+3VA_RTC
(AC_BAT_SYS)+3VA/+5VA
(+3VA_RTC)RTCRST#(PCH)
(Power)AC_IN_OC#(EC)
(EC)PS_ON(+3VA_EC)
(PS_ON)+3VA_EC(EC)
(3VADSW_ON)+3VA_DSW(3VA_DSW_PWRGD)
(EC)DPWROK_EC(PCH)
(+3VA_DSW)PM_BATLOW#(PCH)
(PCH)PM_SLP_SUS#(EC)
(VSUS_ON)+1.0VSUS_VCCPRIM(1.0VSUS_PWRGD)
(EC)PM_RSMRST#_PCH(PCH)
(PCH)SUSWARN#(EC)
(EC)ME_AC_PRESENT_PCH(PCH)
(EC)PCH_SUSACK#(PCH)
(PWR_Switch)PWR_SW#(EC)
(EC)PM_PWRBTN#(PCH)
(EC)SUSC_EC#(Power)
(SUSC_EC#)+12V/+5V/+3V
(EC)SUSB_EC#(Power)
(SUSB_EC#)+12VS/+5VS/+3VS
(SUSB_EC#)+1.0V_VCCST,VCCPLL
(SUSB_EC#)+VCCIO,(+12VS)+VCCSTG
(1.2V_ON)+2.5V(2.5V_PWRGD)
(1.2V_ON)+VDDQ_CPU(1.2V_PWRGD)
(+12VS)+VCCPLL_OC
(SUSB_EC#)+VCCIO(VCCIO_PWRGD)
(ALL_SYSTEM_PWRGD)+VCCSA(IMVP8_PWRGD)
(DDR_VTT_CTRL)+0.6V
(CPU)DDR_VTT_CTRL(Power)
(Power)1.2V_PWRGD(AND)
(Power)IMVP8_PWRGD
(AND)ALL_SYSTEM_PWRGD(CPU/PCH/EC/Power)
(ALL_SYSTEM_PWRGD)VCCST_PWRGD_CPU(CPU)
(EC)PM_PWROK_PCH(PCH)
(PCH)CLK_PCH_BCLK(CPU)
(PCH)H_CPUPWRGD(CPU)

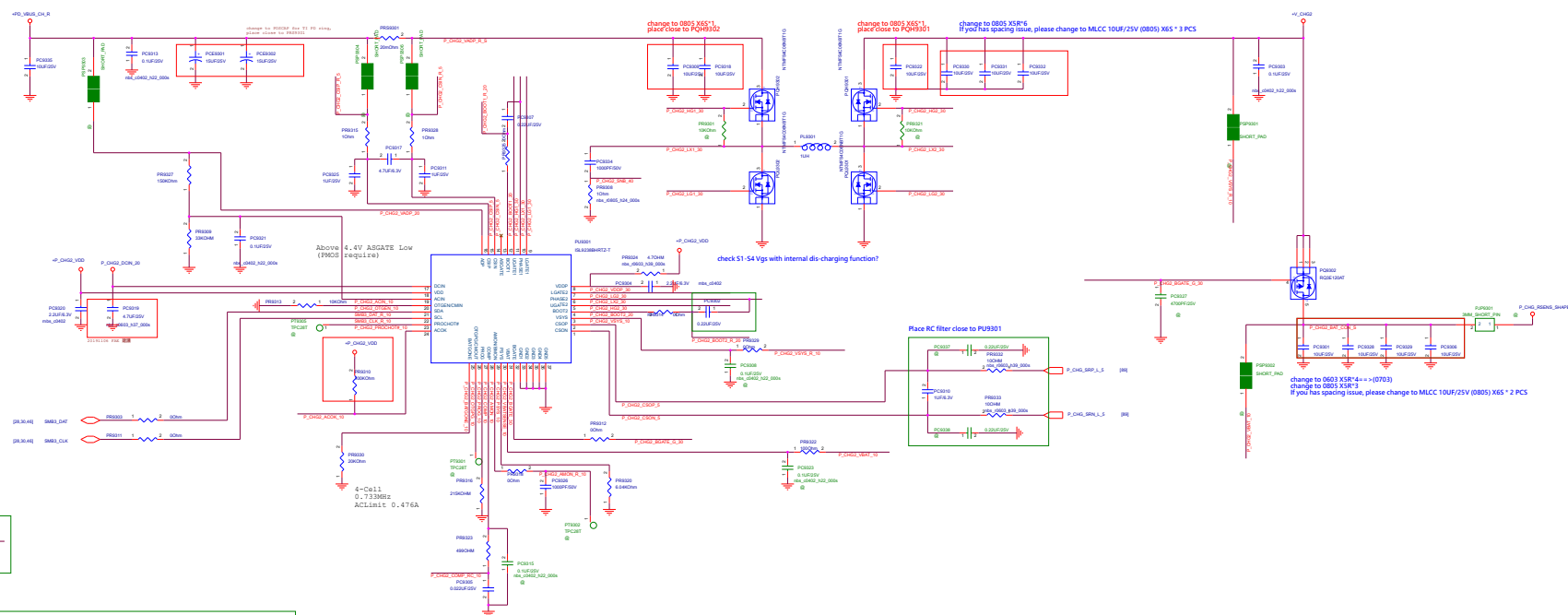
(CPU)P_SVID_DATA_X2(Power)
(EC)PM_SYSPWROK_PCH(PCH)
(PCH)PLT_RST#(CPU/EC/Device)
(P_IMVP8_DRVON)+VCCCORE(IMVP8_PWRGD)
(CPU)H_THERMTRIP#(PCH)
(PCH)DDR4_DRAMRST#(Memory)

+VCCGT

CFL H Power Sequence (AC mode)



Charger ISL9238 (NVDC)



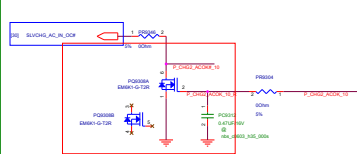
Check operating current(light /havey load-->15mA)

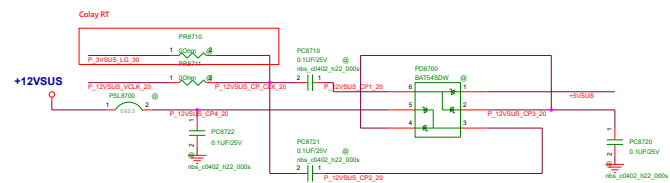
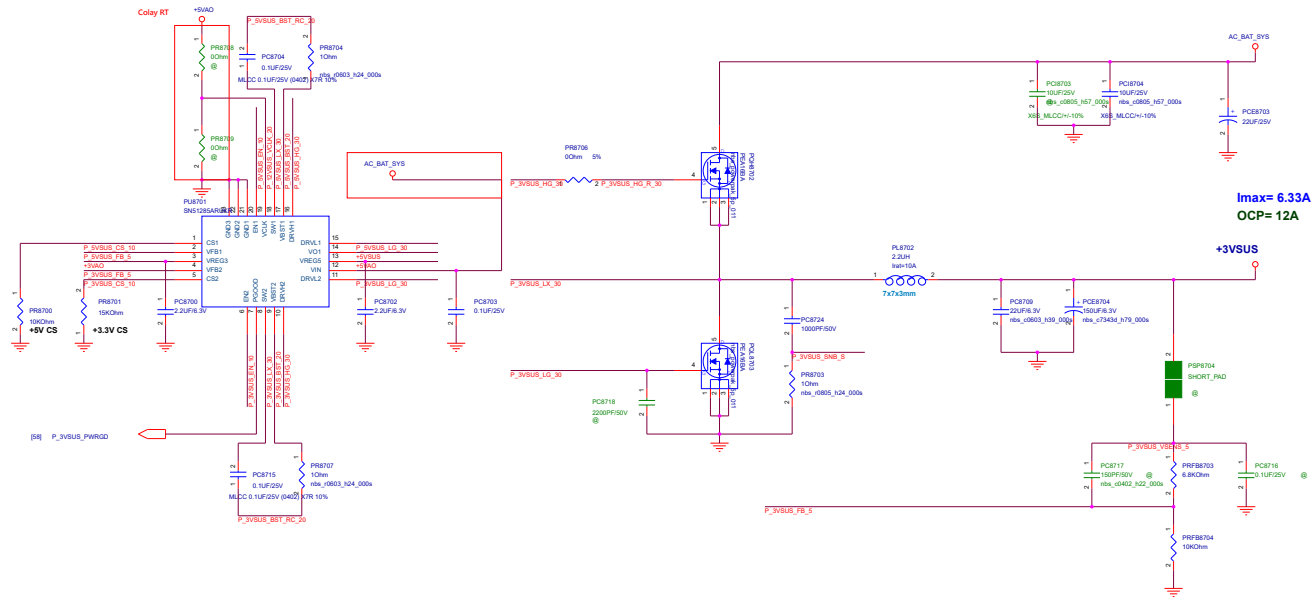
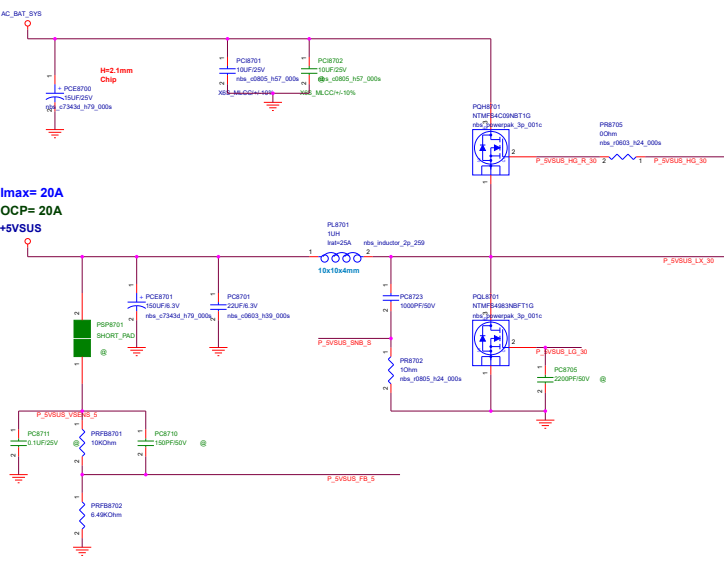


For power state S5, wake-up EC by PD plug-in AC_IN_OC#

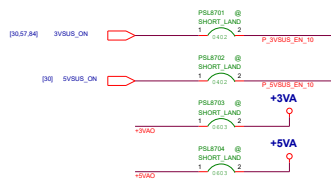
Type C 電壓直接拉住AC_IN_OC#來喚醒EC

(前請EE確認EC端有pull-high)





請 check 整份線路 +12VSUS total 並聯對地電阻不得小於10kOhm



Adaptor Mode (MVP8)							
	S0	CS	S3	D53	S4	S5	S5 with USB Charger+
PS_ON	1	-	-	-	1	-	1
3VADSW_ON	1	-	1	-	1	-	1
3VUSW_ON	1	-	1	-	1	-	1
5VUSW_ON	1	-	1	-	1	-	1
1.36V_ON	1	-	1	-	0	-	0
SUSC_EC#	1	-	1	-	0	-	0
SUSV_EC#	1	-	0	-	0	-	0

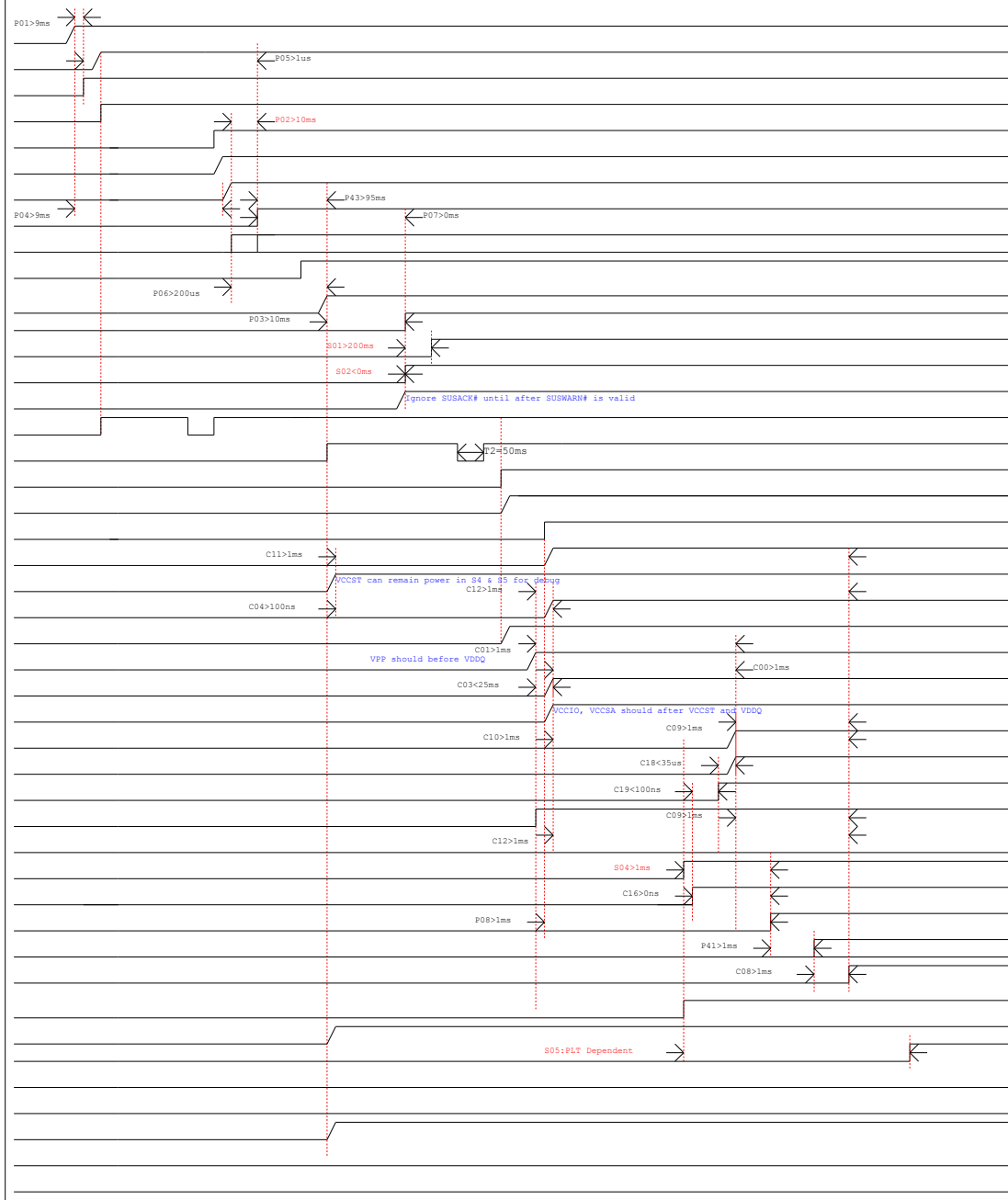
	S0	CS	S3	D53	S4	S5	S5 with USB Charger+
PS_ON	1	-	-	-	0	0	1
3VADSW_ON	1	-	-	1	0	0	0
3VUSW_ON	1	-	-	0	0	0	0
5VUSW_ON	1	-	-	1	0	0	1
1.35V_ON	1	-	-	1	0	0	0
SUSC_EC#	1	-	-	0	0	0	0
5VUSW_EC#	1	-	-	0	0	0	0

PT870* 請放置 PU8700旁;並請放置Trace 上!

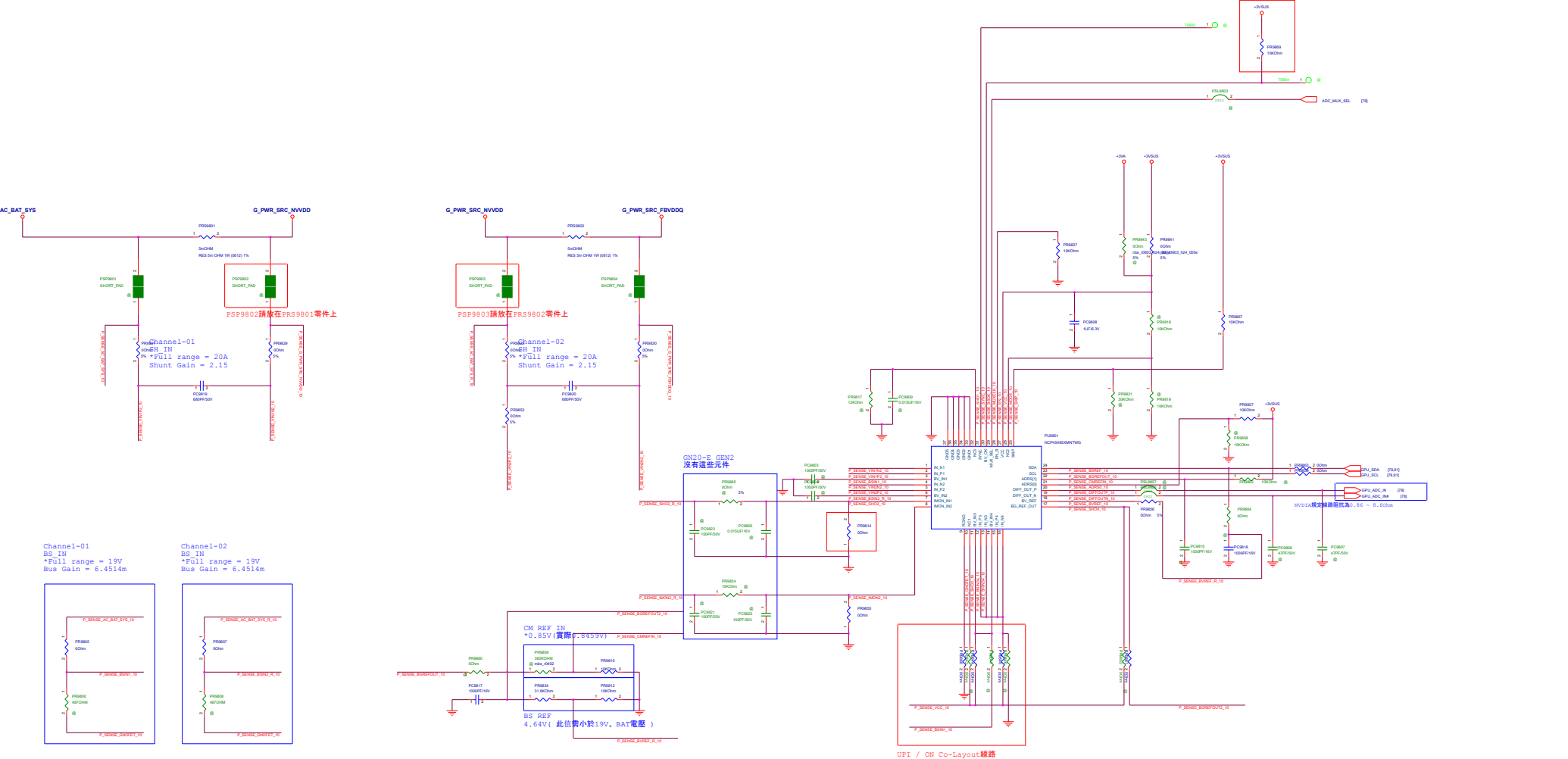


DC-IN Mode

C:CPU (+RTCBAT)+3VA_RTC
P:PCH (AC_BAT_SYS)+3VA/+5VA
S:PLT (+3VA_RTC) RTCRST# (PCH)
Power (Power) AC_IN_OC# (EC)
Signal (EC) PS_ON (+3VA_EC)
(PS_ON)+3VA_EC (EC)
(3VADSW_ON)+3VA_DSW (3VA_DSW_PWRGD)
(EC) DPWROK_EC (PCH)
(+3VA_DSW) PM_BATLOW# (PCH)
(PCH) PM_SLP_SUS# (EC)
(VSUS_ON)+1.0VSUS_VCCPRIM (1.0VSUS_PWRGD)
(EC) PM_RSMRST#_PCH (PCH)
(PCH) SUSWARN# (EC)
(EC) ME_AC_PRESENT_PCH (PCH)
(EC) PCH_SUSACK# (PCH)
(PWR_Switch) PWR_SW# (EC)
(EC) PM_PWRBTN# (PCH)
(EC) SUSC_EC# (Power)
(SUSC_EC#)+12V/+5V/+3V
(EC) SUSB_EC# (Power)
(SUSB_EC#)+12VS/+5VS/+3VS
(VSUS_ON)+1.0V_VCCST, VCCPLL (VCCST_PWRGD)
(+VCCIO)+VCCSTG
(1.2V_ON)+2.5V (2.5V_PWRGD)
(1.2V_ON)+VDDQ_CPU (1.2V_PWRGD)
(+12VS)+VCCPLL_OC
(SUSB_EC#)+VCCIO (VCCIO_PWRGD)
(ALL_SYSTEM_PWRGD)+VCCSA (IMVP8_PWRGD)
(DDR_VTT_CTRL)+0.6V
(CPU) DDR_VTT_CTRL (Power)
(Power) 1.2V_PWRGD (AND)
(Power) IMVP8_PWRGD
(AND) ALL_SYSTEM_PWRGD (CPU/PCH/EC/Power)
(ALL_SYSTEM_PWRGD) VCCST_PWRGD_CPU (CPU)
(EC) PM_PWROK_PCH (PCH)
(PCH) CLK_PCH_BCLK (CPU)
(PCH) H_CPU_PWRGD (CPU)
(ALL_SYSTEM_PWRGD) P_IMVP8_EN_10 (Power)
(CPU) P_SVID_DATA_X2 (Power)
(EC) PM_SYSPWROK_PCH (PCH)
(PCH) PLT_RST# (CPU/EC/Device)
(P_IMVP8_DRVON)+VCCCORE (IMVP8_PWRGD)
(CPU) H_THERMTRIP# (PCH)
(PCH) DDR4_DRAMRST# (Memory)
+VCCGT



CFL H Power Sequence
(DC mode)



	PU9801	PR9805	PR9807	PC9803	PC9804	PC9805	PR9814	PR9855	PR9822
GN20	NCP45495XMTWG 06129-00220000	0 Ohm 10G212000004030	0 Ohm 10G212000004030	⌀	⌀	⌀	0 Ohm 10G212000004030	0 Ohm 10G212000004030	0 Ohm 10G212000004030
N18P-G1	UP9026QQR 06129-00110100	75KOhm 10G212750214010	75KOhm 10G212750214010	1000PF/50V 11G232110214321	1000PF/50V 11G232110214321	0.015UF/16V 11G232115311360	3570hm 10G212357014010	⌀	49.9Ohm 10G212498914010

	PC9810	PR9860	PR9809	PR9810	PR9834	PR9863	PR9859	PC9809	PR9808
GN20	⌀	⌀	⌀	10KOhm 10G212100214010	31.6KOhm 10G212316214010	0 Ohm 10G212000004030	0 Ohm 10G212000004030	⌀	⌀
N18P-G1	1000PF/16V 11G232110211030	0 Ohm 10G212000004030	360KOhm 10G212364004010	680KOhm 10G212680314010	324KOhm 10G212324314010	⌀	⌀	0.015UF/16V 11G232115311360	4870hm 10G212487014010

	PR9806	PR9861	PR9864	PR9857	PR9801	PR9853	PR9817	PR9844/PR9845	PR9846/PR9847
GN20	⌀	0 Ohm 10G212000004030	⌀	10KOhm 10G212100214010	0 Ohm 10G212000004030	0 Ohm 10G212000004030	⌀	0 Ohm 10G212000004030	⌀
N18P-G1	4870hm 10G212487014010	⌀	0Ohm 10G212000004030	⌀	1000hm 10G212100014010	49.9Ohm 10G21249R914010	3570hm 10G212357014010	⌀	0 Ohm 10G212000004030

	PR9866	PR9818/PR9819	PR9821
GN20	0 Ohm 10G212000004030	⌀	⌀
N18P-G1	⌀	10KOhm 10G212100214030	30KOhm 10G212300214010

